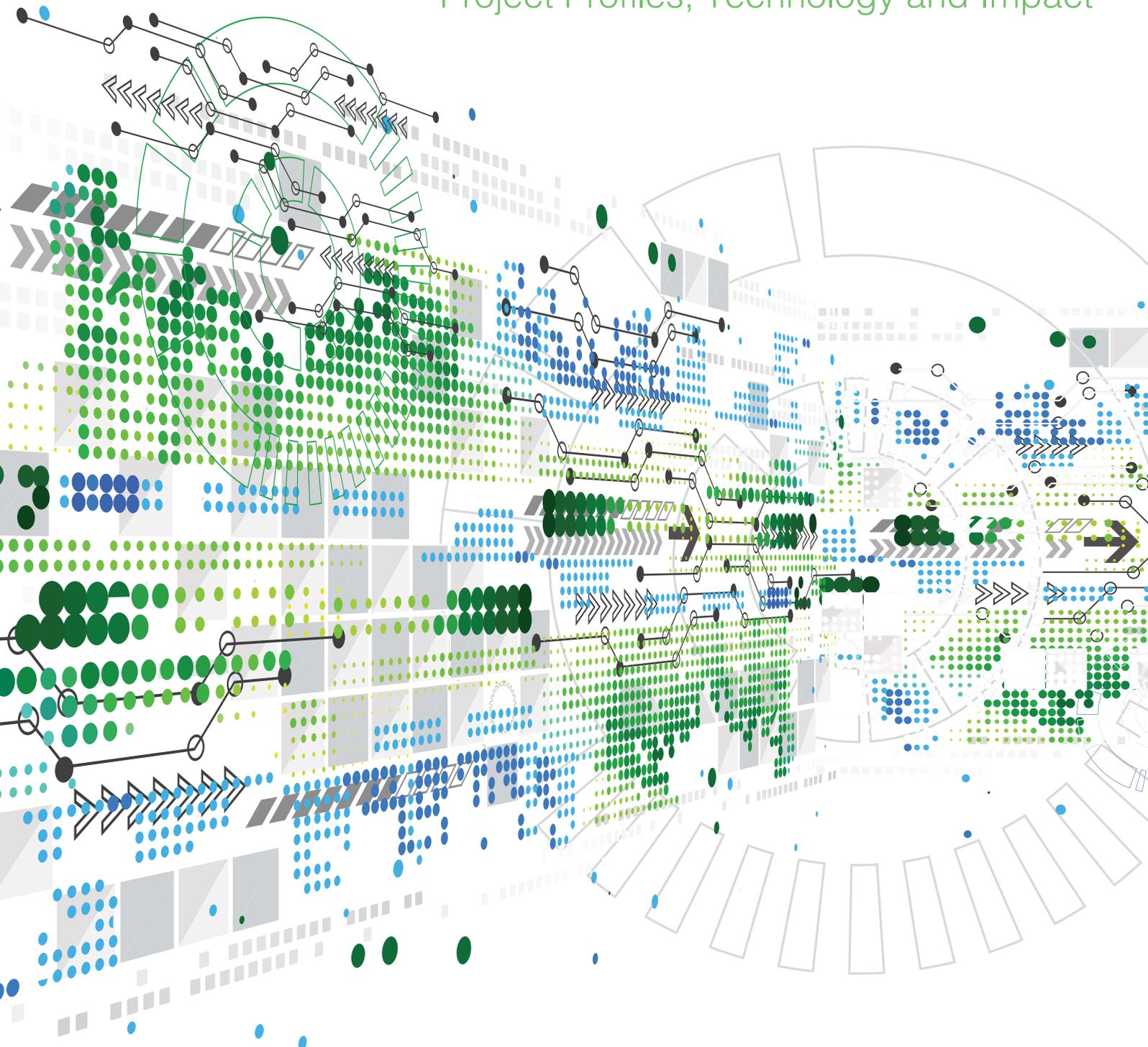


DRIVING DIGITAL INNOVATION

Project Profiles, Technology and Impact





PETER CONNOCK

Penta Director

In Europe, and indeed worldwide, Public funding support has long played a pivotal role in the development of advanced technology. It provides an important incentive that catalyses industrial activity in areas that are important to the economic and societal development of countries. International collaborative research and development is a powerful mechanism through which public support can be leveraged to gain maximum return on investment for both the industrial and public communities.

For over 35 years Eureka, an inter-governmental organisation of 45 countries, has stimulated technology development and innovation through a wide range of transnational collaborative programmes.

Now, and in the future, the digital transformation of our economy and services is a central requirement for international competitiveness, as well as addressing vital societal challenges. Increasingly, technology will be essential for addressing the global sustainability crisis now being faced by us all. Significant innovation will be required to ensure the efficient use of limited resources and the introduction of disruptive capabilities to address environmental and climate targets, while retaining economic growth and quality of life.

Almost no area of economic and social activity will be unaffected by the necessary changes that must be implemented to allow sustainable economic growth, while at the same time addressing the critical needs of the individual

citizen. Digital Health, Precision Farming, Future Mobility, Smart Cities, Zero Carbon Energy are just a few applications that are being transformed through digital innovation. These applications are enabled by core technology development, supported by required capabilities in design, security, connectivity and manufacturing.

At the heart of digital transformation is the technology and related applications enabled by micro- and nanoelectronics. Penta, a Eureka Cluster, is the latest instrument designed to stimulate international collaborative research, development and innovation in the Electronic Components & Systems community. Penta was formed in 2015 to provide a specific support capability to address the huge



challenges created by the rapid development of the global digital economy. Penta is a programme that is open to all elements of the Electronic Components & Systems Community: Large Enterprise, SME's, Research & Technology Organisations and Academic Institutions. It is a flexible, easy to use, nationally supported, funding instrument; stimulating collaborative innovation that is aligned to industrial and funding country priorities. The success of this approach is illustrated by high levels of SME participation at around 38% participation in projects.

Penta has now completed its 6th, and final, call for projects with applications over the lifetime of the programme exceeding €1bn. So far, this has resulted in 27 funded projects addressing a widely diverse range of technology and applications. For the last 3 Calls, Penta has been in a very successful partnership with Euripides, also serving the Electronic Components & Systems community. This has broadened opportunity for both industrial participants and public investors, as well as helping to simplify the funding landscape.

This brochure is designed to give a flavour of the extraordinary range of applications that have been addressed during these 3-year projects, and the significant advances in technology that have been made. Through a combination of written and Video material you will discover both the advances that have been made and the enthusiasm of the project leaders and teams that enabled them. Projects from earlier calls continue to reach their conclusion, and the impact that they make will be added to this portfolio of information.

I hope that you, either as a public investor, project participant or potential project partner appreciate this celebration of effort and achievement – highlighting what can be achieved through the close public-private partnership that Penta has been able to support.

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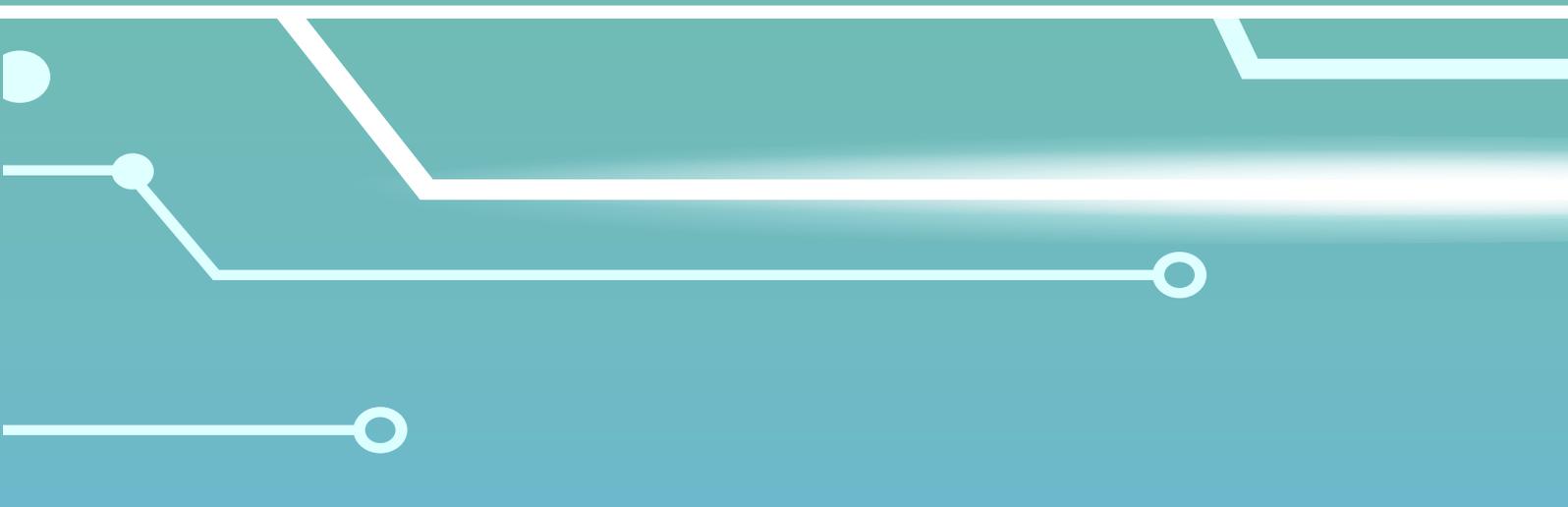
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CosmoDU





16027



Direct integration of latest SiC power and IT electronics expected to produce unprecedented performance gains in smart drives

[CosmoDU]

As machines (such as robots or conveyor-belt systems) become more intelligent, electric drives – the most active parts of these machines – will also need to evolve in intelligence. To achieve this, the CosmoDU project (its name is derived from ‘compact, highly smart, modular drive-control-unit, directly integrated in electric motors’) will deliver the hardware platform of next-generation drive units for production machines. Notably, sensors, signal processing, secure communication and control and power electronics will be directly integrated in the housing of the motor, and this new drive unit will use its self-learning capabilities to adjust and improve its performance (at application-level) in the field.

The evolution of machines, from closed-loop-controlled to truly self-deciding automates, will require electric drives, the most active parts of these machines, to actively adjust their own key operational parameters (such as speed, direction and power) according to the local situation. This will be based on their cognitive abilities, like self-learning and condition monitoring, whereby they gain and apply their own experience, as well as information from similar systems. Smart motors can also easily form a comprehensive system of connected drives as they have bi-directional communication channels and are connected to the infrastructure through Wi-Fi and cable.

Of course, these next-generation devices do not exist yet. However, they are the future and we need to prepare for, and assist with, their arrival. They are essential for a wide variety of applications and should therefore be available on the market. Most importantly, these applications include fabrication processes, which need high flexibility in order to reach the mass-production efficiency envisaged in Industry 4.0.

Hardware platform for next-generation electric motors

The CosmoDU project will develop and deliver the hardware platform for next-generation drive units required by fabrication machines, like intelligent industrial robots and conveyor belts. It will integrate – directly in the motor housing – sensors, signal processing, secure communication and control electronics (for comprehensive performance control and health monitoring), as well as the power and driver stages. Smart drives will have self-learning capabilities for adjusting and improving their performance at application level (such as the robot) in the field. A comprehensive system of sensors will also identify the actual needs of the drives, as reflected in their maintenance and safety status.

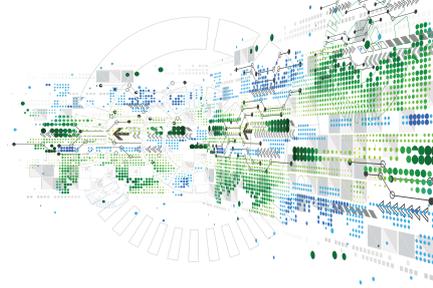
The project will first develop a modular hardware architecture for the integration of all sensors, microelectronics and power modules directly into the housing of an industrial synchronous motor-drive for conveyor belts or industrial robots as target applications. Based on this architecture, component development, module and system integration, as well as demonstrator development and validation testing, will be conducted.

The key technological features include:

- On the information technology (IT) side, highly dense, yet reliable, heterogeneous integration of MEMS, sensors, security, electronics and antenna structures using system-in-package (SiP) and 3D stacking technologies;
- On the power electronics side, wide-bandgap (WBG) devices, a direct combination of driver and power stages, as well as advanced cooling techniques;
- Developing a novel 3D multi-layer-planar integration technology for adding all sensors and signal processing;
- Communication interfaces for active health-monitoring of the power sub-module;
- The direct combination of the latest technologies from both fields – 1200V SiC (silicon carbide) power-electronics, and best-in-class IT electronics operating μ V signals. This is the basis for an unprecedented gain in drive performance.

This project brings together 14 partners – three large companies, eight small and medium-sized enterprises (SMEs) and three research institutes or universities – from Germany and the Netherlands. This well-balanced consortium covers the whole value-chain: from investigating, designing and developing the new processes and equipment; to manufacturing the future smart motors; and finally to their end-use.





KEY APPLICATION AREAS

-  Transport & Smart Mobility
-  Health & Well-Being
-  Energy
-  Digital Industry
-  Digital Life

ESSENTIAL CAPABILITIES

-  Systems and Components Architecture, Design & Integration
-  Connectivity & Interoperability
-  Safety, Security & Reliability
-  Computing & Storage
-  ECS Process Technology, Equipment, Materials & Manufacturing

PARTNERS

AMITRONICS Angewandte Mikromechatronik GmbH / Berliner Nanotest und Design GmbH Fairchild Semiconductor / Fraunhofer Institute for Electronic Nano Systems (ENAS) / Fraunhofer Institute for Integrated Systems and Device Technology (IISB) / Langer EMV-Technik GmbH Robert Bosch GmbH / iemens AG / Advanced Packaging Center BV / Boschman Technologies B.V. / Catena Holding BV / Heliox / Technolution BV / Delft University of Technology

COUNTRIES INVOLVED

-  Germany
-  The Netherlands

PROJECT LEADER

Dr. Kai Kriegel
Siemens AG

www.cosmodu.eu

KEY PROJECT DATES

01 Mai 2017 - 30 April 2020

Project challenges, standards and European leadership

Together with functional performance, CosmoDU will also address new challenges of electro-magnetic compliance (EMC), thermo-electro-mechanical reliability, functional safety and system availability that specifically arise from an ultra-compact design. It will also develop proof-of-concept software for a functional demonstrator drive. Furthermore, project partners will make efficient and effective use of resources by focusing on their particular skills and specialisms: SMEs will be pilot investigators, employing their specific competencies (thus providing them with needed visibility and market acceptance to grow their business significantly); larger industrial firms will use their market knowledge and contacts; while research institutions provide their methodology-research findings.

CosmoDU's novel approach towards integration and self-learning will set the trend for next-generation industrial electric-drives. Its core advantages of flexibility, connectivity and system availability will ensure that the vision behind Industry 4.0 is realised. This project will also act as a template for similar efforts in neighbouring domains, such as electric-mobility, smart energy, and smart infrastructure. Furthermore, its aim to standardise key elements of the architecture, interfaces, and protocols will contribute substantially to strengthening the technological leadership position of the project partners, and of Europe as a whole.

Employment, financial and societal benefits

The self-learning feature will also provide flexibility and increase product quality. This will maintain – and even increase – European manufacturing jobs. While CosmoDU specifically focuses on next-generation electrical drives (for industrial robots or conveyor belts, for instance), this 'template' can easily be adopted and adapted subsequently by other industries and application areas. Tool machines, automated driving and full-scale electro-mobility can produce significant financial benefits, as can smart energy and smart infrastructure.

What is more, societal needs for carbon-free and ultra-safe individual mobility and living are also addressed, as are those for resource-efficient production.

Healthy market outlook

According to IHS, industrial drives (including those used in pumps, fans, compressors and the like) have the highest market-share in terms of IGBT (insulated-gate bipolar transistor) applications. Here, huge potential savings with factory automation are possible by using variable-speed drives, where some 10% of worldwide electricity-consumption could be saved. Furthermore, combining the trend in factory automation towards Industry 4.0, with the large savings achievable by improved drives, industrial electric-drives seem most attractive, particularly when deployed in industrial robots. And basic economic numbers support this: the total market for 400-1200V powertrains relevant to industrial drives is about US\$ 25 billion, compared with an annual growth of more than 10% for drives using conventional technology. With integrated power and IT technology, the market share of these ultra-intelligent integrated powertrains will grow even faster than the market itself. Therefore, the prospects for high return-of-investment (RoI) are good. However, while we see a large market potential, this integration still needs extensive research into such typical areas as feasibility and yield.

Work done on the CosmoDU project can also benefit directly from another strong trend: according to IHS, the number of internet-connected things will grow to 50 billion units by 2025, with the most dominant growth in industrial applications. The technological basis and drivers for this growth will come from smart sensors capable of detecting changes and anomalies in vibration, sound, temperature, humidity, pressure and other physical properties. IHS estimates that the revenue from semiconductor-based sensors alone will grow from US\$8.9 billion in 2014, to more than US\$10.6 billion by 2017. The future looks bright for CosmoDU.

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Penta (E! 9911), is EUREKA Cluster whose purpose is to catalyse research, development and innovation in areas of micro and nanoelectronics enabled systems and applications.

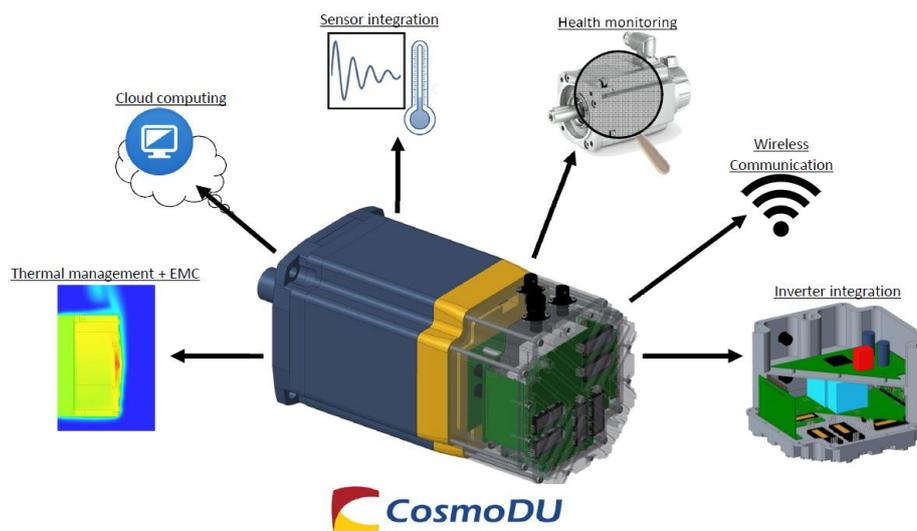


CosmoDU

CosmoDU: bringing intelligence to electric drives for Industry 4.0 manufacturing

A project within the EUREKA PENTA programme

Paris, September 27, 2018 – CosmoDU, a EUREKA PENTA cluster project managed by AENEAS, is bringing intelligence to the electric drives that control production machines such as industrial robots or conveyor belts. The project aims to create the first hardware platform able to implement self-learning capabilities within applications, allowing them to adjust and improve the performance of the applications during operation and to ensure timely preventive maintenance.



These smart intelligent electric drives will be key enablers for Industry 4.0. They will increase manufacturing flexibility and even have the ability to learn from identical units located elsewhere via secure communication links. Moreover they will maximise system availability by eliminating downtime due to unexpected servicing needs. Hence, CosmoDU will not only strengthen the technological leadership of the 14 partners involved, but also support European manufacturing and create new jobs through competitive, smart and highly flexible industrial production.

Highly market-focused, CosmoDU will help deliver mass production efficiency for small lot sizes ('Lot Size One') – a key element of the Industry 4.0 vision. In addition, the hardware platform – which will integrate sensors, signal processing, secure communication and control electronics as well as the power electronics and the driver stages directly in the housing of the motor – will be easily translatable to other domains including tooling machines, automated driving and full-scale electromobility, as well as smart energy and smart infrastructure solutions.

According to IMS Research, there are substantial prospects for a high return on investment from this research. The total market for 400-1200 V powertrains relevant to industrial drives is worth about 25



billion USD in year 2015, with annual growth of over 10% for drives using conventional technology. With integrated power and IT technology, the market share for intelligent integrated powertrains is expected to grow even faster. Furthermore, intelligent electric drives will enable major reductions in energy consumption in factory automation by reducing cabling as well as increasing the overall system efficiency. It is estimated that variable speed drives could cut approximately 10% of worldwide electrical energy consumption, with corresponding savings in costs and CO₂-emissions (Source: ABB).

Besides these economic and environmental benefits, the CosmoDU project will deliver benefits for its participants – three large companies, eight small and medium-sized enterprises (SMEs) and three research institutes and universities from Germany and the Netherlands. The market-leading OEMs and Tier 1 suppliers involved will be able to exploit the results immediately in their businesses. For the expert SMEs, this is an opportunity to employ and develop their expertise in key areas such as electromagnetic compliance (EMC), health monitoring of electronic systems, active performance control, packaging processes and equipment, motor control and system integration of the hardware and software. Similarly, the research organizations will gain valuable knowledge in industrial practice, which will both enrich academic knowledge and improve future research services to industry.

About the PENTA programme (managed by the AENEAS Industrial Association)

PENTA is a EUREKA cluster whose purpose is to catalyse research, development and innovation in areas of micro and nanoelectronics enabled systems and applications - where there is shared national and industrial interest. Based on three key application areas, Transport & Smart Mobility, Health & Well-Being and Digital Industry for the first 3 calls, PENTA programme contributes to the development of electronic solutions with the opportunity for rapid competitive exploitation and a strong impact on European societal challenges. The PENTA project team is supporting SMEs, large corporations, research organisations and universities by facilitating access to funding, fostering collaborative work and creating consortia.

PENTA is managed by AENEAS, the European industry association

About PENTA: <http://www.PENTA-eureka.eu>

About AENEAS: <https://aeneas-office.org>

About CosmoDU

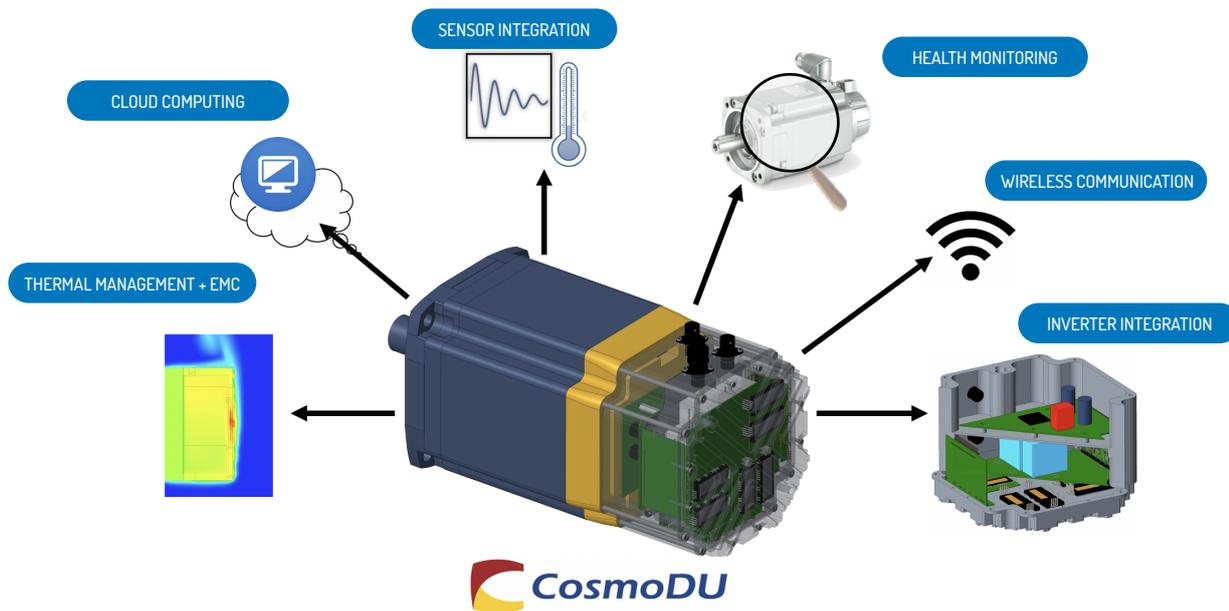
CosmoDU is a RD&I project consortium involving 14 partners from 2 countries. The project partners are: Siemens AG (project leader), AAMITRONICS Angewandte Mikromechatronik GmbH, Advanced Packaging Center BV, Berliner Nanotest und Design GmbH, Boschman Technologies B.V., Catena Holding BV, Delft University of Technology, Fairchild Semiconductor, Fraunhofer Institute for Electronic Nano Systems (ENAS), Fraunhofer Institute for Integrated Systems and Device Technology (IISB), Heliox, Langer EMV-Technik GmbH, Robert Bosch GmbH, Technolution BV. National funding support is provided by Germany and the Netherlands.

About CosmoDU: <https://www.cosmodu.eu>





CosmoDU



The evolution of machines requires electric drives to actively monitor and adjust their own key operational parameters such as speed, direction and power, in case of performance or environmental changes. CosmoDU has developed the hardware platform of next-generation drive units, where sensors, signal processing, secure communication and control and power electronics have been directly integrated in the housing of the motor. This new drive unit uses its self-learning capabilities to adjust and improve its performance.

Background, objectives of the project and faced challenges

Today industrial drives consist of electric motors, inverters, and an additional control stage. Maintenance is done regularly independently from load and system condition. The smart intelligent electric drives developed within CosmoDU will be key enablers for Industry 4.0. They will increase manufacturing flexibility and even have the ability to learn and to communicate. Moreover, they will maximise system availability by eliminating downtime

due to unexpected servicing needs. The objective was to develop a hardware platform which integrates sensors, signal processing, secure communication and control electronics as well as the power electronics and the driver stages directly in the housing of the motor. The platform should be used for different applications as conveyor belts, robotics, tooling machines, automated driving and full-scale electromobility, as well as smart energy



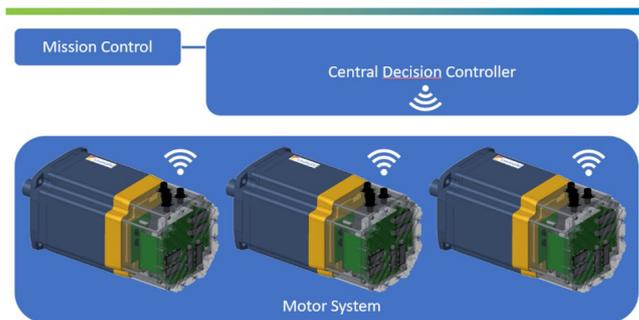


and smart infrastructure solutions. Together with functional performance, CosmoDU has addressed multiple challenges such as electro-magnetic compliance (EMC), thermal management, functional safety and system availability that specifically arise from an ultra-compact design. Indeed, fast switching power devices in the neighbourhood of low voltage components tend to cause EMC issues, while the limited cooling capability of the integrated system is highly demanding in terms of thermal management.

Technological achievements

System architecture

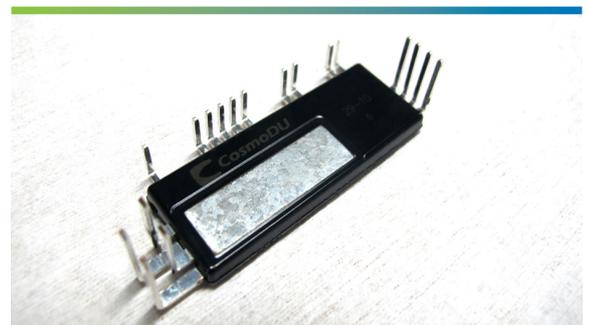
The CosmoDU consortium developed a modular hardware architecture for the integration of sensor, micro and power electronics modules to fit into the housing of a motor drive. A clear partitioning of functions is accomplished by considering the severe requirements related to thermal management and EMC. The architecture enables full integration of the inverter and the sensors for health monitoring and drive performance optimisation. All information is shared throughout the motor and with the higher system layers using a standard for data exchange (OPC UA). This provides a scalable and manufacturer independent way to disclose information towards the higher layers of the control and monitoring system.



CosmoDU system architecture

SiC power modules

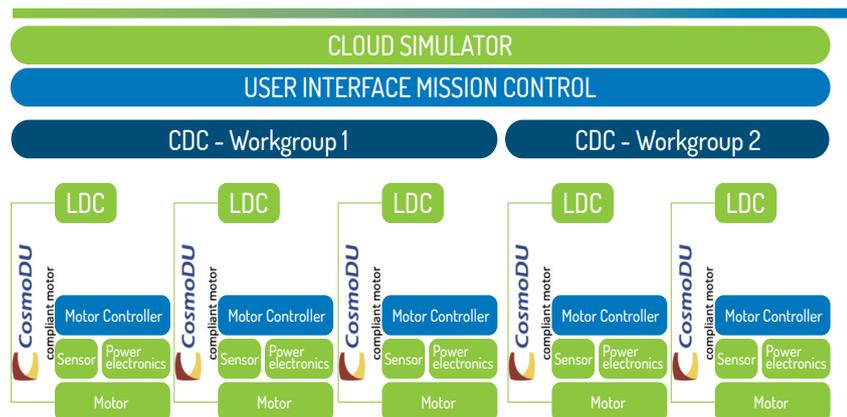
Saving energy is one key element in the efforts to reduce global warming. The use of new silicon carbide (SiC) semiconductors in inverters allows to significantly reduce conduction and switching losses compared to silicon (Si) based power semiconductors. The higher power density and higher temperature capabilities of SiC components were addressed with a power module design for dual side cooling. Better heat transfer and new assembly techniques enable to achieve not only good operational performance but also high reliability.



Encapsulated SiC power module

Condition and health monitoring

Each CosmoDU motor is equipped with its own thermal impedance spectroscopy (TIS) board, allowing to determine the health status of the power modules. The CosmoDU sensor module constantly records motor vibrations as well as sound and provides those data together with motor parameters to the Local Decision Controller. These data gathered in a feature vector are transferred to higher control levels, either to the Central Decision Controller or to the Cloud, for self-learning analysis. This allows the customers to replace components before they fail.



Main layers of the CosmoDU architecture





Secure wireless communication

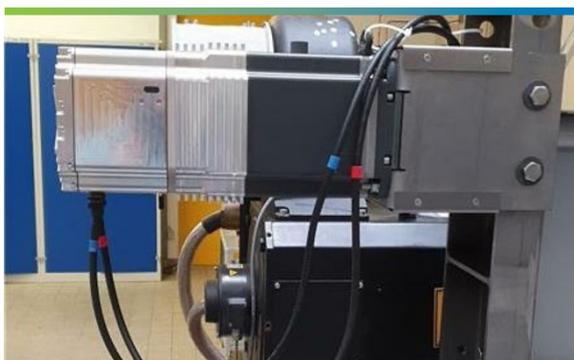
The Wireless communication module shows a performance clearly surpassing the IEEE 802.11ac Wifi standard requirements, particularly in terms of reception quality and associated power usage. Moreover, the successful proper functioning of a prototype IEEE802.11ah Wifi system was shown in an industrial environment under harsh conditions regarding interferences, strange propagation path properties, reflections and damping factors between factory compartments with heavily disturbing motors.



Testing of prototype Wifi system in a harsh factory environment

Integrated smart motor drive

The motor is a series servo motor, on which the electronics housing is mounted. The electronics housing contains the high voltage power electronics as well as the low voltage control, sensor, and communication boards. The compact motor drive unit allows a versatile usage. The wireless communication link, the smart health monitoring and process diagnostics are especially beneficial in systems with decentralised drives, e.g. conveyor belts. The CosmoDU motor serves as sensor and communication hub of other adjacent components of an installation.



CosmoDU motor drive mounted at a demonstrator conveyor belt

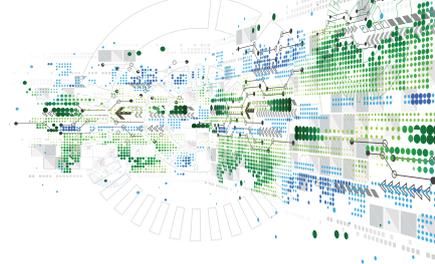
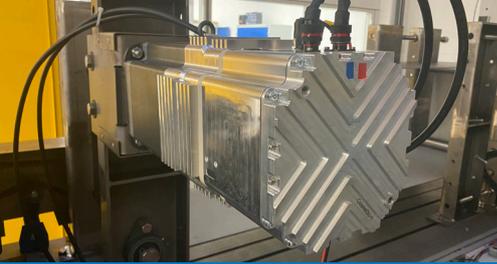
Market Potential

CosmoDU is targeting to deliver a smart hardware platform for next generation electric drives with high efficiency, performance optimisation and health monitoring used in industrial automation systems. The total market for industrial power trains relevant to industrial drives is worth about 25 billion USD, with annual growth of over 10% for drives using conventional technology. With integrated power and IT technology, the market share for intelligent integrated powertrains is expected to grow even faster. More specialised markets are also relevant: e.g. the global conveyor belt market is forecasted to achieve at an annual growth rate of 3.7% during the period 2019-2025, leading to an expected total market size of 5 billion USD in 2025. For this market, the increasing demand partly comes from the mining industry, due to their significant requirements of longer distances, strength, flexibility, easy maintenance, and high-splice strength and safety. Promising demand trends can also be found such in the aviation business, automated production plants or warehousing and logistic systems.

The CosmoDU results will have an impact on the following products:

- Semiconductor, microelectromechanical systems (MEMS) sensors and power modules (ON Semiconductor, Bosch, APC, Boschmann)
- Electrical drives and control platforms (Siemens, Heliox, Technolution)
- Secure Wireless communication (Catena)





KEY APPLICATION AREAS

-  Transport & Smart Mobility
-  Health & Well-Being
-  Energy
-  Digital Industry
-  Digital Life

ESSENTIAL CAPABILITIES

-  Systems and Components Architecture, Design & Integration
-  Connectivity & Interoperability
-  Safety, Security & Reliability
-  Computing & Storage
-  ECS Process Technology, Equipment, Materials & Manufacturing

PARTNERS

- Advanced Packaging Center BV
- AMITRONICS Angewandte Mikromechatronik GmbH
- Berliner Nanotest und Design GmbH
- Boschman Technologies B.V.
- Catena Holding BV
- Delft University of Technology
- Fraunhofer Gesellschaft- IISB
- Fraunhofer Institute for Electronic Nano Systems (ENAS)
- Heliox
- Langer EMV-Technik GmbH
- ON Semiconductor
- Robert Bosch GmbH
- Siemens AG
- Technolution BV

COUNTRIES INVOLVED

-  Germany
-  The Netherlands

PROJECT LEADER

Dr. Kai Kriegel
Siemens AG

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KEY PROJECT DATES

01 May 2017 - 31 October 2020

Societal & Economic Impact

Smart drives will enable major reductions in energy consumption in factory automation by reducing cabling as well as increasing the overall system efficiency. It is estimated that industrial drives could cut approximately 10% of worldwide electrical energy consumption, with corresponding savings in costs and CO2-emissions. Additionally, CosmoDU project will deliver benefits for its participants – three large companies, eight small and medium-sized enterprises (SMEs) and three research institutes and universities from Germany and the Netherlands. The market-leading original equipment manufacturer (OEMs) and Tier 1 suppliers involved will be able to exploit the results in their businesses. For the expert SMEs, this is an opportunity to employ and develop their expertise in key areas such as electromagnetic compliance (EMC), health monitoring of electronic systems, active performance control, packaging processes and equipment, motor control and system integration of the hardware and software. Similarly, the research organizations will gain valuable knowledge in industrial practice, which will both enrich academic knowledge and improve future research services to industry.

CosmoDU will not only strengthen the technological leadership of the involved partners, but also support European manufacturing and create new jobs through competitive, smart and highly flexible industrial production.

Patents/Standardisation/ Publications

The partners actively disseminated the results from CosmoDU project at several domestic and international events and workshops, including EF ECS 2017/2018/2019 and Precisiebeurs 2018, in company with various demonstrating components, posters and oral presentations. Representatives of the ECSEL JU Lighthouse initiative Industry4.E have been contacted for additional dissemination opportunities and collaborative options. The project results will be presented with a booth at the EF ECS 2020. The project delivered several papers to general public and published various press releases via social media including internal newsletter, partner's website, LinkedIn and Twitter.

Future Developments

The innovative approaches in CosmoDU are an important step to higher system integration and smarter ICT in the field of industrial automation. For further decarbonization, the number of efficient industrial drives needs to be increased. Moreover, in a sustainable environment a high reliability and a long lifetime are crucial. This means for future developments that the focus on efficient power devices, reliable packaging, compact design, improved 3D system integration, EMC, secure communication and the application of artificial intelligence will be enforced. To meet these goals, new follow-up projects are under discussion.

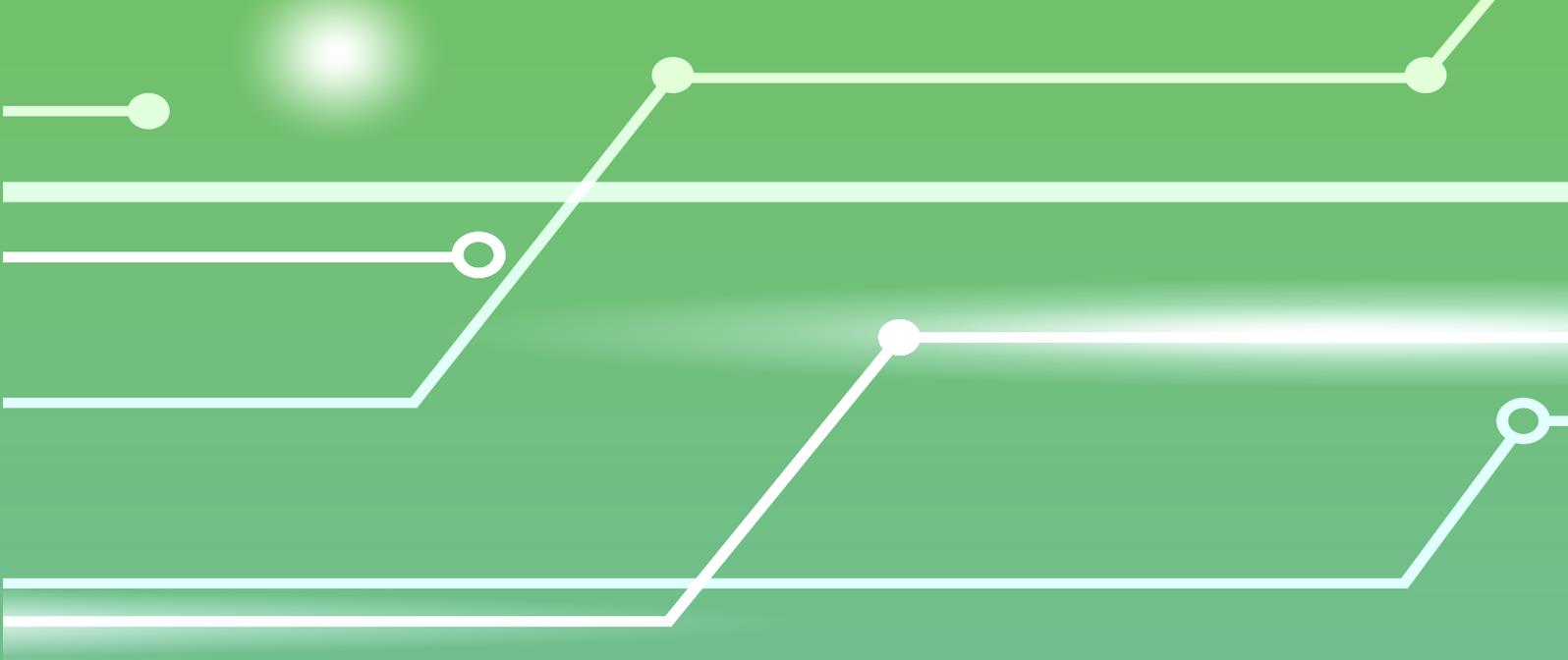
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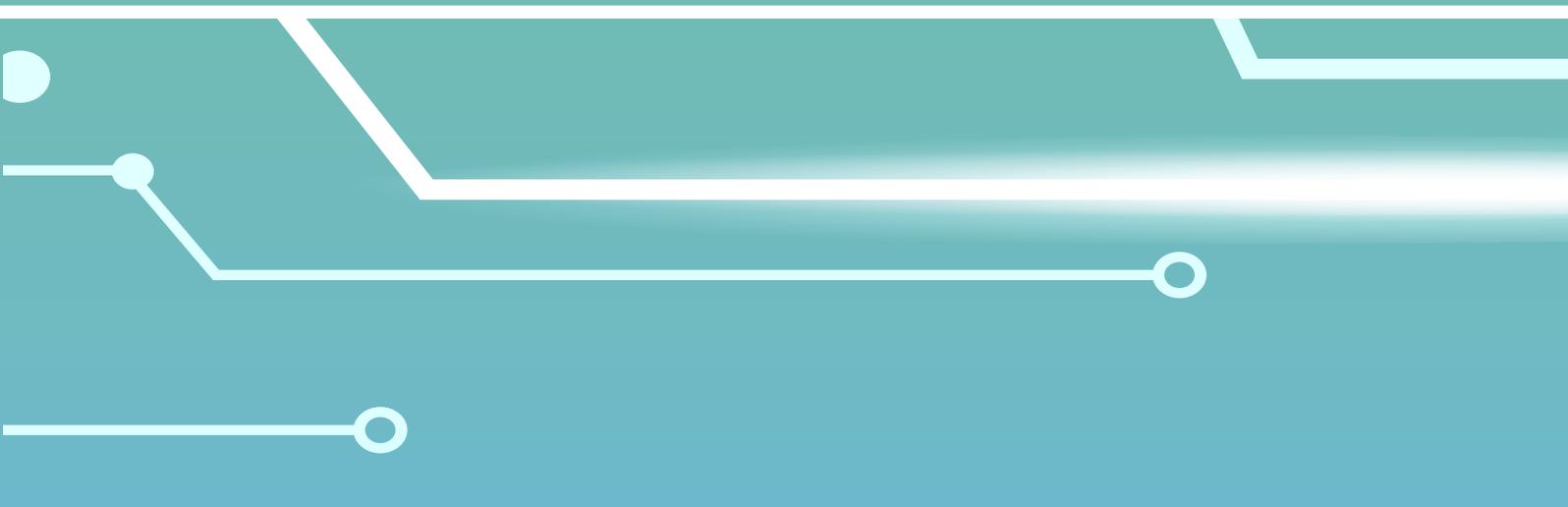


Penta (E! 9911), is EUREKA Cluster whose purpose is to catalyse research, development and innovation in areas of micro and nanoelectronics enabled systems and applications.





DISPERSE





16012



Electronic solutions for MRI scanning of patients with multiple implants drastically reduce examination time and increase accuracy [DISPERSE]

The occurrence of three or four concurrent medical conditions by the age of 70 is now common among an ageing population leading to more and more people wearing implanted medical-treatment devices. Unfortunately, current medical practice generally excludes patients with implants from access to magnetic resonance imaging (MRI). In the case of state-of-the-art implants, only patients with a single implant may be scanned, and even then under severe restrictions. This drastically increases examination time. The DISPERSE project does away with all these limitations, while delivering additional benefits.

What is most noticeable among an ageing population is a steep increase in the incidence of diabetes, musculoskeletal, cardiovascular and neurological diseases. Many of us will develop multiple clinical conditions, either chronic or acute. Studies on the prevalence of comorbidity show that at age 70, occurrence of three or four conditions is common. Treatment of many chronic conditions involves placement of implants or use of body-worn treatment-delivery devices. These electronic devices are mainly found in the elderly population. For numerous identified medical conditions, magnetic resonance imaging (or MRI, a way of obtaining detailed images of organs and tissues throughout the body without the need for X-rays or so-called 'ionizing' radiation) is required for diagnosis and treatment monitoring. As patients develop multiple medical conditions, many of those needing an MRI scan will have one or more implants.

Crucially, current medical practice excludes patients with one or more 'standard' active implantable medical devices (AIMDs) from access to MRI treatment, because MRI scanners need to use (electro-) magnetic fields which are far stronger than those encountered in everyday situations. This causes serious health inequalities for a rapidly growing group of patients. Now, scanning patients with a single, so-called state-of-the-art implant, is permitted under strict and limiting conditions. Unfortunately, these restrictions increase the typical examination time from 20 minutes (for a patient without an implant) to one hour (for patients with a single, advanced implant).

Reducing examination times, increasing scan accuracy

DISPERSE's key objective is therefore to develop the electronic means of reducing examination times of patients with multiple implants by a factor of three, while also improving scanning accuracy. This

objective will be achieved by developing electronics for spatially distributed sensor and transducer arrays exploiting synergies with other domains, which in turn will optimise the workflow for MRI-scanning these patients.

In particular, DISPERSE will develop:

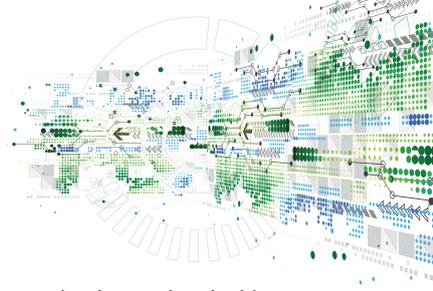
- Improved MR conditional implants (safe under certain tested conditions);
- Multi-implant coexistence;
- Optimal MRI workflow for implants;
- New and improved components.

Tangible results include:

- AIMDs causing less MRI distortion;
- New methods for multi-implant testing;
- Sensor arrays with increased density;
- Miniaturised, low-power sensor and actuator electronics (ASICs);
- High-speed, low-power and low-volume (refers to their small size, not low production volume) photonic modules for data transmission.

DISPERSE will develop a technology value-chain for creating large distributed multiple sensing arrays, including low-latency, interference-free data communication. These sensing networks have a large application potential in other markets, such as smart cities and space. In particular, DISPERSE will demonstrate applications in radio astronomy and acoustic surveillance of public space.





KEY APPLICATION AREAS

- Health & Well-Being
- Digital Life

ESSENTIAL CAPABILITIES

- Systems and Components Architecture, Design & Integration
- Safety, Security & Reliability
- ECS Process Technology, Equipment, Materials & Manufacturing

PARTNERS

- Cochlear
- UZ Gasthuisberg (KU Leuven)
- Luceda Photonics
- MinDCet NV
- Firecomms Limited
- Tyndall National Institute
- ASTRON Netherlands Institute for Radio Astronomy
- G-Therapeutics BV
- Philips Medical Systems
- Sorama BV
- Sound Intelligence
- Technobis

COUNTRIES INVOLVED

- Belgium
- The Netherlands
- Ireland

PROJECT LEADER

Mark van Helvoort
Philips

www.disperse.eu

KEY PROJECT DATES

01 February 2017 - 31 January 2020

Finding the right expertise mix

In order to meet key objectives, the project consortium includes a clinical end-user, application partners, as well as technology and knowledge providers, working together on innovations in photonics, micro-electronic design and packaging. As such, DISPERSE brings together implant manufacturers, an MRI producer and a hospital, together with two acoustic specialists, to develop new acoustic monitoring solutions for detecting patient anxiety. This solution will operate in the harsh MRI acoustic environment. A research partner from the space domain will also provide the project consortium with valuable knowledge on distributed sensor networks.

Wider implications, broader applications

In addition to the strictly technical and technological benefits mentioned earlier, DISPERSE's focus on diagnosis and treatment, for example, fits perfectly in the 'Continuum of Care', a concept involving an integrated system of care that guides and tracks patient over time through a comprehensive array of health services spanning all levels of intensity of care.

On the financial side, the implant market is expected to grow by 71% in 2015-2020, according to US data, and an increasing likelihood that someone aged 70 will require an MRI within the next 10 years could drive the double-digit CAGR (compound annual growth rate) for DISPERSE AIMDs, leading to a total market size of €6.9 billion in 2020. In that same year, the MRI market is expected to expand to €6.1 billion, thanks to shorter examinations times and improved diagnostic capabilities.

Now, DISPERSE's innovative devices for the healthcare market – such as photonic transceivers, ASICs for sensor arrays, and solutions for acoustic observation – have significant potential in at least four other markets:

- **Brain monitoring:** expected to reach US\$11.3 billion by 2020, from US\$ 7.5 billion in 2015 at a CAGR of 7% over the forecast period. Factors –

such as the increasing incidence and prevalence of neurological disorders; rising awareness about neurodegenerative diseases; technological advancements in devices; and growing incidence of traumatic brain-injuries – are driving market growth;

- **Smart cities and acoustic observation:** beyond acoustic patient observation, implementing an array of sound cameras will enable major breakthroughs in the emerging market of audio and classification for smart home (home care) and smart city applications, where there will be greater emphasis on the audio capabilities of video surveillance systems;
- **Space:** application activity focuses on the development of communication technology for a satellite-based radio telescope. Here there is interest in the communication module to be developed in DISPERSE. There is also interest in using DISPERSE as a model for EU-based companies to develop technology needed to build the future space telescope;
- **Photonic components and systems:** photonic data-transceiver technology and components developed in DISPERSE will address wide, lucrative and growing market-segments outside of the MRI application field, both within the healthcare domain, but importantly also in the industrial Internet of Things (IoT), a market which is predicted to reach \$8.6 trillion by 2025.

And interestingly, DISPERSE is also expected to 'disrupt' the therapy market and break the dominance of large pharmaceutical companies by influencing factors that challenge the strong growth of AIMDs.





DISPERSE

DISPERSE investigates solutions for MRI scanning of patients with multiple implants

A project in the EUREKA PENTA programme

Paris, January 18, 2018. The PENTA funding programme, managed by AENEAS, today highlights the DISPERSE project. This project aims to extend Magnetic Resonance Imaging (MRI) scanning to people who currently cannot benefit from this non-invasive technique due to multiple medical implants in their body.

With an aging population, ever more people with implants are likely to require medical scans for conditions such as cancer, neurodegenerative and musculoskeletal diseases. Today, many such patients cannot have MRI scans because their medical devices significantly distort images. Some patients with what are known as 'conditional implants' can have MRI scans, but the scan time is longer than normal. With the use of photonics, micro-electronic devices and innovative packaging solutions, the DISPERSE project is seeking to overcome these limitations and allow patients with multiple implants to be scanned in much faster and more accurately.

The project is also developing innovative techniques to monitor patient anxiety during the exam. An acoustic system based on multiple microphones detects patients' reactions in order to trigger adjustment of the operator workflow. In addition, this acoustic monitoring (enabled by integrated photonics) has the potential to be used in detection and surveillance systems in smart cities, smart homes and automotive applications.



Photo credit: Philips





About the PENTA programme (managed by the AENEAS Industrial Association)

PENTA is a EUREKA cluster whose purpose is to catalyse research, development and innovation in areas of micro and nanoelectronics enabled systems and applications - where there is shared national and industrial interest. Based on three key application areas, Transport & Smart Mobility, Health & Well-Being and Digital Industry for the first 3 calls, PENTA programme contributes to the development of electronic solutions with the opportunity for rapid competitive exploitation and a strong impact on European societal challenges. The PENTA project team is supporting SMEs, large corporations, research organisations and universities by facilitating access to funding, fostering collaborative work and creating consortia.

PENTA is managed by AENEAS, the European industry association.

About PENTA: <http://www.PENTA-eureka.eu>

About AENEAS: <https://aeneas-office.org>

About the DISPERSE project

DISPERSE is a RD&I project consortium involving 12 partners from 3 countries. The project partners are: Philips (project leader), Astron Netherlands Institute for Radio Astronomy, G-Therapeutics, Sorama, Sound Intelligence, Technobis, Cochlear, Gasthuisberg UZ Leuven, Luceda Photonics, MinDCet, Firecomms, Tyndall National Institute. National funding support is provided by the Netherlands, Belgium and Ireland.

About DISPERSE: <http://disperse.eu>





VIDEO



DISPERSE



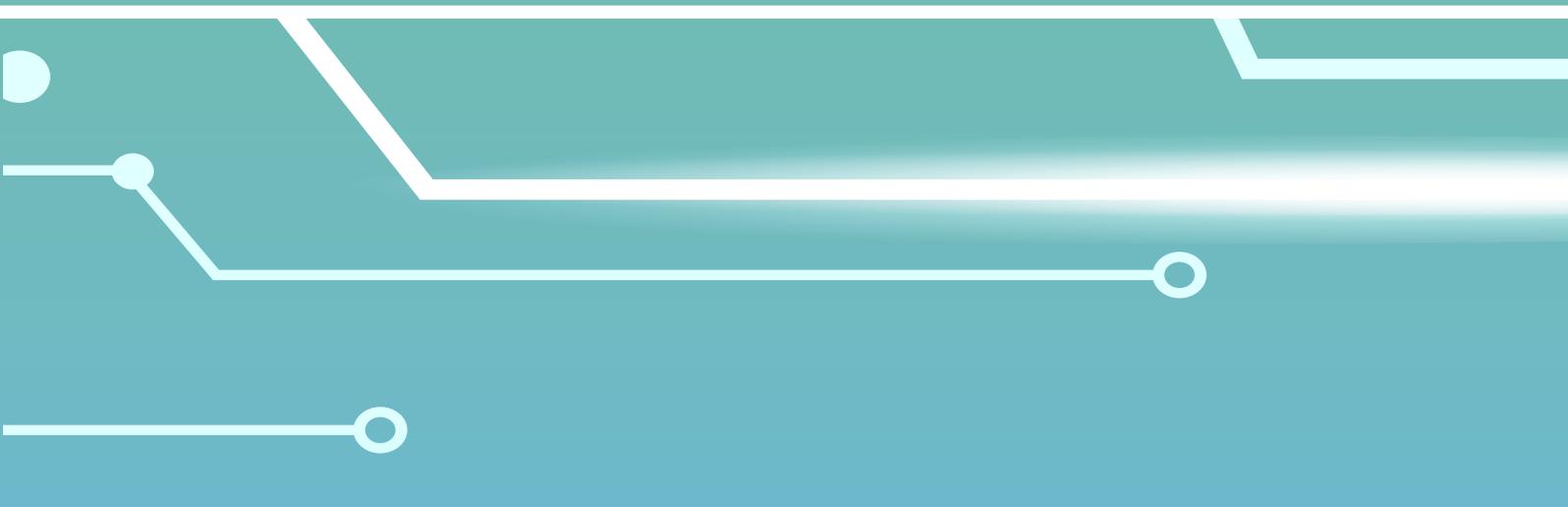
▶ Video: <https://www.youtube.com/watch?v=OWc2IMoJ3KM&feature=youtu.be>



DISPERSE



HADES





16003



Versatile test facility improves system and product quality while reducing design and operational costs [HADES]

The smooth operation of mission- and safety-critical systems calls for early detection of potential problems to avoid safety-related issues and to control costs. The versatile test facilities developed in the HADES project will go a long way to ensure systems are more robust and safer over the complete product lifetime, and help avoid dangerous and costly system breakdowns due to integrated circuit (IC) failures.

Failure in an electronic system could impact it in several ways, notably operational disruption, economic loss or questionable data-integrity. Importantly, mission- and safety-critical systems (like those deployed in the space, automotive, health care or avionic sectors) require early detection of potential problems to avoid safety-related issues and to control costs. In order to guarantee that these systems operate at optimal performance levels calls for the use of a network of embedded test instruments to monitor the status and operation of 'building blocks' or the entire system, providing key data for optimising performance and ensuring proper operation, or to predict future failures. In addition, extracted data must be handled using a standardised and secure interface; and firmware in mobile systems must be online tested and updated securely in real-time.

Unfortunately, current industrial test-technologies cannot handle the needs of a large variety of Internet of Things (IoT) devices that are just appearing on the market, for which large amounts of data must be handled in a secure way. Furthermore, despite the existence of industry standards for IC testing, there are no regulated standards, methodologies and tools that address all these requirements.

Developing a hierarchical and versatile test-infrastructure

HADES will develop and deliver a secure, hierarchical test-infrastructure based on existing standards. This test facility will be versatile and reusable and offer better system monitoring, resulting in reduced test and design costs. It will not only increase dependability through a standardised framework for handling numerous embedded test instruments (ETIs) at the electronic control system (ECS) level; but also on-chip-reliability monitoring and electronic design automation (EDA) tools with diagnostics and online self-repair capabilities. And all of this will be demonstrated at a component and system level.

The project will target the following domains:

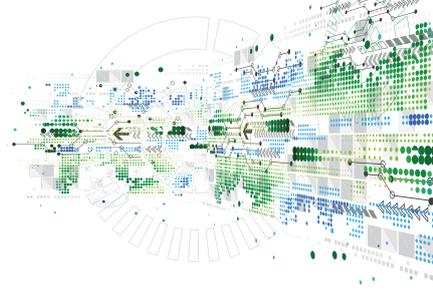
- Machine-to-machine and connected systems;
- Remote-controlled systems;
- Smart homes and mobile phones;
- Safety-critical systems (typically found in the automotive and avionics sectors);
- Mission-critical systems (such as in space and security applications).

HADES will deliver the following:

- Test capabilities and reusability throughout the product lifecycle;
- Test bus access at the required security level;
- Limited test costs compatible with IoT low-cost devices and high volumes;
- Online monitoring to enable prognostics and diagnostics, and improve dependability;
- Online monitoring for system power-management.

Core competencies

The project consortium is pan-European (from France and the Netherlands) and comprises five large companies; four small and medium-sized enterprises (SMEs); five academic and research institutions; as well as several OEMs. The consortium also provides the necessary expertise and experience needed to deliver a secure hierarchical online testing facility through ETIs. The large enterprises are already active in such areas as remote-controlled IoT systems, safety- and mission-critical systems, as well as automotive, smart homes and mobile applications. The SMEs, whose involvement is complementary to the work being done by the large companies, will focus on areas requiring their competencies. Academics and researchers will work on topics



KEY APPLICATION AREAS

-  Transport & Smart Mobility
-  Health & Well-Being
-  Energy
-  Digital Industry
-  Digital Life

ESSENTIAL CAPABILITIES

-  Systems and Components Architecture, Design & Integration
-  Connectivity & Interoperability
-  Safety, Security & Reliability
-  Computing & Storage
-  ECS Process Technology, Equipment, Materials & Manufacturing

PARTNERS

CEA / CNRS / Laboratoire d'Informatique de Robotique et Microélec IROC TECHNOLOGIES / ISSM / NXP Semiconductors France SAS / STMicroelectronics / TEMENTO SYSTEMS / Thales / TIMA Laboratory / Institut Polytechnique de Grenoble / Sorbonne University – LIP6 / D4T Systems / JTAG Technologies B.V. / NXP Semiconductor Netherlands BV / University of Twente

COUNTRIES INVOLVED

-  France
-  The Netherlands

PROJECT LEADER

Brigitte Descouts
STMicroelectronics

www.project-hades.eu

KEY PROJECT DATES

01 October 2017 - 30 September 2020

and challenges beyond state-of-the-art, and on unresolved technical and technological issues. This mix of project partners and expertise ensures that the project addresses relevant industrial problems and stays at the R&D cutting-edge throughout the project and beyond.

Improving quality, reliability and competitiveness

HADES not only supports failure detection, but also provides such capabilities as failure prevention, self-healing, self-repair and fault tolerance. In addition, it facilitates diagnosis and failure analysis and contributes to better system traceability. Furthermore, since ETIs will come with dedicated software, they will facilitate interaction and control across the complete ecosystem (such as IC manufacturer, system integrator and customer). Crucially, all concepts and techniques will be developed according to strict system-security principles. And by offering system developers greater robustness and dependability, HADES will make European products more competitive and ensure their wider use though improved quality (eliminating health hazards, for instance, will make them more attractive).

A promising market

It is important to point out that test tools are increasingly playing a key role in the overall manufacturing value-chain, regardless of product and its projected lifetime. Crucially, test is becoming a key enabler for IC and systems manufacturers to deliver products at the quality and cost-levels demanded by the market. In fact, without the backing of a powerful test architecture and test services, a product's sales potential will be reduced.

The global automated test equipment (ATE) market is expected to be valued at US\$4.48 billion by 2020, according to Radiant Insights. In addition, increasing design complexity, coupled with the need for effective testing, is expected to drive demand in the global automated

test-equipment market. Prime Research offers a broader view of the overall test market by including the electronic manufacturing segment, which is expected to represent another US\$1.28 billion in 2014.

Furthermore, markets where HADES is expected to create added-value and enhance competitiveness are also growing, thereby also driving demand for this project's test deliverables. Gartner forecasts almost 30% growth through 2020 for IoT semiconductor revenue, which spans every industry and is driven by the immense scale of low-cost devices. Some in the industry even believe this growth will transform the semiconductor business. A case in point is automotive, which will see a significant rise in demand for semiconductors due to a 30% annual increase in networked cars, and where one in five automobiles will be receiving internet services by 2020. In fact, the total semiconductor revenue from electronic equipment is expected to reach US\$45 billion in 2020, and with strong demand in the next ten years, IoT, which is at the heart of this growth, will generate revenues of US\$11.5 billion in 2018.

Finally, consumers looking to enhance their lifestyles will also play a central role in growing IoT demand. In the home, where each household could contain more than 500 devices by 2022, demand will grow for semiconductors. Smart TV and set-top box (STB) revenues will continue to increase, and so will remote patient-monitoring for post-surgery or chronic-disease surveillance (in the USA, 86% of all health-care spending in 2010 was for people with one or more chronic medical conditions). Wearable systems are also expected to grow by more than 280% between 2015 and 2018. And other personal devices, like smart glasses, smart watches and mobile phones, will also be in greater demand as these devices start to play a bigger and more significant role in the life of the consumer.



HADES

HADES project develops automated chip-level testing for safer, more reliable IoT systems at lower cost

A project within the EUREKA PENTA programme

Paris, Thursday 28 February 2019 - Increased safety, reliability and cost-control for Internet of Things (IoT) devices are the focus for HADES, a EUREKA PENTA Cluster project, managed by Industry Association AENEAS. Vast numbers of devices are becoming connected via the IoT, from smart phones and smart home systems to safety-critical systems in airplanes and road vehicles. Indeed, every household could contain 500 connected IoT devices by 2022. This ever-increasing complexity calls for a new generation of miniature electronics test instruments that can be built into devices and systems to keep them operating safely, dependably and with optimal performance. HADES's next-generation test facilities will go beyond current solutions, leading to systems that are more robust and safer over the complete product lifetime. They will also help avoid dangerous and costly system breakdowns due to integrated circuit (IC) failures.

The market potential for HADES test facilities is huge covering IoT, automation and consumer devices. By 2020, the global automated test equipment (ATE) market is expected to be worth US\$4.48 billion¹. Specifically, the project will address machine-to-machine and connected systems, remote-controlled systems, smart homes and mobile phones, safety-critical systems (typically found in the automotive and avionics sectors) and mission-critical systems (such as in space and security applications). For IC and systems manufacturers, test is becoming a key enabler to create products at the quality and cost-levels demanded by the market. By offering system developers greater robustness and dependability, HADES will help make European products more competitive and attractive through improved quality.

The test capabilities delivered by HADES will be based on existing standards and provide a standardized framework for numerous embedded test instruments (ETIs) at the electronic control system (ECS) level. These will be versatile and reusable throughout the product lifecycle, which is key to reduced test and design costs – an important advantage for high-volume, low-cost IoT devices. They will also allow for online monitoring for prognostics, diagnostics and power-management, which means devices will operate more dependably and with greater energy efficiency.

The HADES project consortium is pan-European, comprising five large companies, four small and medium-sized enterprises (SMEs), four academic and research institutions, and several OEMs. This mix of project partners and expertise will ensure that the project addresses relevant industrial problems and stays at the cutting-edge of R&D throughout the project and beyond.

¹ Source: Radiant Insights Oct 2015 <https://www.radiantinsights.com/press-release/global-ate-market>





About the PENTA programme (managed by the AENEAS Industrial Association)

PENTA is a EUREKA cluster whose purpose is to catalyse research, development and innovation in areas of micro and nanoelectronics enabled systems and applications - where there is shared national and industrial interest. Based on the Electronic Components & Systems (ECS) Strategic Research Agenda (SRA) key areas and essential capabilities, PENTA programme contributes to the development of electronic solutions with the opportunity for rapid competitive exploitation and a strong impact on European societal challenges. The PENTA project team is supporting SMEs, large corporations, research organisations and universities by facilitating access to funding, fostering collaborative work and creating consortia.

PENTA is managed by AENEAS.

More on PENTA: <http://www.penta-eureka.eu>

More on AENEAS: <https://aeneas-office.org>

About HADES

HADES is a RD&I project consortium involving 14 partners from 2 countries. The project partners are: CEA, CNRS-LIRMM, D4T Systems, IROC, INVIA-ISSM, JTAG Technologies, NXP Semiconductors (France and Netherlands), STMicroelectronics, TEMENTO Systems, Thales, TIMA Laboratory, University of Twente and UPMC. National funding support is provided by France and The Netherlands.

More on HADES: <https://www.project-hades.eu/>

HADES

Hierarchy-Aware and secure embedded test infrastructure
for Dependability and performance Enhancement of integrated Systems

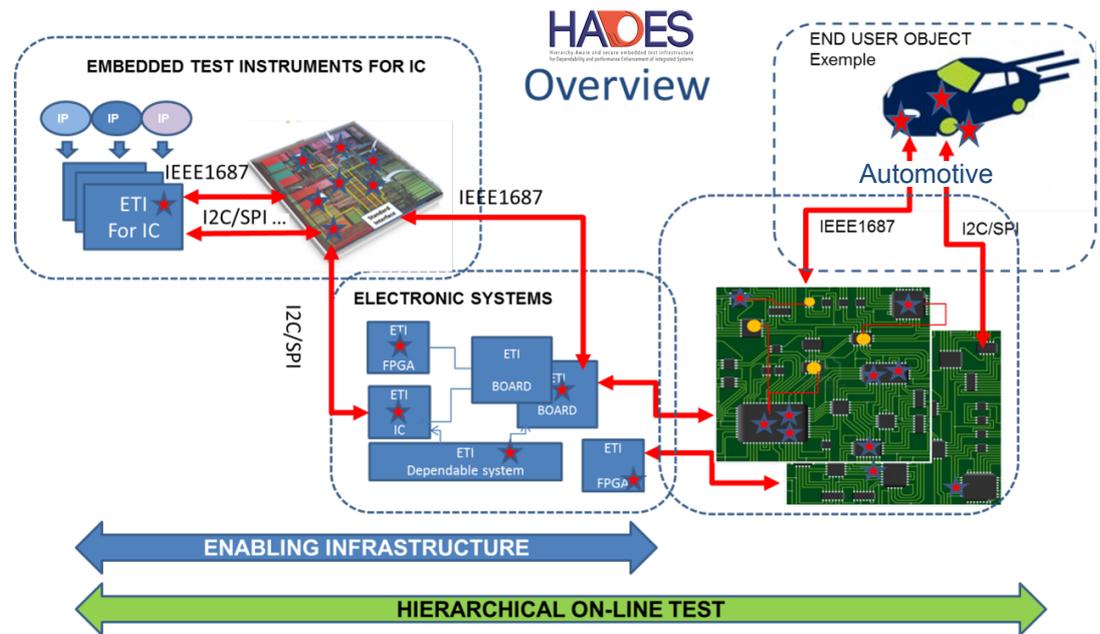




PROJECT IMPACT

16003

HADES (Hierarchy-Aware embedded test infrastructure for Dependability and performance Enhancement of Systems) has improved the functional safety of Electronics Components and Systems in order to prevent dangerous failures or to control them as they occur. [HADES]



Today's electronic systems require high reliability and functional safety. The "Manufacture and forget" approach has been phased out and equipment vendors are expected to provide support through the entire lifetime of their products. The solution is to use test features to manage reliability challenges, increase operational lifetime and support extended operating environments and dynamic applications.

Background, objectives of the project and challenges

HADES provides solutions for self-test and self-diagnosis of Systems-on-Chips (SoCs) while improving their dependability. More specifically, the project aims at embedding into SoC networks multiple embedded test instruments (ETIs) for both analog and digital Intellectual Property (IP) cores that are interfaced to a common digital test infrastructure. The ETIs equip the SoC with key capabilities; such as reliability monitoring to alert the end-users before the failures occur, on-line self-test to detect failures due to latent defects and aging, and data collection for failure diagnosis purposes. ETIs also offer feedback for self-repair, performance optimisation, and reliability enhancement. The goal is to design flexible ETI's that are reusable from post-manufacturing testing to on-line testing in the field of operation.

The test interface is based on the new standard

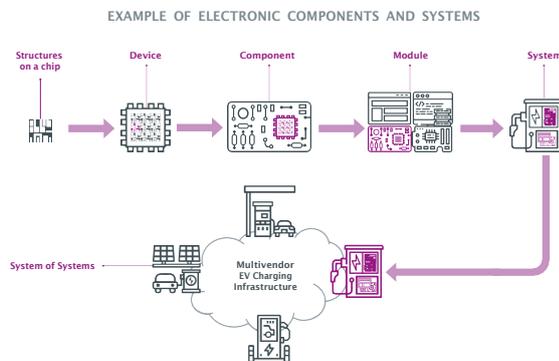
IEEE1687 which has allowed the possibility to build advanced hardware-software environments to monitor and control many different embedded instruments and related applications. Securing the test infrastructure has been of main concern to prevent unauthorised access that could result in stealing secret keys, performing memory dumping, and modifying memory values to get a privilege escalation.

HADES goes beyond the state-of-the-art by moving from a classic design approach, based on a post-silicon fabrication test paradigm, to a new more efficient, scalable and low-cost on-line test approach.

The scope of HADES has been to develop a comprehensive environment to perform the testing of the electronics systems. The range of Electronic Components and Systems (ECS) is very wide, going from transistors in silicon chips acting as individual electrical switches, through the integration in smart systems, up to global System of Systems



(SoS) performing complex cognitive tasks and interacting with numerous humans and machines. A very simplified view of this ECS “stack” or “Russian dolls” is shown in the Figure below:



The Proliferation and Imbrication of ECS in the Electric Vehicle charging infrastructure

Source: Eurotech- Illustration from ECS SRIA 2021 page 14

Ensuring the reliability, safety and security of ECS has become a major challenge since the simultaneous demand for increased functionalities and continuous miniaturisation of ECS causes interactions on multiple levels.

Technological achievements

HADES has addressed multiple challenges; such as setting up the infrastructure and the software to test the chip, using the new standard communication protocol IEEE 1687, developing tools for the reliability analysis to conform to safety standards such as ISO 26262 for the Automotive market. Access for die testing was enabled by Built-in-Self-Test and Equipment Test Instruments. The portability of the interface and communication software has also been developed to address multiple application domains.

Implementation of the standard IEEE 1687

This required a hierarchical approach for testing all the components of the system. Temento Systems, Tima Laboratory and STMicroelectronics have demonstrated the capability of the IEEE1687 standard to monitor a board and a chip, as well as NXP Semiconductors Netherlands on another demonstrator. They have also implemented a limited pin test interface with an analog test bus, which resulted in the filing of a patent.

TIMA Laboratory, University of Twente and JTAG technologies have developed efficient algorithms and extended their software with IEEE1687 support, achieving scalability, interactive behaviour and lifetime portability.

D4T Systems has developed basic compatibility in their software tools for the new IEEE1687 standard.

Development of Embedded Test Instruments (ETIs)

NXP Semiconductors France and CNRS-LIRMM have developed Embedded Test Instruments (ETIs) that enable testing of Radio Frequency devices using standard digital Automatic Test Equipment. Targeted Application: Smart Home ZigBee Transceiver (2.4GHz) from NXP Semiconductors intended for the IoT market.

TIMA Laboratory and STMicroelectronics have demonstrated an ETI that achieves the static linearity built-in self-test of Successive-Approximation-Register (SAR) analog-to-digital converters (ADCs) that are built using capacitive digital-to-analog converters. A dramatic test time reduction has been achieved.

Université Pierre et Marie Curie (UPMC) newly Sorbonne University has developed low-overhead ETIs for analog and mixed-signal IP cores that are reusable for post-manufacturing testing, on-line testing in the field of application, and failure analysis and diagnosis. Sorbonne University has also developed ETIs for fault-tolerance in hardware accelerators for Spiking Neural Networks (SNNs), which constitute the third generation of neural networks aiming at bridging the gap between biology and machine learning.

iROC Technologies has developed a complete library of ETIs and infrastructure for a systematic technology qualification and measurements of the chips. The effectiveness of these ETIs has been demonstrated on CMOS 65 and 28 nm, up to FinFET technologies. An Electronic Design Automation (EDA) platform was built to validate the functional safety of complex circuits targeting ISO26262 certification.

D4T Systems has developed a new software add-on to quickly analyse the performance of ETI's in a system model simulation. The results are achieved in collaboration with University of Twente. Two papers have been published on the topic.

CNRS-LIRMM and CEA have developed low-overhead ETIs (reliability, area and power overhead trade-off) based on approximate computing circuits to tolerate faults in advanced ICs.

LIRMM and STMicroelectronics have developed a learning-guided approach for diagnosis of mission mode failures. Proposed solution provides reduce and accurate list of candidates to guide the failure analysis phase.

Security of test infrastructure

The aim is to provide a practical path toward better security by protecting electronic systems test bus access from any evil-minded intrusion while maintaining strict compliance with test standards and without affecting test economics and quality.

TIMA Laboratory, CNRS-LIRMM and JTAG Technologies have worked on the security of test infrastructure access and Secure Data transfer. They have succeeded in integrating data scan encryption in a standard test flow. This secured test infrastructure was successfully implemented on Xilinx boards and on a JTAG Technologies JT 2156 training board.



JT 2156 training board
Copyright JTAG technologies

Some functionalities on a SoC can operate at specific cycle time, while other functionalities may operate at cycle times $n/2$, $n/3$, etc. Thales SIX GTS was able to develop a unique Logic built-in self-test (LBIST) on several clock domains, instead of testing each individual domain, by themselves, at that domain frequency. This LBIST will be soon embedded in a big Application Specific Integrated Circuit ASIC (230mm²) taped out in a 65 nm technology.

Thales-Design Services (DIS), ex INVIA, has investigated and developed a flexible ABIST to process internal (CPU driven) or external (Software driven) test, increasing the reliability and security of Integrated Circuits (ICs). It is designed to get a single signature from the test of multiple analog IPs present in an IC. It allows detecting defects or physical attacks in analog modules when the Automatic Built-In Self-Test ABIST system is launched during production test or on the customer side depending on configurations.

Demonstrators

iROC Technologies has developed methodologies and set-ups for complete reliability and functional safety assessment before and during chip design (through EDA) and after chip manufacturing through a test set-up able to submit a chip to multiple variety of tests: radiation, environmental testing as well as hardware fault injection.

A video that shows TIMA laboratory ETI for SAR ADCs static linearity test is available on public platforms: <https://hades.iroctech.com/videos/>

TIMA Laboratory has also developed methods and a digital core for image quality evaluation and optimisation loop for detection and correction of defective pixels in CMOS imagers, paving the way for self-healing imagers.

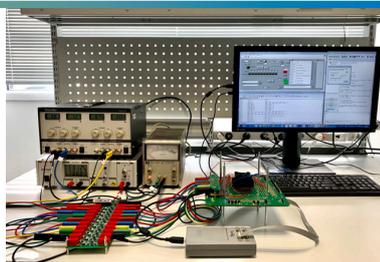


Image Quality Optimisation

Copyright TIMA Laboratory/Institut Polytechnique de Grenoble

NXP Semiconductors France and CNRS-LIRMM have developed an indirect test strategy that considerably lowers the cost of the industrial testing phase of RF circuits. This generic framework approach was successfully tested on NXP products and will soon be further extended for the lifetime verification of RF circuits.

STMicroelectronics, TIMA Laboratory and Temento Systems have developed a 1687 demonstrator based on a SoC processor silicon product. The SoC targeted embeds the state-of-the-art of different elements of the safety mechanism, including the basics like SRAM BIST or more advanced ones like in-situ slack monitors. The best candidate interface, as studied in other work packages, is used to access, and control, this safety mechanism in a way that they can be used as an ETI.



IEEE 1687 demonstrator based on a SoC processor silicon product

Copyright Temento Systems

Market Potential

With a forecast of more than 40 billion of connected devices in the world in 2025, the market for IOT-dedicated integrated circuits is getting very competitive. Typical examples of such circuits are Systems on Chip that integrate the application processor together with embedded RF front-end. Along with the growth of industrial and home appliances, protocols such as BLE and Zigbee® have become ubiquitous for short-range communicating devices.

NXP is one of the leaders of the home automation and the IoT semiconductor market. To be able to keep this leadership, the testability, quality and features of those

products must be improved constantly. The impact of HADES is essential in terms of quality, test cost, time to market, and its results help improve two main fields:

1. An auto-test feature is essential to guarantee the proper functionality of safety critical products such as fire detectors, entrance access control, smart metering and even healthcare devices.
2. An improved production cost together with new application features help maintain research and development activities in France. HADES innovation is also deployed within other European sites and at NXP worldwide.

The expected impact is the improvement of quality (Parts Per Million) by a factor of 2 for the production test. In term of test cost, a reduction of 30% on test equipment cost is expected, thus improving market share in this highly competitive consumer market.

The automotive transformation will boost the silicon value in the car, which is expected to reach 45 Billion \$ in 2023 (Source: IHS – Automotive semiconductor market tracker – June 2020).

The heart of the ADAS applications (Advanced Driver Assistance System) is a system on chip whose ultimate goal is to transform the car into an autonomous vehicle. ADAS has to be 100% dependable and the ETIs developed in HADES demonstrated a proof of concept in hierarchical tests of the SoC that will be a differentiator with respect to the competition.

NXP Semiconductors Netherlands is a major industrial player in the car digitisation and developed an enhanced design automation for on-chip instrument infrastructure using IEEE 1687 ICL. They issued the European patent 82154724 “Limited Pin Test Interface with Analog Test Bus”. The innovation will reduce the test effort by 60%, thereby reducing the time to market and lowering the production test cost.

Thales SIX GTS developed a new LBIST insertion flow, using also the IEEE1687 standard, and the LBIST management module is expected to be reused in future ICs embedded in a range of products delivered by THALES.

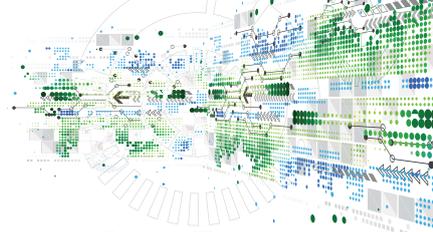
THALES DIS, has developed a flexible ABIST controller to process internal (CPU driven) or external (Software driven) test, increasing the reliability (defects) and security of ICs. This ABIST controller will be embedded on secure ICs products, especially when Machine-to-Machine (low defect rate) type of products are required and in secure and certified IPs (used for System On Chip securitisation) type of product.

Spill overs have also benefited SMEs: D4T System software solution is positioned between chip design and manufacturing with an impact on more robust, more reliable applications for several high-quality end markets. The compliance to standards makes this new product scalable to other application domains increasing the impact of HADES developments to a wider variety of system products.

JTAG Technologies enlarged the use of their IEEE 1687 tool to reach all the test instruments, and this improvement will further promote JTAG Technologies existing tool chain to support more customers that exploit the IEEE 1687 capabilities.

TEMENTO enriched their software existing product with a set of ETIs based on the 1687 standard and demonstrated it while running fault injection.

Exploitation is promising with a first beta site expected in 2021. iROC Technologies currently hold a leading position with their SoCFIT EDA platform and new capabilities have been added, targeting the certification for ISO26262 Tool Confidence Level 3, key to address



KEY APPLICATION AREAS

-  Transport & Smart Mobility
-  Health & Well-Being
-  Energy
-  Digital Industry
-  Digital Life

ESSENTIAL CAPABILITIES

-  Systems and Components Architecture, Design & Integration
-  Connectivity & Interoperability
-  Safety, Security & Reliability
-  Computing & Storage
-  ECS Process Technology, Equipment, Materials & Manufacturing

PARTNERS

CEA
 CNRS - Laboratoire d'Informatique, de Robotique et Microélectronique de Montpellier (LIRMM)
 D4T Systems SA
 iRoC Technologies SA
 JTAG Technologies BV
 NXP Semiconductors France SAS
 NXP Semiconductors Netherlands BV
 STMicroelectronics
 Temento Systems SAS
 THALES DIS DESIGN SERVICES SAS
 THALES SIX GTS FRANCE
 TIMA Laboratory/ Institut Polytechnique de Grenoble
 University of Twente
 UPMC - Université Pierre et Marie Curie
 newly Sorbonne University

COUNTRIES INVOLVED

-  France
-  The Netherlands

PROJECT LEADER

Jean-Luc Bataillon
 STMicroelectronics

the electrical cars and ADAS market. 2 to 3 new licenses per year are expected.

Societal & Economic Impact

The semiconductor total available market grew by 7.3% in 2020 compared to 2019, despite the Covid-19 pandemic and the political conflict between the United States and China. This demonstrated to politicians, key decision-makers and the general public that semiconductors are a Key Enabling Technology in a digitised society. More and more cars are now equipped with several image sensors and algorithms, powered by artificial intelligence to capture the environment around the car and take action, like emergency breaking. Such features will have to be adopted by a large majority of drivers if the objective is to move to autonomous driving, and the sine qua non condition is to develop electronic system and software with a 100% reliable functional safety that, for example, will be able to alert the driver and pull over the vehicle in case of a failure of the autonomous driving controller.

The quality, reliability, safety and cybersecurity of electronic components and systems are, and will be, fundamental to a society that is more and more digitised This key domain of the ECS was strengthened by HADES, as well as the technological leadership of the involved partners.

Similarly, the research organisations, e.g. CNRS-LIRMM, Sorbonne University, TIMA Laboratory, and University of Twente, have gained valuable knowledge working together and with industry towards functional safety solutions for microelectronics. Some of the material that was developed during the course the project is already included in M.Sc. programme curricula of Universities in France and the Netherlands. Research organisations have also offered several tutorials in international conferences and summer schools on topics related to the project. 14 PhD theses have been carried out within the framework of the project, enhancing significantly the labour force in this domain.

Patents/Standardisation/Publications

The project results from HADES featured strong dissemination activity and achieved considerable publicity, targeting high-impact and world-class conferences and journals. 56 international conference articles, 17 journal articles, 17 workshop articles were published, together with 8 invited talks and 6 keynote talks presented in conferences. The project results were presented at EF ECS 2020, with posters and videos made available in the virtual booth. The partners also delivered a Special Session at the IEEE conference IOLTS'20 dedicated to the project.

The implemented innovations are protected by 3 patent applications:

- NXP Semiconductors NetherlandsL: European Patent 82154724 "Limited Pin Test Interface with Analog Test Bus"

- TIMA Laboratory: M Portolan_ "Test apparatus and method for testing an integrated circuit". Patent No. FR3066606A. 23 March 2018.

- CEA: M. Seif and V. Gherman, "Device And Method For Controlling Refresh Cycles Of Non-volatile Memories", FR1658135 (070550 US FLO/VBO)

3 MSc thesis / 14 PhD dissertations were produced.

NXP Semiconductors NL was active in IEEE P1500, IEEE P1687.1 and IEEE P1687.2 workgroups to drive third party silicon IP and EDA. iROC Technologies is a member of French ISO 26262 committee and a member of the Working Group for the JEDEC JESD89B revision. University of TWENTE was also very active in TESTA (TESt STandard) workshops on (mixed-signal) JTAG (IEEE 1687.1/2) standardization. TIMA Laboratory participated in the leading standardisation proposal for support of non-JTAG interfaces inside the IEEE P1687.1. Sorbonne University was active in the working group activities of the 2 standards IEEE P1687.2 (Standard for Describing Analog Test Access and Control) and IEEE P2427 (Standard for Analog Defect Modelling and Coverage).

Future Developments:

Today, most applications and standards in the electronics components and systems domain require high reliability, security and functional safety. As such, the topics explored in HADES are, and will be, fundamental to digitised society.

HADES can be considered a precursor project and the numerous activities & innovations demonstrated in HADES established the foundations for going even further to develop new disruptive applications related to electrical cars and ADAS, Advanced Space missions and Medical - especially Implantable devices. The markets in these 3 sectors, in which Europe already has a strong share, will experience spectacular growth.

Novel ETIs will be needed to focus on automated intelligent insertion, using on-chip Intelligence techniques based on Machine Learning, to extend the applicability and usefulness of physical data. The support of new and upcoming standards for the IoT, for reliability, for functional safety, for security, such as ISO 26262, IEEE P2851, IEEE 1687, will need close collaboration among all players to build leadership going forward in this coming generation of advanced Components and Electronic Systems.

Novel Software and EDA are needed to manage FuSa/R and complexity of novel applications:

- Massive use of Machine Learning techniques
- Introduction of a novel concept "Design for FuSa/R", in line with the existing DFM/DFR (Design for Manufacturing/Reliability)
- Sensor data fusion for data presentation.

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Hyb-Man





16013



Integrating design and production into a single end-to-end process creates flexible manufacturing and a quicker response to market demands

[Hyb-Man]

The Hybrid 3D Manufacturing of Smart Systems project (or Hyb-Man) will impact the European electronics manufacturing industry by delivering expertise in the individual technologies, integrating them into one, end-to-end hybrid 3D manufacturing process. This will create value in European manufacturing.

Producing today's electronic products is generally an assembly of separate parts: housings, structural elements, populated PCBs and discrete devices, brought together in a complex sequence of semi-automated steps and then tested as a complete assembly. Furthermore, the drive to reduce cost and improve quality has resulted in standardised components and sub-assemblies that are made into mass-produced products.

Unfortunately, this approach requires large, separate production lines for the sub-assemblies (such as PCB and housing); high investment levels for equipment/tooling; and substantial labour overheads for the manufacturing of the final product, including handling, assembly, interconnect and process control. Furthermore, the value chain is fragmented, with substantial 'parts tourism' (components are often shipped over long distances to different process steps in the value chain). This increases lead-times and has a negative environmental impact. Moreover, in the past decades we have seen a major part of electronics mass-manufacturing migrate from Europe to Asia, where low-wage economies and the availability of human capital resonate well with the requirements of fixed-configuration, mass electronics-manufacturing.

Implementing flexible, first-time-right production

Hyb-Man will respond to these drawbacks by developing innovative hybrid 3D manufacturing methods with the objectives of attaining high flexibility and first-time-right production. These methods are based on multi-material additive manufacturing (AM) – also referred to as 3D printing – as a core production technology, combined with automated assembly and the integration of electronic parts.

The project will first develop individual processes, and subsequently combine them into a single, integrated production chain that includes design rules, in-line testing and quality monitoring to a high-technology readiness level. The resulting production process will be highly flexible, because

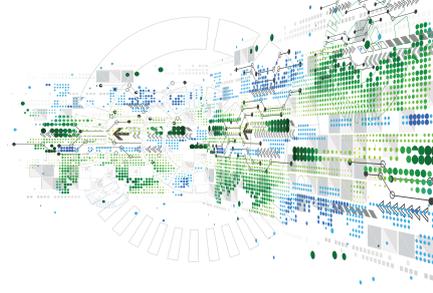
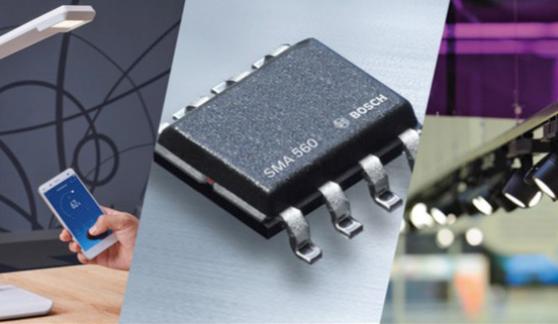
it is a digital process driven by data, which does not require product-specific equipment, tooling or moulds. This migration from tool-centricity to data-centricity is the key factor that impacts cycle times, process-setup costs and design/product flexibility.

Key project activities and deliverables will be:

- Developing end-user/product specifications from the LED lighting and automotive-sensor applications to be used to derive process and metrology requirements;
- Developing hybrid 3D manufacturing technologies which meet these requirements and are mutually compatible;
- Developing materials for electrical conductive, insulating and structural elements in parallel with these processes;
- Developing design rules for products and processes, based on the relationship between the processes, materials and product properties;
- Integrating these technologies and in-line control methods into a single, process-flow architecture, including the required hardware/software to be used for process-tuning and optimisation;
- Producing demonstrators and prototypes for the LED lighting and automotive-sensor application use-cases, using the integrated process flow-architecture;
- Evaluating the demonstrators to provide feedback on the process performance and to identify improvements.

Key project competencies

To make AM suitable for electronic end-products, individual and combined processes, quality standards, reliability and integration with current methods, all of these need to be brought to a higher maturity level. The project consortium provides the technical competencies required across the complete value-chain: materials, processes, equipment, products and applications. This



KEY APPLICATION AREAS



Digital industry



Digital Life

ESSENTIAL CAPABILITIES



Systems and Components :
Architecture, Design & Integration



ECS Process Technology, Equipment,
Materials & Manufacturing

PARTNERS

Fraunhofer-Gesellschaft zur Förderung der
angewandten Forschung e.V

Henkel AG & Co

KGaA, Neotech AMT GmbH

Robert Bosch GmbH

XENON Automatisierungstechnik GmbH

Eindhoven University of Technology

Philips Lighting B.V

Reden BV

Technolution BV

TNO - Nederlandse Organisatie voor Toegepast
Natuurwetenschap

VSL

COUNTRIES INVOLVED



Germany



The Netherlands

PROJECT LEADER

Rob van Asselt
Philips Lighting B.V.

<http://hybman.eu>

KEY PROJECT DATES

1 April 2017 - 31 March 2020

consortium will also have considerable market impact, not only on the integrated electronic end-products, but also on new materials, processes and equipment, software and simulation tools, as well as knowledge/design rules.

Flexible production creates key business advantages

Flexible production is achieved through the removal of product-specific tooling; the absence of large stocks of end products; local production; and form-freedom in production. This will lead to such substantial business benefits as:

- Faster response to changes in the market, with localised production and reduced component and tooling lead times;
- Increased product diversity by adopting flexible manufacturing technologies;
- Cost-effective manufacturing of small series and customer-centric (semi-bespoke) solutions;
- New product designs offering improved functionality and new form factors not previously possible.

Now, these business benefits will give European electronics-manufacturing companies the ability to maintain their leading position in the rapidly changing market for electronic products, which increasingly demand optimised and semi-bespoke solutions. The constraints of current manufacturing infrastructure, optimised for low-cost/high-quality products that are mass produced in enormous quantities in Asia, result in standardised components and product designs. They also lead to limited shape freedom and a rigid supply chain; as well as pressure to minimise variation and allow high fixed-manufacturing costs to be amortised over many produced units.

Opportunities in flourishing markets

The AM global market is expected to grow to €6.5 billion in 2016 and exceed €19 billion in 2020. Current developments in AM for medical, automotive and aerospace applications are significant. The global market for electronics manufacturing services was €1,200 billion in 2014, with an expected growth to €1,600 billion in 2019. Two important trends relevant to Hyb-Man are the increasing demand to produce embedded electronics; and the market penetration of printed electronics and hybrid systems – signifying integration of printed and silicon-based components. Products that combine both technologies will increasingly drive a printed-electronics market. Assuming hybrid manufacturing in Europe can capture 1% of the AM market, this would already represent a potential market value of €200m in 2020.

Finally, significant advances in information and communication technology, combined with sensor technology and robotics, open up new opportunities in what is called Internet of Things (IoT). This is a very wide market and includes consumer, industrial and government applications. It is estimated that by 2020, dozens of devices per human being will be connected to the internet. This means an annual growth of 20% and a potential value of €12 trillion in terms of IoT. The demand for connected devices spans multiple industries, and is also seen as an opportunity for reshoring manufacturing. Notably, Europe has potentially a full eco-system for IoT, ranging from market leaders in smart sensors, embedded systems, software, network vendors and telecommunication, to application integrators, dynamic small- and medium-sized enterprises and industrial early-adopters.

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Hyb-Man

Hyb-Man to transform production of smart electronic systems using 3D manufacturing methods

A project within the EUREKA PENTA programme

Paris, 5 April 2018 – The EUREKA PENTA funding programme, managed by AENEAS, today highlights the Hyb-Man project. The Hyb-Man (Hybrid 3D Manufacturing of Smart Systems) project is developing additive manufacturing methods (also known as 3D printing) to enable flexible, first-time-right production of smart systems for lighting and automotive applications. Partners in Hyb-Man aim to develop 3D manufacturing as a core production technology. This will be combined with automated assembly and integration of electronic parts, design rules, in-line testing and quality monitoring. Together, these will make the entire production process more flexible. Manufacturers will be able to respond rapidly to changing market demand, expand their product diversity, offer cost-effective manufacturing of small product runs, and produce designs and form factors currently not possible.

The market for electronic products is evolving, with growing demand from manufacturers for customised and semi-bespoke solutions. However, up to now, the emphasis has been on mass production of standardised components and assemblies. Electronic products are made from separate devices and components, in a series of semi-automated processes, and then tested as a complete assembly. This requires dedicated production lines and specialised tooling. In addition, such manufacturing often relies on low-wage economy labour and transportation of parts around the world. Hyb-Man will transform this situation by basing core production on the digital processes of 3D printing which eliminate the need for dedicated manufacturing lines and product-specific tools.

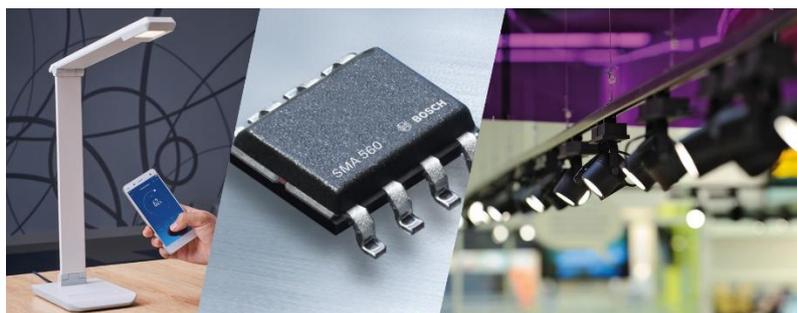


Photo credit: Philips Lighting and Bosch

The project has major potential for European industry and involves partners from across the entire electronic components and systems value chain. Hyb-Man methods will boost Europe's ability to compete in the global market for electronics manufacturing services, which was worth €1,200 billion in 2014 and is expected to grow to €1,600 billion in 2019¹. They will enable European industry to bring back production from others part of the world, as well as reducing environmental impact and increasing opportunities for recycling. Europe's manufacturers will also be able to respond to the increasing demand for embedded electronics², and the emergence of printed electronics and hybrid systems (printed and silicon-based

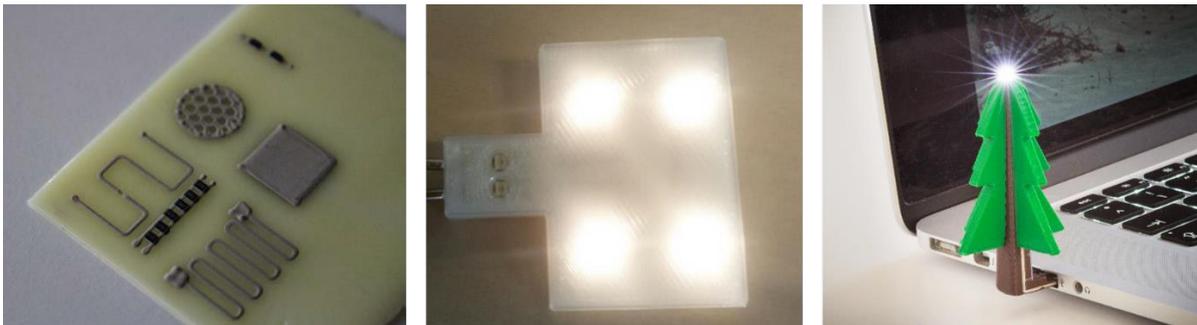
¹ <http://www.researchandmarkets.com/reports/3340028/the-worldwide-electronics-manufacturing-services>

² <http://www.rm-platform.com/linkdoc/AM%20SRA%20-%20February%202014.pdf>



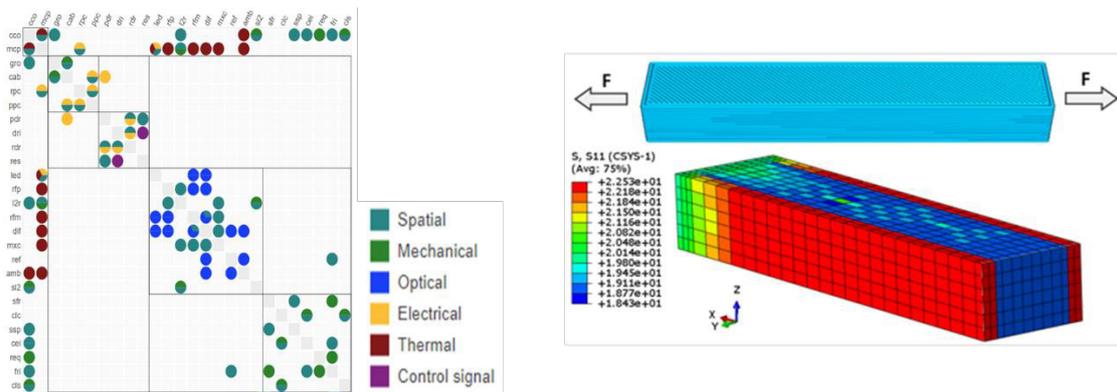
components). These benefits are likely to be significant: just 1% of the additive manufacturing market is predicted to be worth €200 million in 2020.³

The benefits from the cross functional cooperation between different organisations in Hyb-Man is already clear in the first year of the project. Product specifications from end users were translated to technology requirements and first demonstrators are produced to investigate hybrid manufacturing challenges.



Examples of hybrid manufactured electronic structures: in-plane, embedded and 3D structures
 Photo credit: Bosch, Philips Lighting and Neotech

An important aspect of the project is to increase product and process understanding by modelling and experimental validation. A Design Structure Matrix approach is used to visualise and optimise the relations between product properties, components and functionalities. For a more detailed understanding of process influences on product properties, a method has been developed to create simulations models automatically from the code used to drive the FDM (Fused Deposition Modeling) printer. The created models have demonstrated that in a FDM process, the orientation of the filaments have a significant effect on the local stiffness.



Design structure matrix and stress models - Photo credit: TU Eindhoven and Reden

³ <http://www.wohlersassociates.com/2015report.htm>



About the PENTA programme (managed by the AENEAS Industrial Association)

PENTA is a EUREKA cluster whose purpose is to catalyse research, development and innovation in areas of micro and nanoelectronics enabled systems and applications - where there is shared national and industrial interest. Based on three key application areas, Transport & Smart Mobility, Health & Well-Being and Digital Industry for the first 3 calls, PENTA programme contributes to the development of electronic solutions with the opportunity for rapid competitive exploitation and a strong impact on European societal challenges. The PENTA project team is supporting SMEs, large corporations, research organisations and universities by facilitating access to funding, fostering collaborative work and creating consortia.

PENTA is managed by AENEAS, the European industry association

About PENTA: <http://www.PENTA-eureka.eu>

About AENEAS: <https://aeneas-office.org>

About Hyb-Man

Hyb-Man is a RD&I project consortium involving 11 partners from 2 countries. The project partners are: Philips Lighting B.V (project leader), Eindhoven University of Technology, Fraunhofer-Gesellschaft zur Förderung der angewandten Forschung e.V, Henkel AG & Co, KGaA, Neotech AMT GmbH, Reden BV, Robert Bosch GmbH, Technolution BV, TNO - Nederlandse Organisatie voor Toegepast Natuurwetenschap, VSL, XENON Automatisierungstechnik GmbH. National funding support is provided by Germany and the Netherlands.

About Hyb-Man: <http://hybman.eu/>





Hyb-Man

Ambition	Hyb-Man Develop hybrid 3D manufacturing methods to enable flexible first time right production of smart systems		
Objectives	1. Essential technologies	2. First time right production	3. Demonstration in innovative products
Activities	<ul style="list-style-type: none"> • AM/3D printing • 3D electronics processing • 3D assembly & interconnect 	<ul style="list-style-type: none"> • Process integration • Metrology and control platform • Knowledge and design rules 	<ul style="list-style-type: none"> • Product specifications and process requirements • Demonstrator realization and evaluation

Hyb-Man develops hybrid digital manufacturing technologies to produce three-dimensional electronic functions integrated in the structural parts. Hybrid digital manufacturing encompasses the combination of additive manufacturing (3D printing) with assembly and 3D integration of electronic parts, and in-line quality monitoring into one integral production chain. Major opportunities are in flexible and cost-effective production of smart systems, enabling customised electronics for new lighting and automotive products.

Background, objectives of the project and challenges

To achieve the ambitions of the Hyb-Man project, three objectives have been formulated which address the major challenges.

The first objective is to develop the technologies needed for hybrid 3D manufacturing. This includes 3D printing of mechanical structures that meet the requirements for use in end products, printing of electrical structures in horizontal and vertical directions, and placement and electrical connection of standard components such as LEDs and sensors. Special emphasis is on the mutual compatibility of the technologies, and the inclusion of methods to monitor the progress and quality during manufacturing.

The second objective is to enable first-time-right production of systems with integrated mechanical and electrical functionality. First-time-right refers to both product designs and controlled processes. This requires deep understanding of the relation between the product properties and the processes, documented in design guidelines. This understanding is created by a combination of numerical modelling and process investigations. Process control is achieved by the integration and combination of various technologies in the proper way, including methods for in-line inspection and control.





The third objective is to demonstrate the hybrid 3D manufacturing approach in two innovative product cases: LED lighting and automotive acceleration sensors. The specifications of these products determine the technology requirements. Dedicated product designs are made, which fit with the selected technologies. Products are manufactured and evaluated against the requirements. This includes environmental and stress testing, to mimic the long-time use in actual products.

Technological achievements

Hybrid manufacturing technologies, materials and processes

Technologies to print electronics in 3D developed in the project, resulted in new and improved processes and materials. 3D printing structural materials based on extrusion (FFF) and photopolymerisation (SLA), were combined with pick and place (P&P) of standard components, and direct write techniques of curable conductive inks and pastes. Better process understanding was generated to allow printing of fully integrated three-dimensional systems, and to improve process stability and reproducibility.

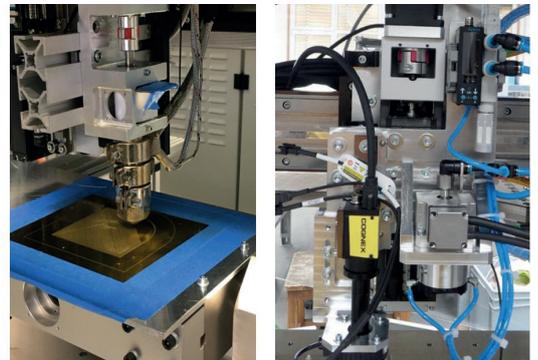
Metrology and in-line control technologies

In-line inspection and control methods were developed, including contactless resistance measurement based on Eddy-current sensing, and a vision-based pick and place system for component embedding.

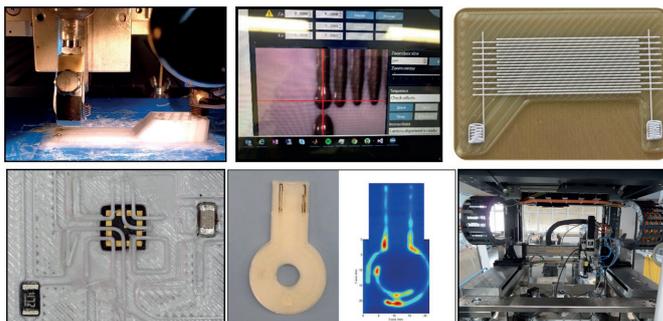
Manufacturing systems combining 3D printing, printed electronics and pick & place

The partners successfully implemented these new technologies into two prototype manufacturing systems, based on FFF and SLA technology combined with P&P. These systems can produce functional electronic products that are completely hybrid manufactured. Monitoring and control have been implemented for integrated temperature control, level sensing and camera inspection.

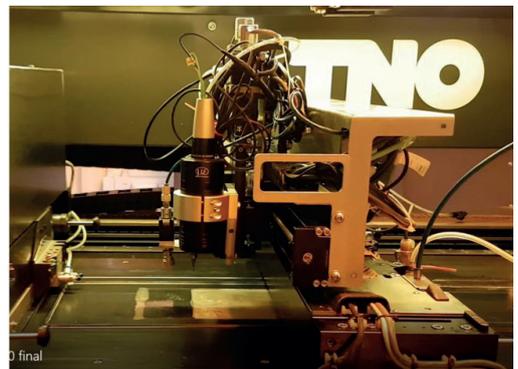
Manufacturing technologies developed during Hyb-Man (Neotech, TNO, Xenon)



FFF based machine (left) and P&P Unit (right)



Technologies developed in the Hyb-Man project (Fraunhofer IFAM, TNO, Bosch, Neotech, VSL, Xenon, Signify)

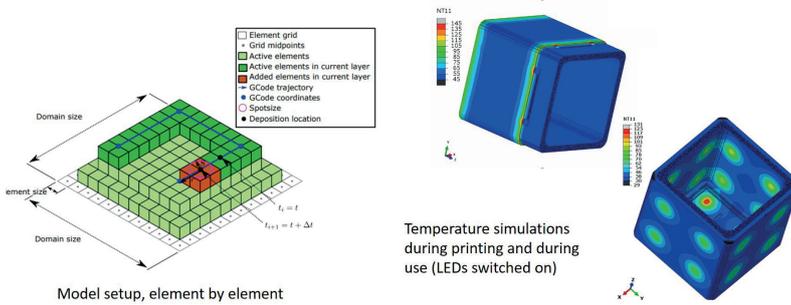


SLA based machine



Modeling and design rules

Simulation tools and strategies have been developed to model mechanical properties, stress, and temperature profiles during printing and product use. The models are dynamic and add elements in time, like in 3D printing, and achieve the right level of accuracy which is validated by experiments. Basic design guidelines are explored by implementing exemplary cases in the Reves design exploration software.

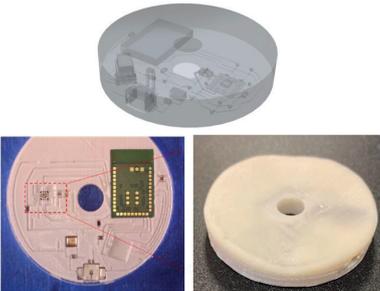


Example of simulation method and results (Reden, TU Eindhoven)

Demonstrators: automotive, LED lighting

LED lighting and automotive demonstrators including embedded tracks, connectors, LEDs, sensors and Bluetooth modules have been made by both process routes. The key electrical and geometrical properties have been reached: conductivity up to 20% of bulk copper was achieved, which is suitable for medium power applications.

automotive acceleration sensor device



LED lighting prototypes



Printed product demonstrators (Bosch, Neotech, TNO, Signify, Fraunhofer IFAM)

The project demonstrators have been used extensively: they are well received and clearly show the properties and opportunities to various stakeholders. Several ideas for further improvement of processes, designs and applications have been generated, to make the next step towards end-user products that benefit from the design freedom enabled by 3D embedded electronics.

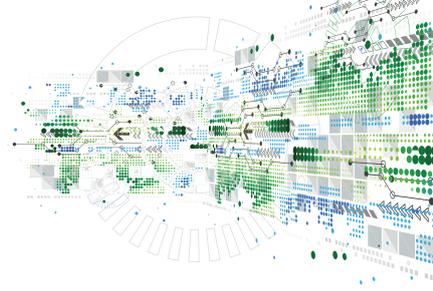
Market Potential

Additive manufacturing and 3D printed electronics markets are forecasted to grow 13-26% per year up to 2028. The 3D printing electronics market is still small and will grow as technology matures, cost is reduced, and technical specifications are met.

Up to now significant interest has been raised for the Hyb-Man demonstrators, materials, process chains, process control and modelling methods. The innovation achieved reinforces the competitive position of all partners in 3D printed electronics. Neotech has received first requests for R&D production systems and Technolution has started deploying parts of the control platform in customer projects.

The Hyb-Man market impact is expected to reach 10-100 M€ per year, based on:

- end products for automotive (Bosch), LED lighting (Signify, extension of 3D printed LED lightings), as well as other applications
- new materials (Henkel, Fraunhofer IFAM), processes and equipment (Neotech, Xenon, TNO)
- metrology (VSL) and control platforms (Technolution) to improve process control
- modelling tools and support (Reden, TU Eindhoven)



KEY APPLICATION AREAS



Digital industry



Digital Life

ESSENTIAL CAPABILITIES



Systems and Components :
Architecture, Design & Integration



ECS Process Technology, Equipment
Materials & Manufacturing

PARTNERS

Fraunhofer-Gesellschaft zur Förderung der
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Neotech AMT GmbH

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Reden BV

Technolution BV

TNO - Nederlandse Organisatie voor Toegepast
Natuurwetenschappelijk Onderzoek

VSL

COUNTRIES INVOLVED



Germany



The Netherlands

PROJECT LEADER

Rob van Asselt
Signify BV

www.hybman.eu

KEY PROJECT DATES

1 April 2017 - 31 March 2020

Societal & Economic Impact

The Hyb-Man project enables the capability to bring electronics manufacturing back to Europe, by mastering a complex set of technologies. We brought together material, process, modelling, and design expertise from different partners to develop the combined technologies to the next level. Together the partners have created an eco-system which covers the complete value chain of materials, equipment, product manufacturers/OEMs and end users, which is key to realise commercial manufacturing and to drive market adaptation of 3D embedded electronics. This eco-system provides Europe with a world-leading position which will be difficult to replicate. Economic growth in Europe is further driven by the fact that the manufacturing processes are first-time-right and highly digitised, enabling cost-effective local production of high-tech electronic products in small series.

During the project an end to end approach towards first time-right production has been developed, from material to process to simulation to product. The Hyb-Man partners have demonstrated technical leadership in their field of expertise, which helps to attract talented scientists, designers, developers, and partners, thereby driving further economic growth and impact. In the coming years 7-10 new job positions per year are anticipated in the areas of material and process development, manufacturing, product design, process control, simulation tools and software. This number will increase when applications expand to other areas.

Hyb-Man also creates significant environmental benefits, because material usage is reduced, less transportation is needed due to local production, products can be recycled, and materials reused at end of life. Material usage is reduced by first-time-right production (no need for multiple print runs and less process failures), product designs optimised to achieve the functionality with minimum amount of material, and products made to order (no obsolescence or waste of products on stock).

Consumers will benefit from these developments by getting access to new smart products with additional capabilities, new form factors and a reduced environmental footprint.

Patents/Standardisation/ Publications

The partners actively disseminated the project results at various events, including large conferences such as IDTechEx, LOPEC and Productronica/Semicon. In total 58 events were visited, and 42 oral presentations given. The know how created in the project has resulted in three patent applications.

Products manufactured by the new hybrid manufacturing methods will follow existing standards for e.g. LED lighting and automotive applications.

Future Developments

The great progress and insights generated in Hyb-Man resulted in the aim to evolve into a follow-up project, to move forward in the following areas:

- Use of functional materials and material combinations to further increase integration of electrical, mechanical, and optical functionality.
- Process industrialisation towards scalable volumes, reduced cost and cycle times, and closed loop control.
- Improved models, faster calculations and integration of simulation and design software.
- New applications that benefit from customisation and miniaturisation, using improved 3D electronics design tools and easier conversion to process settings.

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Hyb-Man

MIRS





16014



Infrared-sensing platform will grow detection markets and drive smart applications in medical, lighting and automotive [MIRS]

MIRS (Midget InfraRed-based Sensor systems) is developing a generic technology platform to reduce the cost of infrared (IR) sensing systems through extreme miniaturisation, and to enable the mass-manufacturing of low-cost, high-volume infrared-detector devices. This project will demonstrate this technology platform with the creation of a highly accurate contactless spot thermometer for mobile devices, as well as a demonstrator of a low-resolution infrared focal plane-array to track and count people in a smart building. This will prepare the ground for advanced automotive and other detection applications.

As markets and technical requirements grow, smart systems for people detection, activity-context interpretation, as well as, surveillance and gesture recognition, are becoming increasingly sophisticated. Although wafer-level cameras have become relatively cheap, their application still suffers from inherent problems. Fortunately, far-infrared (FIR) sensors have a high potential to resolve these issues, but technologically they lag behind consumer cameras. However, although bolometer arrays are still on the higher-end of many mass applications, thermopile sensors have the best chance to provide functional enhancements for increased ambient intelligence, smart vehicles and a broad variety of other applications.

Developing core technologies for healthcare and people detection

Project MIRS' main goals are to develop a generic innovative technology platform in order to reduce the cost of infrared (IR) sensing systems, and ultimately enable the low-cost mass manufacturing of emerging, high-volume infrared-detectors. In order to address these challenges and bring technology to a higher system-level, the MIRS project will investigate key enablers: from wafer to application system.

To achieve this, MIRS will focus on the development of a general infrared-sensor MEMS (micro-electro-mechanical system) technology platform to enable two distinct types of infrared sensors: a single-pixel infrared spot thermometer with narrow optical field-of-view (FOV); and an infrared pixel-array detector for people detection, which can ultimately be integrated in a smart building's lighting system. Now, the strength of the project is that both types of sensors are served with the same main MEMS technology platform (70% of the required modules are common to both types of sensors).

The main project element is the thermopile sensor, used to develop and deliver the two types of infrared-sensor applications:

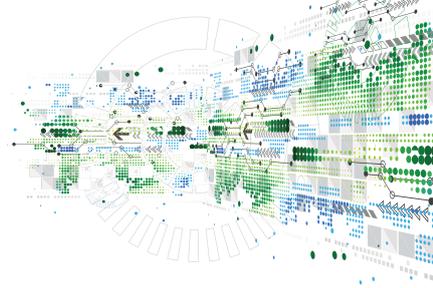
Spot thermometer: using a single-pixel infrared thermopile sensor in combination with current applications, such as the ear-thermometer. An application demonstrator will also be developed to show the workings (on a component level) of a small-footprint, low-cost, single-pixel infrared sensor, the core of the spot thermometer. It should be noted that sensors currently available don't yet use the wafer-level-packaging (WLP) technology, but instead use a large TO39 package. This makes the end product both bulky and pricey. The large packaging is required because CMOS and the infrared sensors are not integrated, and because the pixel size of the infrared sensor is a bit large. These issues impede the integration of this kind of sensor in high-volume applications, like mobile devices.

People-detection sensor: using an infrared thermopile pixel-array and discrete optical lens, working together with such current applications, as heating, ventilation and air-conditioning (HVAC) systems. Similarly, these sensors don't yet use WLP technology, which means bulky TO39 packaging is also deployed. The current limitation of these detectors is their high cost, which impedes their use in high-volume applications, like smart building. An application demonstrator will be developed to show the workings of an infrared pixel array to track and count people in a smart building.

Prepared for challenges

The project consortium has the necessary experience and expertise to deal with key advanced concepts, such as sensor design, CMOS and MEMS integration, and wafer-level packaging with optical integration, as well as, final assembly, packaging and innovative signal processing. It is also prepared to respond creatively to typical challenges – such





KEY APPLICATION AREAS

-  Transport & Smart Mobility
-  Health & Well-Being
-  Digital Life

ESSENTIAL CAPABILITIES

-  Systems and Components Architecture, Design & Integration
-  Safety, Security & Reliability
-  Computing & Storage
-  ECS Process Technology, Equipment, Materials & Manufacturing

PARTNERS

Melexis
aixACCT Systems GmbH
Christian-Albrechts-Universität Kiel
Fraunhofer-Institut für Siliziumtechnologie ISIT
X-FAB MEMS Foundry GmbH
X-FAB MEMS Foundry Itzehoe GmbH

COUNTRIES INVOLVED

-  Belgium
-  Germany

PROJECT LEADER

Carl Van Buggenhout
Melexis

KEY PROJECT DATES

01 May 2017 - 30 April 2020

as miniaturisation of detectors using deep-vacuum eutectic wafer-bonding technology; integrating optics using silicon lenses; and moulding with packaging and assembly.

Exploiting the temperature market

Infrared temperature detectors have very broad application and market potential. That is not surprising considering temperature is a fundamental variable which plays a key role in numerous mechanical, chemical, physical, industrial and medical processes. Two technologies – pyroelectric and thermopile, which MIRS is exploiting – can be found in this market. Thermopile technology can serve almost all market segments, but in monetary value represents a smaller market share (US\$82m in 2014). Although applicable in a lot more market segments, thermopile technology is currently more expensive, thus limiting penetration in massive-volume, low-cost markets. That said, growth in the thermopile market – with an estimated compound annual growth rate (CAGR) of 30% – is expected to improve in 2015-2020, thanks to smart buildings and mobile devices. The sales forecast for contactless spot thermometers for mobile devices is US\$108m by 2020.

Opportunities in lighting and detection

People-detection sensors have targeted applications in smart lighting systems for office or home, and a market forecast of US\$34m by 2020. It is therefore useful to look at the total lighting market for professional luminaires, systems and services, which is expected to grow from €32.5 billion in 2014 to €39.7 billion in 2020, representing a 3% CAGR over the same period. The expected growth in the professional market is primarily driven by the transition to LED and connected lighting, where professional customers are rapidly replacing conventional luminaires with LED ones, and where a significant part of the connected lighting

systems will have infrared-based presence sensors embedded.

The growth of professional connected lighting systems is expected to create new opportunities in high-end, professional services. As a result, the total market size for systems and services is expected to grow from €5 billion in 2014 to €10.6 billion in 2020, measured by sales. This represents a 13% CAGR over the same period, with systems and services representing approximately 20% of the total professional market by 2020. This corresponds to a similar growth in the volume of integrated sensors.

One of the contributing factors to the increased use of LED technologies is the expanding offering of systems with sensors and networks. This trend can be defined as digital light, connected lighting systems or smart systems, which offer multiple applications for professionals and consumers, and which deliver energy-savings, among other benefits. However, these applications currently deploy pyroelectric sensors

A new emerging market is the illumination market that goes beyond providing energy savings, and addresses applications, like optimisation of office space and overall safety. Both markets are highly competitive. With new innovations in infrared-sensor technologies targeted in MIRS, European lighting suppliers can outpace the industry and offer new systems and services to defend and further grow their global leading position.

And there is an interesting spin-off from this project. Thanks to application similarities, detection sensors used to track and count people will in fact prepare the ground for advanced automotive scene detection in assisted or autonomous driving, and other applications involving motion detection.

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Penta (E! 9911), is EUREKA Cluster whose purpose is to catalyse research, development and innovation in areas of micro and nanoelectronics enabled systems and applications.





MIRS

MIRS infrared-sensing technology platform cuts cost of infrared sensors for growing applications in mobile, digital lighting and automotive markets

A project within the EUREKA PENTA programme

Paris, 4 April 2019: MIRS (Midget InfraRed-based Sensor systems), a EUREKA PENTA Cluster project, operated by Industry Association AENEAS, is addressing growing demand for low-cost infrared (IR) sensing systems through development of a technology platform that enables high-volume manufacturing. From thermometers built into smartphones to the detection of people in buildings via sensors integrated in digital lighting systems, IR sensing has vast potential. Sales for infrared detectors are expected to reach approximately 500Mio USD by 2020 with "smart building" and "smart heating, ventilating, and air conditioning (HVAC)" being principle drivers for growth¹.

Furthermore, because the ability to detect heat via IR sensing is so widely applicable, it can be used in many other situations as well. These include medical processes, warning of dangers in the environment, contactless detection of unwanted heat losses or generation in buildings, and detection of pedestrians by self-driving cars. The MIRS project aims to address the many market opportunities by delivering a combination of very small size, high performance and low-cost based on its generic technology platform and extreme miniaturization.

Specifically, MIRS is developing a MEMS (micro-electro-mechanical system) platform that integrates IR sensors and the necessary optics at wafer level (i.e. on the silicon wafers on which chips are made). This platform will provide 70% of the required modules for two key types of sensor: single pixel infrared spot thermometers and infrared pixel-array detectors for people detection.

Moreover, by combining both pyroelectric and thermopile sensing, the MIRS platform will open the way to new business opportunities. Thermopile sensors measure radiated energy and are widely applicable, whereas pyroelectric sensors detect changes in radiation and are principally used for motion detection. Bringing them together in a single platform will enable applications in areas such as low-energy products and movement detection without the need for digital signal processing. Furthermore, while the thermopile market is currently relatively small, it is expected to grow at an estimated compound annual growth rate of 30% or more, if costs and size can be reduced.

The MIRS consortium pursuing these goals forms an innovation partnership that spans the entire value chain. It includes organisations and companies from research (CAU, ISIT) and production (XMF, MFI, AIX) through to the market (MELEXIS). Its members bring expertise in all areas from sensor design and CMOS and MEMS integration through to wafer-level packaging with optical integration, as well as know-how in final assembly, packaging, testing and innovative signal processing.

¹ Source : Yole Development estimates, November 2015





About the PENTA programme (managed by the AENEAS Industrial Association)

PENTA is a EUREKA cluster whose purpose is to catalyse research, development and innovation in areas of micro and nanoelectronics enabled systems and applications - where there is shared national and industrial interest. Based on the Electronic Components & Systems (ECS) Strategic Research Agenda (SRA) key areas and essential capabilities, PENTA programme contributes to the development of electronic solutions with the opportunity for rapid competitive exploitation and a strong impact on European societal challenges. The PENTA project team is supporting SMEs, large corporations, research organisations and universities by facilitating access to funding, fostering collaborative work and creating consortia.

PENTA is managed by AENEAS.

More on PENTA: <http://www.penta-eureka.eu>

More on AENEAS: <https://aeneas-office.org>

About MIRS

MIRS is a RD&I project consortium involving 6 partners from 2 countries. The project partners are: Melexis (Project leader), aixACCT Systems GmbH (AIX), Christian-Albrechts-Universität Kiel (CAU), Fraunhofer-Institut für Siliziumtechnologie ISIT, X-FAB MEMS Foundry GmbH (XMF), X-FAB MEMS Foundry Itzehoe GmbH (MFI). National funding support is provided by Belgium and Germany.

More on MIRS: <http://www.penta-eureka.eu/downloads/ProjectProfiles/penta-project-profile-16014-mirs.pdf>



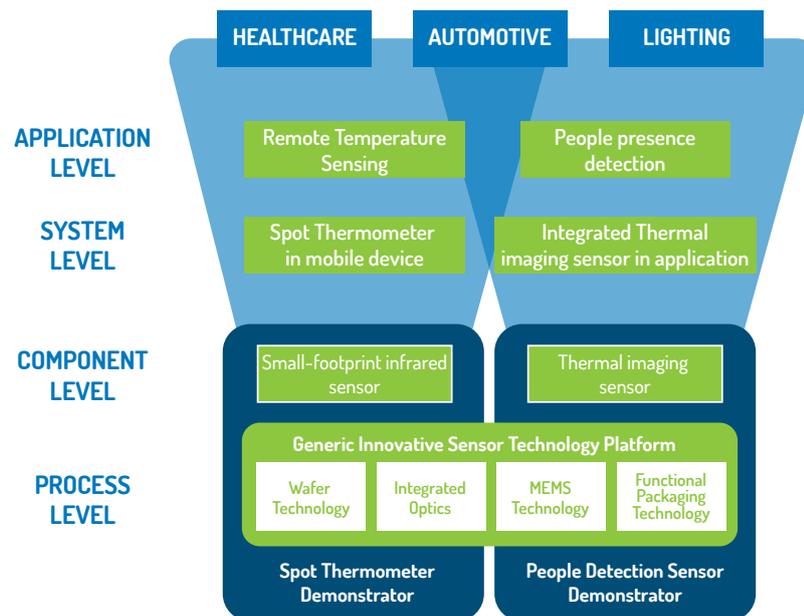


16014



An Infrared-sensing platform that will grow detection markets and drive smart applications in medical, lighting and automotive.

[MIRS]



Scope of the MIRS project – including the three targeted application domains of Healthcare, Automotive and Lighting

MIRS (Midget InfraRed-based Sensor systems) has developed a generic technology platform to reduce the cost of infrared (IR) sensing systems through extreme miniaturisation, and to enable the mass-manufacturing of low-cost, high-volume infrared-detector devices. The project has demonstrated this technology platform with the creation of a highly accurate contactless spot thermometer for mobile devices and wearables, as well as a demonstrator of a low-resolution infrared focal plane-array to track and count people in a smart building. This will prepare the ground for advanced automotive and other detection applications.

Background, objectives of the project and faced challenges

Infrared (IR) sensors for temperature measurements that are responsive in the wavelength domain from 3µm to 15µm suffer today from expensive optical elements and packaging solutions.

There are two main reasons why infrared detectors are not yet integrated as temperature measurement systems in high-volume applications:

- Optical integration costs. Suitable long-wave infrared transparent materials like ZnSe, CaF or Ge are expensive and not always robust for the target application.
- Packaging cost and size. The state-of-the-art package of this kind of sensors is bulky and doesn't allow an easy integration in many products.





The primary goal of the MIRS project was to develop a generic innovative technology platform in order to reduce the cost of the IR sensing systems by extreme miniaturization, with the final objective to enable low-cost mass manufacturing for emerging high volume infrared detector markets.

The challenges lay in the process integration of the key technology building blocks that were envisioned in this project, such as: the deep vacuum wafer-level bonding of cap wafers to monolithically integrated MEMS-CMOS silicon wafers; the integration of a novel optical silicon lens technology with cap wafers; the integration of pyroelectric elements on MEMS-CMOS silicon wafers; and the compatibility of Through-Silicon Vias (TSVs) into permanently cap-bonded monolithically integrated MEMS-CMOS silicon wafers.

Technological achievements

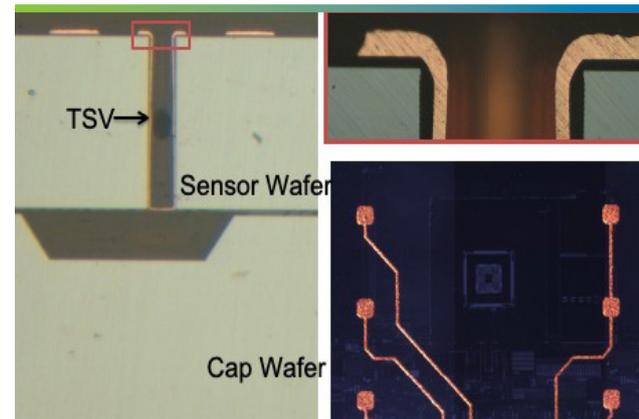
Within the MIRS project, 4 key technological innovations have been achieved.

The first key innovation relates to the technology required to manufacture infrared sensors. Due to the nature of the infrared sensor as a micro-electro-mechanical system (MEMS) sensor, it must be embedded in a hermetic housing, with a low pressure inside that housing, in order to maximize the sensitivity of the sensor. To achieve the lowest-cost manufacturing technology, that hermetic housing with low pressure is created on the wafer-level, whereby a silicon cap wafer is hermetically bonded to a silicon sensor-CMOS wafer. MIRS-partner XFAB has demonstrated a major improvement of the Technology Readiness Level (TRL) of their hermetic wafer-level bonding technology which enabled to create demonstrators on the product-level by MIRS-partner Melexis.



Wafer-level hermetic sealing of more than 5000 infrared sensor chips under deep vacuum
Copyright XFAB

The second key innovation concerns the integration of Through-Silicon Vias (TSVs) inside permanently bonded infrared sensor wafers, with the goal to create infrared sensor systems with a reduced footprint by enabling chip-scale packages. MIRS-partner X-FAB MEMS Foundry GmbH (XMF) has advanced their TRL to demonstrate a wafer-level feasibility of integrated TSVs inside infrared sensor wafers with permanently bonded cap wafers.



Wafer-level integration of Through-Silicon Vias (TSVs) inside permanently bonded infrared sensor wafers
Copyright XFAB

For the third key technology innovation, MIRS-partner Fraunhofer-Institute for Silicon Technology (ISIT) has developed a patented approach to integrate high-end silicon planoconvex lenses inside cap wafers by using silicon balls with a pre-sorted Radius-of-Curvature (ROC). A video that shows the fabrication and demonstration is available on public platforms: <https://www.youtube.com/watch?v=IXm9ALz89Qc>



Demonstrator of a cap wafer with more than 5000 silicon lenses on a wafer

The inset shows singulated caps with planarized silicon ball lenses resulting in a planoconvex silicon lens inside a cap for integration with an IR sensor.
Copyright Fraunhofer ISIT





Within the fourth key technology innovation pillar of the MIRS project, MIRS-partners Fraunhofer ISIT and University of Kiel (CAU) have integrated AlScN pyroelectric elements on a CMOS-MEMS wafer. MIRS-partner aixACCT has developed a laser-based measurement tool in order to characterize those AlScN layers, which was successfully used to assess the performance of the AlScN pyroelectric elements that were integrated on the CMOS-MEMS wafer in the project.

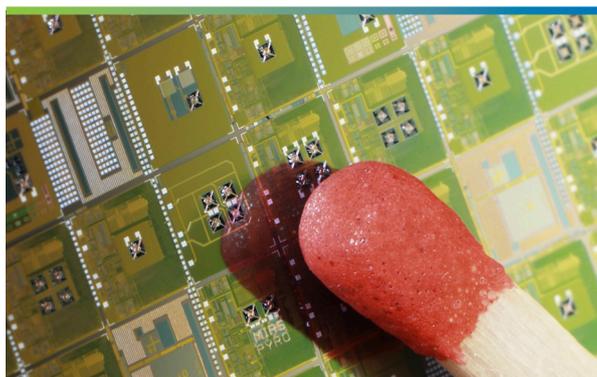


Illustration of the integrated AlScN pyroelectric elements on a CMOS-MEMS wafer
Copyright Fraunhofer ISIT

Market Potential

With the core technology advancements that had been reached in the project, the complete MIRS consortium built two important demonstrators: a contactless single-pixel IR temperature sensor as well as a multi-pixel IR detector. The high-sensitivity single-pixel IR temperature sensor can be combined with the innovative lens approach to result in a sensor with a narrow optical Field of View (FOV) which enables contactless fever thermometer applications without the need to approach the sensor close to the target person. This enables the device-maker Melexis to approach multiple markets in the mobile health domain, like fever thermometers as well as mobile devices for continuous health monitoring, such as smart watches, sports watches and medical wearable devices.

The multi-pixel IR array detector has large potential in fever screening access control applications – which is a booming COVID19-driven market, but also serves emerging markets like people detection applications for smart buildings. Lower-cost systems could drive up the volumes from high to mid-end systems in Heating, Ventilation and Air-Conditioning (HVAC) applications, in which Melexis has further enhanced its position. Also, other small appliances and industrial applications, such as cook top safety monitoring, electrical cabinets safety monitoring or production parameters monitoring (e.g. for 3D-printer materials) are expected to see a further growth, albeit not as fast as for the consumer, medical and smart building markets.

Last but not least, the automotive trends of electrification, personalization and autonomous driving requires IR temperature sensors for better personalized thermal comfort inside the car, for driver/passenger monitoring to detect (e.g. occupancy, potentially nausea, drowsiness and others). Device-maker Melexis has an excellent position as one of the key suppliers to the automotive market with an average of 11 Melexis chips in every new car.

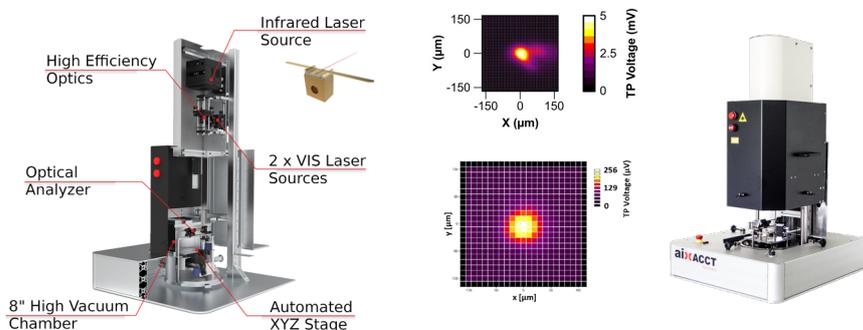


Illustration of the measurement tool developed by aixACCT for the characterization of pyroelectric materials

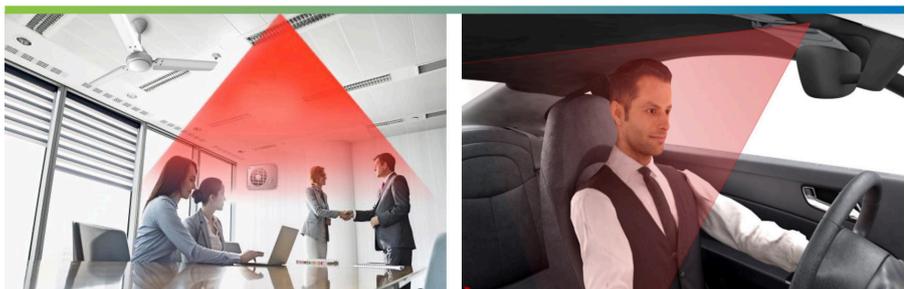
The measurement tool developed by aixACCT consists of an infrared laser source, coupled with fiber optics to create an illumination spot on a test wafer, located in an 8" vacuum chamber on a chuck, coupled to an automated XYZ stage.

Copyright: aixACCT

Application domains of IR temperature sensors

The left picture shows a potential people detection sensor in smart buildings, in which smart building algorithms can be applied to count the amount of people in meeting rooms, thereby enabling to better regulate the Heating, Ventilation and Air Conditioning (HVAC) system, as well as detecting unoccupied or over-dimensioned spaces in smart offices – all contributing to reduce our common environmental footprint as well as at the same time provide comfort for people.

The right picture illustrates an in-cabin automotive application in which the multi-pixel IR array detector can support the driver-assistance system for a more accurate feedback signal of the driver temperature in the regulating loop of the HVAC system.



Copyright Melexis



KEY APPLICATION AREAS

-  Transport & Smart Mobility
-  Health & Well-Being
-  Digital Life

ESSENTIAL CAPABILITIES

-  Systems and Components Architecture, Design & Integration
-  Safety, Security & Reliability
-  Computing & Storage
-  ECS Process Technology, Equipment, Materials & Manufacturing

PARTNERS

- Melexis NV
- aixACCT Systems GmbH
- Fraunhofer-Gesellschaft zur Förderung der angewandten Forschung e.V.
- University of Kiel
- X-FAB MEMS Foundry GmbH
- X-FAB MEMS Foundry Itzehoe GmbH

COUNTRIES INVOLVED

-  Belgium
-  Germany

PROJECT LEADER

Carl Van Buggenhout
Melexis

KEY PROJECT DATES

01 May 2017 - 31 July 2020

Societal & Economic Impact

The societal impact of IR temperature sensors can be split into two domains. The first domain comprises contactless body-core thermometers with medical accuracy for healthcare applications (like fever thermometers). The current COVID19 pandemic has massively boosted the need for contactless thermometers in medical wearable devices, which requires these IR temperature sensors to be small, lightweight and low-cost – yet very accurate – in order to determine a person’s body-core temperature. Within the MIRS project, the team has focussed on miniaturizing IR temperature sensors with these objectives, and they have successfully created a demonstrator of such an IR temperature sensor.

The second domain of interest is attributed to a growing market of smart systems for people detection, activity context interpretation, surveillance and gesture recognition – which all are becoming increasingly sophisticated. Although standard cameras have become relatively cheap, their application still suffers from two major problems. Above all, privacy concerns of people feeling observed need to be seen as a social requirement that technologists have to fulfil. Secondly, the need for external light with CMOS/CCD imagers is often an unresolvable problem. IR detectors don’t require external light because all objects emit IR radiation, which can be detected with these IR detectors. This kind of IR detectors can only detect but not recognize people because they only measure differences in temperature. As such, IR detectors have a high potential to resolve these issues. The MIRS demonstrator of an IR detector also prepares the ground for advanced automotive scene detection in assisted or autonomous driving.

Patents/Standardisation/ Publications

Throughout the execution of the project, the university of Kiel (CAU) has discovered ferroelectricity in AlScN – which to the best knowledge of the MIRS team hadn’t been reported upfront – and which could enable novel microelectronic applications. The Fraunhofer-Institute for Silicon Technology in Itzehoe (ISIT) has been granted a patent on their novel method of integrating silicon optical lenses in cap wafers, which can be wafer-bonded to IR sensor-CMOS wafers. That achievement enables them to further develop their technology, which has the potential to drastically reduce the cost of infrared silicon optics. In the MIRS project patent applications have been generated by XMF which are now being assessed by the patent offices. Besides, also many technical papers have been published and presentations have been given on the key technology building blocks which were scoped in the project.

Future Developments

The MIRS project delivered very exciting results, which will be exploited by further advancing these innovative technologies, towards achieving a Technology Readiness Level (TRL) that enables mass production of new improved products. The Christian-Albrechts-University of Kiel (CAU) has decided to continue their explorative work on ferroelectricity of AlScN with the aim to enable novel microelectronics applications, and the measurement tool of aixACCT will be further extended to other applications.



Demonstrator of an IR People Detection Sensor for smart building applications

On the left: image of a scene as captured by a standard camera; on the right: visualized image of the same scene as detected by the MIRS IR People Detection Sensor. The two people in the scene are detected by the MIRS IR People Detection Sensor as two individual hotspots in the room, but they can’t be identified, which resolves the privacy concern of standard cameras.

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MIRS



Serene-IoT





PROJECT PROFILE

16004



Remote care and diagnostic tools offer patients better, longer and autonomous ‘active life’ at a much lower price

[SERENE-IoT: **Secured & EnerGy EfficieNt hEalth-care solutions using IoT technologies**]

With a growing ageing population (in which many could experience multiple chronic diseases), governments and health authorities in the European Union are rightly concerned with rising health-care costs. Remote health-care offers a way of alleviating this problem and the SERENE-IoT project supports this approach through quality remote-care and diagnostic tools based on advanced, smart health-care, and the internet of things.

Medical progress in last decades have significantly fallen mortality rates and have staidly improved our global health and this transformation is impacting seriously our health and social care systems. Some 30% of the population in the European Union (EU) will be over 65 by 2030; two out of three people of retirement age will have at least two chronic illnesses. Currently, 70% of health-care are on chronic illnesses and 41% on hospital care; and health-care costs in the EU represent 9% of GDP and are expected to reach 10.5% in 2060. Fortunately, the convergence of the health-care and the high-tech mass-market ecosystems is coming to a point where things and people are increasingly connected, as with the internet of things (IoT), and where health-care is partly divided between hospital and home. Impacting our health models, the Internet of Medical Things (IoMT) is born. Unsurprisingly, the economic and social impact due to chronic diseases in Europe will make this move mandatory in order to keep medical and social services sustainable and improve patients’ quality of life.

Remote health-care and diagnosis through the internet of things

SERENE_IoT will focus on benefiting the patient with an improved quality of life and better access to health-care in general, as well as reducing health-care costs. It will achieve this by addressing the specific needs of patients being handled remotely by professional caregivers through the development, by European companies and research institutions, of smart e-health IoT devices and an advanced architectures.

The core values of this project are:

- High quality of health-care services;
- High level of trust (security, safety, privacy, robustness);
- Efficient execution of required tasks;
- Interoperable and compatible information technology (IT) systems;
- Reduced costs compared to current traditional care.

Major project outcomes and deliverables will be three Clinical Prototypes that will validate benefits derived

from remote-care scenarios. In line with the so-called medical innovation cycle (up to ‘clinical prototype’ level), SERENE-IoT will develop three medical devices to meet the following medical challenges:

1. Providing homebased health-care services remotely: by developing the first low-power medical IoT module validated with two class IIx medical devices;
2. Early detection of Methicillin-resistant bacteria: by developing the first low-power mobile detector for MRSA (antibiotic-resistant bacteria);
3. Fall prevention: by developing a fully wireless insole for fall detection and risk monitoring.

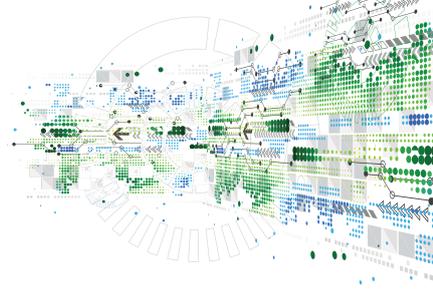
These medical devices will be validated in real clinical environments under mono-centric and multi-centric clinical conditions. Importantly, the three demonstrators will be used to provide the necessary validation of advanced concepts needed by European industry for the development and manufacture of products and services in the area of remote medical-care.

Importantly, SERENE-IoT will contribute to the evaluation of a secure, end-to-end, IoT system platform in ‘real-life’ scenarios (including the use of the proposed health-care data structure), while demonstrating the resulting benefits. Certification and industrialisation phases will follow the SERENE-IoT project.

The right mix means a balanced and holistic approach

The SERENE-IoT consortium – from France, Germany and Spain – provides a balanced and holistic approach to this project, thanks to the mix of project partners (large firms, SMEs and academia) which covers the health IoT ecosystem – from integrated device manufacturer (IDM) and original equipment manufacturer (OEM), to end-user service-provider. And the involvement of industrial supply-chain and health-care providers ensures the right devices and services are developed. In addition, the consortium, specifically the academics, will be involved in promoting standards, sharing technical material and raising awareness of the achieved results through international journals,





KEY APPLICATION AREAS

-  Health & Well-Being
-  Energy
-  Digital Industry
-  Digital Life

ESSENTIAL CAPABILITIES

-  Systems and Components Architecture, Design & Integration
-  Connectivity & Interoperability
-  Safety, Security & Reliability
-  Computing & Storage
-  ECS Process Technology, Equipment, Materials & Manufacturing

PARTNERS

CHU Grenoble / CEA LETI/LIST / Flavia IT / Fraunhofer / Fresenius Kabi / Grenoble INP - LCIS / LMU Klinik / Maatel / Medtronic / Idemia / Orange Labs / Seidor / SensingTex / SGS-TÜV Saar / Spring Techno / STMicroelectronics / UAB / XFAB

COUNTRIES INVOLVED

-  France
-  Germany
-  Spain

PROJECT LEADER

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KEY PROJECT DATES

01 June 2017 - 30 November 2020

publications, as well as conferences and exhibitions.

Thanks to SERENE-IoT, project partners – who are also stakeholders from across the healthcare value-chain – will validate new advanced IoT-based technical concepts, and subsequently create new market opportunities in the European health-care industry, paving the way for the deployment of such connected devices in the EU.

The health-care industry is expected to evolve towards a more competitive and efficient marketplace as a result of new flourishing business models based on remote health-care and diagnostics. Now, while the process to reach this goal will further evolve, it could also be slow, nonlinear and include parallel initiatives. That is why supply-chain members need to contribute to a common, acceptable solution, and why such a consortium – which covers the complete supply-chain and works in a collaborative way – was formed initially.

Benefiting health and health-care stakeholders

Techniques developed in this project could synergistically improve energy efficiency, as well as, safety and security, of IoT systems. SERENE-IoT will also impact all stakeholders in the very complex health and health-care ecosystem. The health-care market has a particularly high number of stakeholders with complex 'interactions', which vary according to country, culture and local laws. IoT systems will collect, process and make available several types of information: not only medical data related to a patient (caregiver's concern), but also device-related information, such as device status and location (manufacturer's concern) and medical consumables (purchasing department's concern) and the like. Importantly, the introduction of IoT technologies in the medical field could also open up new application areas. However, exploiting this data properly will require reorganising the market value-chain in order to provide new and innovative services.

Healthy IoT and health-care markets

Several IoT surveys forecast up to 50 billion connected objects in 2020, with an exchange of more than 50 trillion gigabits of data (according to IDC). This is what is termed the third wave of the internet, which

is expected to have a tremendous impact at different levels. At the technological/scientific level, drivers will be new scientific developments (like 'big data') through multiple, connected smart objects with safety, privacy, security and power constraints. At the societal level, our daily lives will be improved by such innovations as smart health, smart cars and smart energy. And on the industrial/economic level, there will be a continual creation of new business opportunities for established companies, SMEs and start-ups in multiple innovation domains.

According to the 'Yole Development' report issued in September 2017, analysts estimate that there are today more than 45 million IoMT devices and more than 235 million in 2020. Based on this report, two major medical devices can benefit from the connectivity: the existing medical devices moving to connected medical devices and the new connected medical devices created on purpose. This market is distributed in the 4 following segments: implanted patients, professional monitoring, self-quantified patients, lack of autonomy patient assistance.

The global Connected medical devices market represents \$9.6B revenues in 2017 and will grow to reach more than \$23.7B in 2022. Thanks to IoT technology the patient become a genuine actor of his own care and of his social environment, and thus shaking up our current social representation of a dependent person.

The clinical prototypes produced by SERENE-IoT illustrate perfectly the picture depicted in Yole report. Adding connectivity on already existing medical devices and developing medical devices on purpose thanks to connectivity, the clinical prototypes address the three segments having the best perspectives in the IoMT market:

- Professional monitoring segment with CAGR: 21.4%
- Self-quantified segment: 18.7%
- Assistance segment: 15.5%

Finally, a June 2015 report from McKinsey Global Institute, estimates that 89% of the potential annual economic-impact of health-care IoT applications in 2025 will be in advanced economies, versus 11% in developing ones; and Europe will be one of the first to deploy these new technologies.

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Penta (E! 9911), is EUREKA Cluster whose purpose is to catalyse research, development and innovation in areas of micro and nanoelectronics enabled systems and applications.





Serene-IoT

SERENE-IoT: creating secured connected healthcare devices for higher patient quality of life at lower cost for health services

A project within the EUREKA PENTA programme

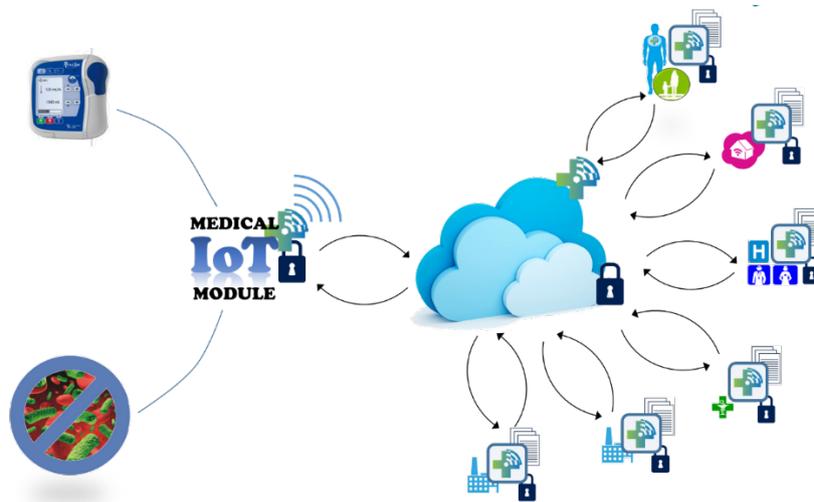
Paris, XX November 2018 – SERENE IoT, a project within the EUREKA PENTA Cluster managed by the Industry Association AENEAS, is developing clinical prototype solutions for connected healthcare services and diagnosis at home, based on Internet of Things (IoT) devices. Aging populations, a rise in chronic disease and a shortage of healthcare professionals in developed and developing countries are putting severe strains on healthcare systems. SERENE-IoT is focusing on solutions that will have positive impacts on quality of life and cost reduction in three domains. The first is remote healthcare ('hospital at home') based on an internet-connected infusion / nutrition pump. The second is rapid, early detection of antibiotic resistant infection (Methicillin-resistant bacteria) and the third is fall prevention via a device that monitors the wearer's gait.

In the European Union alone, estimates indicate that 30% of the population will be over 65 years-old by 2030, and two out of three people in retirement age will have at least two chronic diseases. Currently, 70% of health care costs are spent on chronic diseases, and 41% are dedicated to hospital care. By supporting the shift towards 'hospital at home' care, early detection and prevention, SERENE-IoT seeks to reduce healthcare expenses in its three domains by 50%, as well as promoting lifelong health and high-quality long-term support for people with chronic and / or advanced disease.

Security, safety and privacy are central to the SERENE-IoT project, ensuring that the devices will fully protect sensitive medical data within an end-to-end IoT system platform. In addition, the project will tackle other technical challenges to create devices that are easy to use, interoperable, small, and low power so they can operate for extended periods without recharging. Overall, the project aims to deliver societal and economic benefits, while opening market opportunities for European companies – globally, the healthcare IoT market is expected to grow from USD 32 billion in 2015 to USD 163 billion by 2020¹.

The SERENE-IoT consortium brings together key players from across the value chain, which allows for a shared understanding of needs, development of complementary technologies and a common vision for connected healthcare and the 'hospital at home' concept. The consortium comprises two care givers, seven large enterprises, five SMEs and five university labs and research institutes from three countries. These include specialists in telecommunications and safety-security systems providers, as well as healthcare solutions manufacturers.





Remote Healthcare flowsheet diagram

About the PENTA programme (managed by the AENEAS Industrial Association)

PENTA is a EUREKA cluster whose purpose is to catalyse research, development and innovation in areas of micro and nanoelectronics enabled systems and applications - where there is shared national and industrial interest. Based on the Electronic Components & Systems (ECS) Strategic Research Agenda (SRA) key areas and essential capabilities, PENTA programme contributes to the development of electronic solutions with the opportunity for rapid competitive exploitation and a strong impact on European societal challenges. The PENTA project team is supporting SMEs, large corporations, research organisations and universities by facilitating access to funding, fostering collaborative work and creating consortia.

PENTA is managed by AENEAS, the European industry association

About PENTA: <http://www.penta-eureka.eu>

About AENEAS: <https://aeneas-office.org>

About SERENE-IoT

SERENE-IoT is a RD&I project consortium involving 19 partners in 3 countries. The project partners are: STMicroelectronics (Project leader), CEA LETI, CHU Grenoble, Flavia IT, Fraunhofer, Fresenius Kabi, Grenoble INP- LCIS, Idemia, LIST, LMU Klinik, Maatel, Medtronic, Orange Labs, Seidor, SensingTex, SGS-TÜV Saar, Spring Techno, UAB, XFAB.

About SERENE-IoT: <http://serene.minalogic.net/>

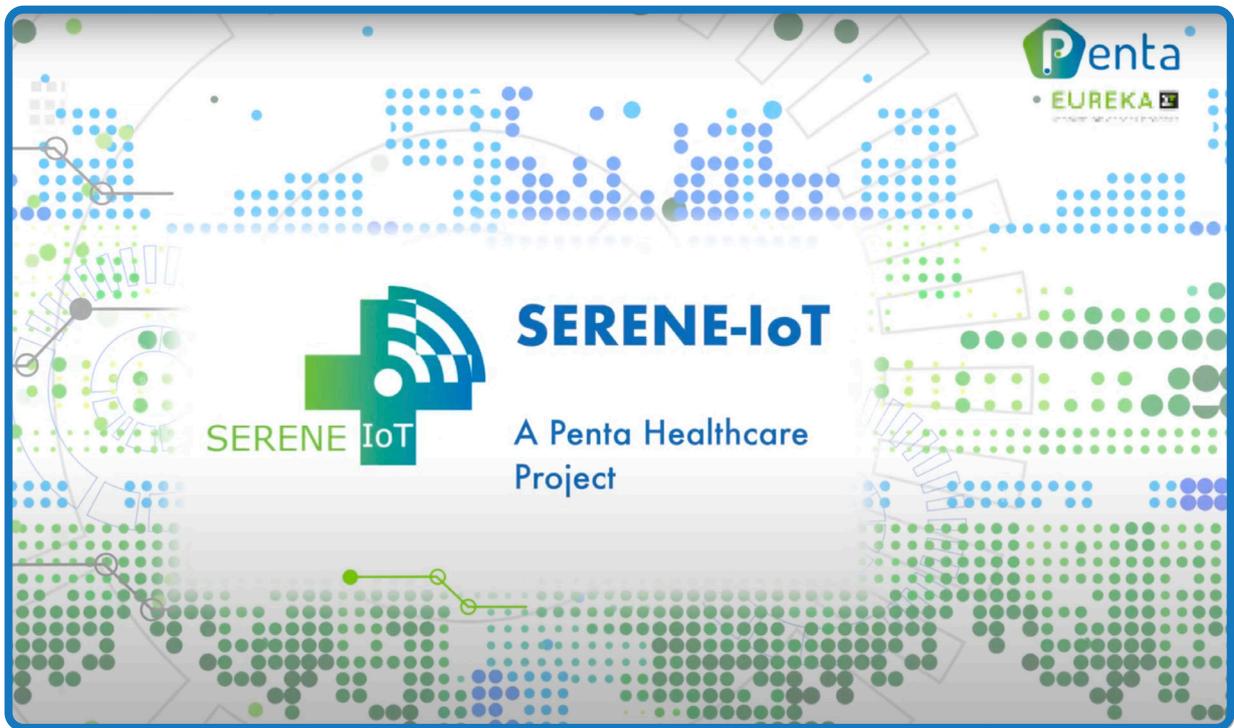




VIDEO



Serene-IoT



▶ Video: <https://youtu.be/c02-twSdywQ>



ESAIROQ





16113



Low-cost sensor technologies for measuring and monitoring air quality will impact health, societal and environmental issues [ESAIRQ]

Driven by a growing demand for sensors and the potential of using semiconductor technologies in this application space, the Environmental Sensors for Air Quality (ESAIRQ) project focuses on developing essential technologies for gas sensing, while researching selective, sensitive and reliable sensors at affordable costs for mass exploitation. ESAIRQ's deliverables, notably its gas, fine-particle and pathogen-sensing technologies, will have a significant health, societal and environmental impact.

Society is paying increasing attention to air quality since air pollution is growing and its negative impact understood, thanks to publications and environmental regulations. Importantly, with more and more highly isolated buildings, indoor air exchange is limited and the monitoring and control of air quality will be crucial. This is especially true since formaldehyde emissions from furniture and new building interiors, as well as volatile organic compounds (VOCs), are becoming a health hazard. The change in buildings and the awareness of health risks underscore the importance of monitoring environmental air quality. All of this, together with new applications, is triggering demand for sensors to measure air quality.

Researching and developing sensor technologies for mass gas-sensing

With the growing demand for sensor technologies and the potential of semiconductor technologies in this application area, ESAIRQ aims at further developing essential technologies for gas sensing with research in selective, sensitive and reliable sensors at affordable costs for mass exploitation. The miniaturised sensor technologies developed in this project will be key enablers for creating sensor networks for air-quality monitoring which can be formed either by embedding sensors in the basic infrastructure, or even in mobile devices. The gas, fine-particle and pathogen-sensing technologies will have a significant impact on measures based on known air-quality and composition.

The realisation of low-cost, affordable sensors that fulfil the requirements of size, sensitivity, selectivity and lifetime will need to deal with technological challenges to:

- Increase the selectivity of sensors, especially to particle matter and polluting organic and inorganic gases when offered as gas mixtures;
- Miniaturise in the functional integration of, for example, emitters and detectors or circuits needed to control absorption and desorption;

- Profit from cost and quality advantages of the semiconductor process-technologies for high-volumes and low-cost compatible processes which will be developed;
- Enable low-power integration of sensors in connected solutions, and establish services.

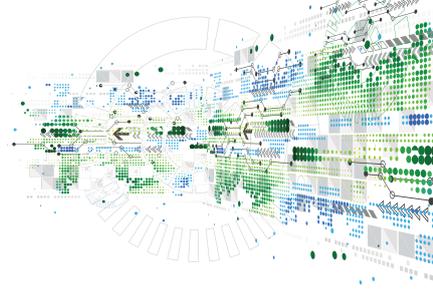
With the planned research, ESAIRQ aims to realise:

- Miniaturisation and functional integration of infrared spectral sensors;
- Functional integration on a chip-level, leading to decrease in power consumption;
- Miniaturisation of fine-particle sensing/fire detection;
- Functional integration of thin membrane layers and sandwich-layer structures, together with innovative gas-sensitive layer systems;
- Sensor arrays and control algorithms leading to selective gas sensors;
- A miniaturised device for airborne pathogen detection.

Societal, economic and environmental impacts

ESAIRQ will develop essential technologies for gas sensing, focusing on research in selective, sensitive and reliable sensors at affordable costs for mass exploitation. These miniaturised sensor platforms developed in this project are key enablers for highly sensitive and selective sensor-systems or sensor-networks for air-quality monitoring.

The mobile gas and fine-particle sensing platforms will have a significant societal impact in reducing mortality rates and health-care costs in polluted environments. In addition, results of the project will strengthen the European landscape in terms of sensor technologies, and manufacturing and application know-how. They will also generate new markets. Importantly, education and the drive for new start-ups will be supported by European-wide collaboration.



KEY APPLICATION AREAS

-  Health & Well-Being
-  Automotive and Transport (future)

ESSENTIAL CAPABILITIES

-  Systems and Components Architecture, Design & Integration
-  Connectivity & Interoperability
-  Safety, Security & Reliability
-  ECS Process Technology, Equipment, Materials & Manufacturing

PARTNERS

INSTITUT MIKROELEKTRONICKYCH APLIKACI S.R.O / Afore Oy / Gasera Ltd. / Pegasor Oy / Vaisala Oyj / VTT Technical Research Centre of Finland Ltd / Aryballe Technologies SA / Asygn SAS / CEA / FARE / mirSense SAS / Soitec / EC-Sense GmbH / eesy-innovation GmbH / Fraunhofer ENAS / Infineon Technologies AG / Infineon Technologies Dresden GmbH / InfraTec GmbH Infrarotsensorik und Messtechnik / University of Regensburg / UST / Umweltsensortechnik GmbH / University of Malta / Technische Universiteit Eindhoven / Stichting IMEC Nederland / Philips Electronics Nederland BV / Philips Consumer Lifestyle B.V. / Qmicro BV / University of Twente / AlphaSIP Aragón

COUNTRIES INVOLVED

-  Czech Republic
-  Finland
-  France
-  Germany
-  Malta
-  Netherlands
-  Spain

PROJECT LEADER

Dr Wolfgang Dettmann
Infineon Technologies AG
www.project-ESAIRQ.com

KEY PROJECT DATES

21 June 2018 to 20 June 2021

Future outlook looks promising

The market for environmental MEMS sensors was reported in 2015 to be worth \$28 million and 35m units, and expected to reach \$155m in 2021, with 256m units at a compound annual growth rate (CAGR) of 39% from 2015-2021.

Wearables are one of the platforms ripe for new sensor integration, and also a basis for new service offerings. The most significant market-analysis data was found for smart watches and glasses. Here, major growth rates were expected in 2015, when shipments were expected to increase from around 100m units, to around 200m in 2019. This high-growth rate indicates a highly attractive and competitive future market.

Demand for air purifiers in Asia is skyrocketing. The forecast for sensor shipments presented at the European MEMS Summit in September 2016 predicts high growth of over 5m units in 2021.

Finally, the hospital-acquired infections (HAI) diagnostics market is projected to grow to \$83m by 2020, with a CAGR of 8.5%, mainly driven by public and government awareness which is pushing technological developments in this sector. The overall food pathogen testing market is expected to grow to \$17.16 billion in 2021, with a CAGR of 4.6%. Even though this market is less demanding than the clinical one, commercialisation of biosensors for the food-safety industry is growing as legislation creates new standards for microbial monitoring. With quicker detection time and reusable features, biosensors will be important to those activities whose revenues can be affected by pathogen contamination.

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ESAIRQ

As air quality becomes a global issue, the ESAIRQ project innovates new chip-based technologies for low-cost sensitive air quality sensors

A project within the EUREKA PENTA programme

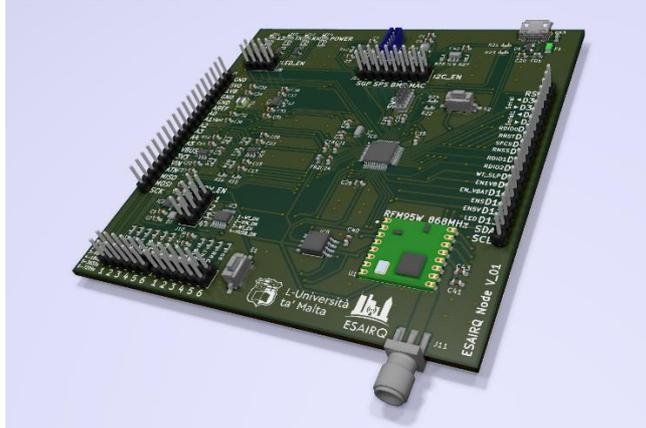
Paris, Thursday 12 September 2019 -With growing global awareness of air quality and its impact on human health, ESAIRQ (Environmental Sensors for Air Quality) is developing essential technologies for gas sensing. ESAIRQ is a project within the EUREKA PENTA Cluster, managed by Industry Association AENEAS, aimed at delivering selective, sensitive and reliable sensors at affordable cost for mass markets. New platforms for gas and fine-particle sensing have the potential for significant societal impact through a reduction in mortality rates and health-care costs in polluted environments. This is reflected in expansion of the market for environmental MEMS sensors. Reported to be worth USD 28 million in 2015, this market is expected to reach a value of USD 155 million by 2021, at a compound annual growth rate (CAGR) of 39%.¹

A better understanding of the health implications of air quality is also leading to stricter measurement and regulation. Buildings are particularly coming under the spotlight as improved insulation and limited air exchange with outside air can lead to build-ups of emissions of harmful volatile organic compounds (VOC) such as formaldehyde from furniture and interiors. ESAIRQ is developing miniaturised sensor technologies that will be key to sensor systems or sensor networks that monitor air quality and composition in such applications. The sensors could be embedded in basic infrastructure or in mobile devices, including as connected solutions. In addition, these technologies could be applied in other domains, for instance, medical environments and food safety to detect and identify air-borne pathogens.

Specifically, ESAIRQ is seeking to increase the selectivity of sensors to particle matter and to enhance detection of polluting organic and inorganic matter within gas mixtures. Research will focus strongly on miniaturisation and functional integration of components at chip-level to lower costs and energy consumption, while allowing for capabilities such as fine particle / fire detection and pathogen detection. The project will also apply semiconductor process technologies normally used for high volume, low cost manufacturing to deliver further cost and quality advantages.

The ESAIRQ consortium consists of twenty-six businesses and academic research organizations from six different EU countries. Their combined know-how will allow Europe to gain a strong position in the market for gas, fine-particle and pathogen-sensing technologies with potential to bring positive benefits for health, society and the environment. Several industry and SME partners have the approach to manufacture in Europe. Infineon targets the market of highly miniaturized sensors and will manufacture miniaturised sensors or components for sensor systems. Umweltsensortechnik GmbH is a successful medium sized enterprise with a development and production of ceramic sensor technology.

¹ Yole development 2016- MEMS industry 2016



UM sensor node
Copyright: University of Malta

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PENTA is managed by AENEAS.
More on PENTA: <http://www.penta-eureka.eu>
More on AENEAS: <https://aeneas-office.org>

About ESAIRQ



ESAIRQ is a RD&I project consortium involving 26 partners from 6 countries. The project partners are: Infineon (project Leader), Afore Oy, AlphaSIP Aragón, Aryballe Technologies SA, Asygn SAS, CEA, EC-Sense GmbH, eesy-innovation GmbH, Fraunhofer ENAS, Gasera Ltd, Institut Mikroelektronických Aplikací S.R.O, InfraTec GmbH, mirSense SAS, Philips Electronics Nederland BV, Pegasor Oy, Philips Consumer Lifestyle B.V., Qmicro BV, Soitec, Stichting IMEC Nederland, Technische, Umweltsensortechnik GmbH, Universiteit Eindhoven, University of Regensburg, University of Malta, University of Twente, Vaisala Oy, VTT Technical Research Centre of Finland Ltd.

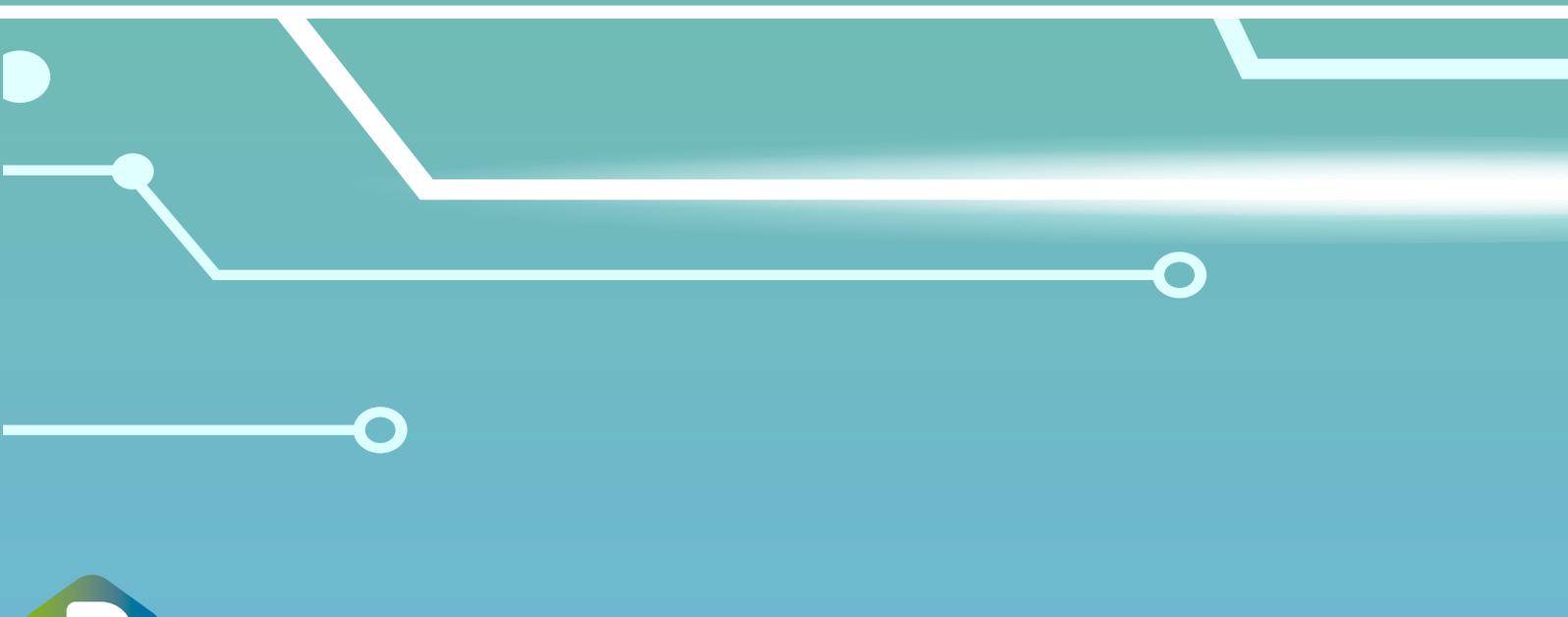
National funding support is provided by Czech Republic, Finland, France, Germany, Malta and The Netherlands.

More on ESAIRQ: <https://www.project-esairq.com/>





MuSiC





16105



An affordable, open, modular reference-platform to protect critical services on shared networks [MuSiC]

MuSiC (or Multi-level Security for Critical services) provides scalable and certifiable security to devices within the mid- to high-data-rate, cost-effective range. In particular, this project secures against threats related to applications, operating systems, the web and networks, with the prime purpose of protecting critical services on shared networks.

Cybersecurity Ventures (a cybersecurity researcher) predicts that global annual cybercrime costs will grow from \$3 trillion in 2015 to \$6 trillion annually by 2021. This includes data damage and destruction, lost productivity, embezzlement, fraud, as well as, post-attack disruption to the normal course of business, and theft of intellectual property and personal and financial data. Consequently, integrity and confidentiality of all handled information are becoming increasingly crucial.

The development of internet and mobile communications, and the increasing number and diversity of connected devices, are all making digital services ubiquitous. High-end devices—like smartphones, PCs and tablets in the consumer market—are becoming more secured. However, mid- to high-data-rate, cost-effective devices (such as IP cameras and routers) are still vulnerable due to a lack of certification and off-the-shelf-secured solutions.

Innovative way to secure critical services on shared networks

The goal of MuSiC is to develop an affordable, open, modular reference-platform providing a scalable and certifiable solution for any connected device (including mid- to high-data-rate ones) that secures against any threats related to applications, operating systems, networks and the Web, by protecting critical services on shared networks.

One technological innovation is to develop a novel architecture (both hardware and software), which is optimised for low-power and a cost-efficient IoT (internet of things), as well as, communication devices supporting the security mechanisms existing today on high-end computing and mobile devices. MuSiC plans to target several markets where trusted devices and digital services are required.

The major project outcomes will be:

- A scalable secure solution for the development of trusted devices offering adequate processing capabilities to support multimedia services, protecting against various kinds of attack covering secure access and sensitive data protection;

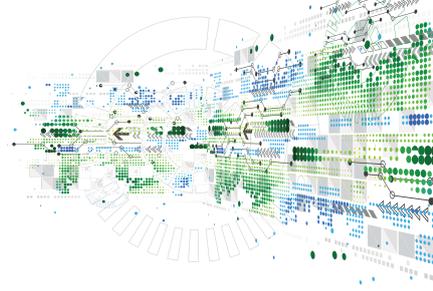
- Cost-effective, common-criteria security-certification paths up to the level required by mission-critical services in order to give users and manufacturers confidence in these trusted devices;
- Demonstrators for representative use-cases within Smart City and public protection and disaster relief applications, integrating these trusted devices and validating their security and performance requirements.

Outputs of the demonstrators using trusted devices will be:

- New services for Smart City applications based on public lighting and traffic monitoring demonstrated in France and/or in the Czech Republic;
- Secure UWB (ultra-wideband), a precise and fast location-detection system which integrates comprehensive security features, including an advanced encryption algorithm for data links;
- High-fidelity simulators to generate the scenarios and test the MuSiC approach;
- Demonstrator to validate optimal network communications during an emergency situation with an unmanned aerial vehicle (UAV);
- Real-time multimedia communication services;
- Built-in adaptive reconfiguration that ensures that the most resource-efficient versions of algorithms are used, based on the context of use;
- Improved IoT platform ready for diverse Smart City scenarios.

The project consortium is a good example of European collaboration. It is composed of 15 partners, with expertise in security and safety, and covering both the project technology and market value-chains. The consortium includes large- and small-enterprises strongly committed to promoting and disseminating industrial standards.





KEY APPLICATION AREAS

-  Transport & Smart Mobility
-  Health & Well-Being
-  Energy
-  Digital Industry
-  Digital Life

ESSENTIAL CAPABILITIES

-  Systems and Components Architecture, Design & Integration
-  Connectivity & Interoperability
-  Safety, Security & Reliability
-  Computing & Storage
-  ECS Process Technology, Equipment, Materials & Manufacturing

PARTNERS

STMicroelectronics / Prove & Run / CEA LIST / CEA LETI / AIRBUS Defense and Space / ADWAVE / FIT of Brno University of Technology / CAMEA / Enigmmedia / HI-Iberia Ingeniería y Proyectos / Quobis Networks SL / Tecnologías Servicios Telemáticos y Sistemas SA

COUNTRIES INVOLVED

-  Czech Republic
-  France
-  Spain

PROJECT LEADER

Marcello Coppola
STMicroelectronics Grenoble2 SA

KEY PROJECT DATES

01 June 2018 to 30 May 2021

Expected market impact

Several key markets, which could be impacted by MuSiC, need attention. The first is the cybersecurity and IoT market one. Here, global spending on cybersecurity products and services for defending against cybercrime is projected to exceed \$1 trillion cumulatively between 2017 and 2021. The global IoT security market was valued at \$4.83 billion in 2015 and will reach \$43.23 billion by 2020, growing at a compound annual growth rate (CAGR) of 55.01%.

Looking at the Smart City market, there are 315m street lights in the world, growing to 359m by 2026. LED (light-emitting diode, a semiconductor light source) and smart street-lighting will cumulatively represent a \$69.5 billion market opportunity over the next decade, as many cities replace their high-pressure sodium street lights with LEDs. And a growing number of cities are also discovering the benefits of incorporating new sensors and networked control into their new lights. Networked street lights provide an ideal platform for a range of innovative Smart City applications. The global homeland security surveillance-camera-market is expected to reach \$6.64 billion by 2021. The increase in traffic surveillance is one of the key factors driving growth in this market. Furthermore, the number of online traffic cameras used to monitor traffic flow on our roads is doubling every two-and-a-half years.

Public safety agencies around the world are echoing demands for the deployment of cost-effective broadband services. The total broadband LTE (long term evolution, a wireless communications standard) public-safety market is expected to grow at a CAGR of 44% over the next six years. Migration toward broadband LTE public-safety brings a new type of competition across the value chain, from content delivery device-providers to infrastructure/service providers. By 2024, there will be over 12m public safety broadband users using LTE-based devices.

Finally, the secure IC (integrated circuit) market will expand from \$1.8 billion units in 2016 to 3.5 billion units in 2021. However, this market will not be driven by a single type of solution. A layered security approach, as proposed by MuSiC, will result in OEMs (original equipment manufacturers) and service providers utilising a combination of hardware- and software-based mechanisms. And as 'things' functions become more standalone, the demand for hardware-based security will increase.

Removing the barriers

Unfortunately, market barriers exist because security has been largely considered a secondary issue. Not all applications require the same levels of security and cost-to-risk analysis. Minor things have low-costs, leading to low-power/memory requirements, thus limiting possible solutions. In addition, new OEMs lack the expertise, manpower or budgets. And fragmentation from an architecture perspective (hardware, software, operating system) is not helping either. Crucially, MuSiC will remove these barriers by offering an affordable open, modular and secure reference-platform.

MuSiC will achieve this by:

- Supporting the competitiveness of major European security-solutions actors;
- Growing the market for trusted devices, thus addressing OEMs and service providers, including emerging IoT suppliers who are often small medium enterprises lacking the required expertise in security;
- Protecting data and privacy of European citizens while reducing cybercrime costs;
- Promoting and extending existing security standards.

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VIDEO



MuSiC

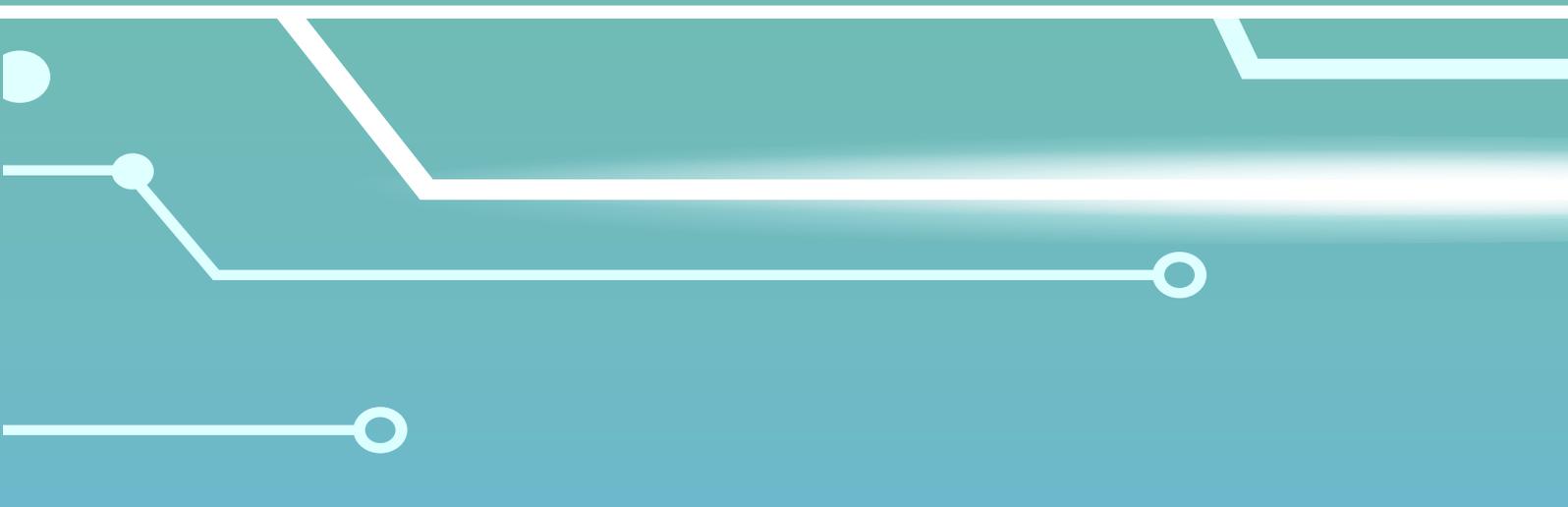


▶ Video: <https://youtu.be/6PLEy6Iz-y0>





SENSATION





16106



Developments in machine vision and ultra-HDTV broadcast will significantly improve resolution, colour gamut, dynamic range and image quality [SENSATION]

Cameras with higher resolution, increased speed, and wider dynamic range and colour gamut are needed to fulfil the needs of next-generation machine-vision and ultra-HDTV broadcast systems. These are key challenges the SENSATION project addresses through and improvements to existing components, and new developments.

Image capture and transmission are generic technologies that are deployed in a multitude of business applications, including manufacturing, health-care, security, automotive, TV broadcast, digital entertainment (such as digital cinema and gaming) and, more recently, agriculture. In order to improve product quality and increase productivity, the resolution and speed of systems have to increase continually, under constraints of power consumption and thermal performance. In addition, vision-based professional applications will require higher spatial and temporal resolutions and improved image quality, especially in broadcast.

Help is at hand. Modern CMOS (complementary metal oxide semiconductor) image sensors have already started replacing the older, slower and power-hungry CCD (charged coupled device) ones. However, more needs to be done. Current machine-vision systems are mostly based on the industrial PC, where image processing takes place. In order to be able to process ever-increasing pixel rates, future machine vision will be based on embedded systems, which are not only smaller and more cost-effective than PCs; but also faster and consume less power thanks to highly optimised architectures. These are compelling benefits.

Developing next-generation machine vision and broadcast systems

The overall goal of the SENSATION project is to develop technologies and improve building blocks needed for the next generations of CMOS image sensors, video processing and transmission. Responding to the market trend of vision-based professional applications in image capture – that is, the move towards higher spatial and temporal resolutions, wider colour gamut, higher dynamic range and improved image quality – new and improved building elements will be developed to drive and address these trends in production technologies, as well as connectivity and digital networks.

This project investigates such innovations as image processing, image compression and transmission that are needed for future machine-vision systems. This is in line with Industry 4.0, the name given to the current trend of automation and data exchange in manufacturing technologies. Specialists in all these areas will work together creatively to develop

the necessary elements of the value-chain. And, because standardisation is of paramount importance in the machine-vision market, there will also be collaboration with standards groups in Europe, USA, Japan and China.

On another front, the broadcast market is starting to migrate from HDTV to ultra-HDTV, a standard which supports 4Kx2K and 8Kx4K resolutions; 12 bits per pixel (versus 10 bits in HDTV); and a wider colour gamut and an increased dynamic range. Another aim of this project is to develop new and improved image processing (IP) in image sensors (moving from the 0.18µm/110nm to the 65nm technology node), and to bring UHDTV to a higher specification level.

It is worth noting that, though products associated with the high-end machine-vision and broadcast target markets are quite different, the technical challenges are very similar. It is therefore very beneficial to do R&D for both markets in the same project. This not only helps to share knowledge and designs between project partners, but it also helps develop and apply new standards that can be deployed in both markets.

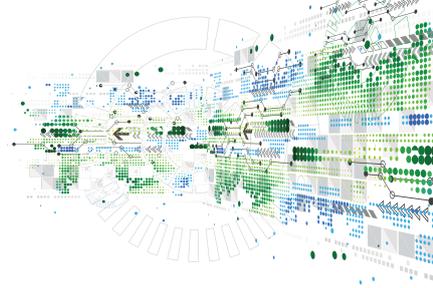
Key project developments and deliverables are:

- Building blocks for CMOS image sensors: smaller global shutter pixels; increased dynamic range; increased data rates; auto-focus pixels; improved ultra-high-speed architectures; and high-speed serial interfaces;
- New solutions for camera transmission;
- Demonstration of results in cameras for machine vision and broadcast, and image-sensor evaluation set-ups;
- Standards for a high-speed serial interface for image sensors, image compression and camera interfaces. Here the broadcast development team will work with the SMPTE standardisation body.

Creative players needed

In order to meet future market requirements, innovations are required in products of all companies in the machine-vision and broadcast value-chains. A highly qualified and multi-disciplinary team is therefore required to develop the various aspects of the technologies, such as optics, image capture,





KEY APPLICATION AREAS

-  Transport & Smart Mobility
-  Health & Well-Being
-  Digital Industry
-  Digital Life

ESSENTIAL CAPABILITIES

-  Systems and Components Architecture, Design & Integration
-  Connectivity & Interoperability
-  Safety, Security & Reliability
-  ECS Process Technology, Equipment, Materials & Manufacturing

PARTNERS

Caeleste CVBA
intoPIX
ON Semiconductor Belgium BVBA
Adimec Advanced Image Systems BV
Delft University of Technology
Grass Valley Nederland BV

COUNTRIES INVOLVED

-  Belgium
-  Netherlands

PROJECT LEADER

Jochem Herrmann
Adimec

www.project-sensation.eu

KEY PROJECT DATES

01 January 2018 - 31 December 2020

video processing and transmission, and to optimise these technologies. This is why leading European companies in the imaging industry with proven track-records are part of the SENSATION project, jointly working on the required innovations. The project consortium consists of an R&D institute; fabless (without in-house chip production) design houses; semiconductor manufacturers and system integrators advanced in image sensor technologies, as well as design, video processing, transmission and camera integration.

Demonstrators will be developed, not only to verify functionality and performance, but also to demonstrate to potential customers the outcome of the project. This will also allow project partners to stay in the forefront of their markets and further improve their market position. Unusually, not only is there collaboration within the same value chain, but with outside ones as well. Partners collaborating in the SENSATION project face, for example, the same technological challenges found in different non-competitive markets. This not only drives information sharing (in experience, designs, best practices), but also joint developments and cooperation in standardisation.

Market growth

Taking a look at the markets in which SENSATION will play a role, the main growth areas for machine-vision products (which focus on high resolution, high frame-rate, and area scan) are North America and EMEA (Europe, Middle East and Africa). However, significant growth is also expected in Asia and China. The market size in 2015 for machine-vision cameras was put at US\$650m (excluding smart cameras and smart sensors). The compound annual growth rate (CAGR) for cameras is about 2%, several times that for industrial image-sensors which are also deployed outside the machine-vision-camera market.

In the next five years, the machine-vision market is expected to be driven by the following:

- Industry 4.0 in general, and regional initiatives like 'made in China 2025' will stimulate smart manufacturing where robotics and smart vision will play a key role;
- In the high-end market, the combination of ever-more demanding

inspection tasks and the continual push for lower overall cost-of-ownership drive the need for small pixel, high resolution sensors that can perform high quality inspection at reasonable frame-rates, thereby reducing the overall inspection time (and cost);

- This trend sets new challenges throughout the vision system, including the smaller sensor-pixels which need to deliver improved optical performance;
- New camera-interface standards enable the move of sharply increased bit-rates from camera to centralised vision-systems. In parallel, there is also a trend towards on-camera 'smart' or 'embedded' vision, resulting in distributed image processing and a localised inspection decision process.

In 2015, the outside-broadcast market was US\$58m and the studio market US\$100m. The main growth areas are Asia-Pacific, Latin America and Russia. These markets will in the coming years be mainly driven by the following:

- Content creators are moving towards higher-resolution formats for sports broadcast television and cinema, to create premium-quality content in a market with intense competition from Web content, pay-TV, and video-on-demand. Japan is the first country to roll out UHDTV in 4K and 8K. The 2020 Olympics will be partly broadcast in 8K;
- Even though many TV programmes are being watched on-demand, consumption of live events is growing globally and will continue to increase, resulting in continual investment in cameras for live-event production and broadcasting;
- Slow-motion will continue to increase in popularity. Broadcasters will be using more cameras with slow-motion features in a wider range of applications (programmes). The trend is towards multi-purpose cameras instead of specialty cameras for each application;
- And equipment prices and operational cost will decrease giving content-creators faster return on investment.

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Penta (E! 9911), is EUREKA Cluster whose purpose is to catalyse research, development and innovation in areas of micro and nanoelectronics enabled systems and applications.





SENSATION

SENSATION new technologies and building blocks for machine vision and Ultra-HDTV broadcast

A project within the EUREKA PENTA programme

Paris, November 8, 2018 – SENSATION, a project within the EUREKA PENTA Cluster managed by AENEAS Industry Association, is developing innovative image capture, transmission and processing technologies for high-end Machine Vision and Broadcast applications. The project focuses on key requirements common to all professional vision-based applications namely: higher spatial resolution, higher temporal resolution (frame-rate), wider colour gamut, higher dynamic range and improved image quality.

Image capture, processing and transmission technologies are used in numerous applications from manufacturing to healthcare, security, automotive, digital entertainment (TV broadcast, digital cinema, gaming) and even agriculture. Moreover, while machine vision for industrial production processes and broadcast are extremely different markets, the technical challenges are fundamentally the same. By collaborating on key building blocks, the partners in the SENSATION project are sharing knowledge and opening the way to creating standards relevant to both application areas.

Machine vision is an important technology for modern production processes, with manufacturers looking for solutions for ever-more demanding inspection tasks to improve product quality and increase productivity. This calls for small pixel, high resolution sensors that can perform high quality inspection at high speeds. To meet these requirements, along with faster image processing and lower costs, SENSATION is working on the next generation of CMOS (Complementary Metal Oxide Semiconductor) image sensors with higher data rates, smaller pixels with global shutter capability and high dynamic range, as well as serial I/O to allow for easier interfacing and power reduction. It is also developing embedded systems that can process image data faster than the current systems which rely on external PCs, as well as on faster transmission of data to centralized vision systems.

In the broadcast market, demand is being driven by the migration from HDTV to ultra HDTV (UHDTV). The UHDTV standard supports 4K and 8K resolutions, 12 bits per pixel (compared to 10 bits in HDTV), a wider colour gamut and an increased dynamic range. Meeting the standard calls for improvements in all aspects of image capture and processing. Although new, UHDTV is already attracting attention particularly for live events and sports broadcasting. Japan is one of the first countries to roll out UHDTV and part of the Olympic Games 2020 in Japan will be broadcast in 8K.

The SENSATION project brings together key European players with proven track records in the imaging industry including R&D institutes specialised in image sensor technologies, image sensor designs and video processing; fabless design houses; a semiconductor manufacturer; image compression experts and system integrators. Through this collaboration the partners can speed innovation, drive standardisation and strengthen Europe's ability to compete in global markets for image capture, processing and transmission.





About the PENTA programme (managed by the AENEAS Industry Association)

PENTA is a EUREKA cluster whose purpose is to catalyse research, development and innovation in areas of micro and nanoelectronics enabled systems and applications - where there is shared national and industrial interest. Based on the Electronic Components & Systems (ECS) Strategic Research Agenda (SRA) key areas and essential capabilities, PENTA programme contributes to the development of electronic solutions with the opportunity for rapid competitive exploitation and a strong impact on European societal challenges. The PENTA project team is supporting SMEs, large corporations, research organisations and universities by facilitating access to funding, fostering collaborative work and creating consortia.

PENTA is managed by AENEAS.

About PENTA: <http://www.penta-eureka.eu>

About AENEAS: <https://aeneas-office.org>

About SENSATION

SENSATION is a RD&I project consortium involving 6 partners from 2 countries. The project partners are: Adimec Advanced Image Systems BV (Project leader), Caeleste CVBA, intoPIX, ON Semiconductor Belgium, Delft University of Technology and Grass Valley Nederland BV. National funding support is provided by Belgium (Flanders region) and The Netherlands.

About SENSATION: <https://www.project-sensation.eu>



ULIMPIA





16101



Technology and fabrication methods are making ultra-sound diagnostics affordable and impacting continuous medical care [ULIMPIA]

ULIMPIA combines state-of-the-art MEMS ultra-sound technology with innovations in conformably patch technology to create an open platform for diagnostic ultra-sound patches. These body patches will enable continuous monitoring of bodily functions, making ultra-sound diagnostics affordable to the consumer, but also keeping health costs down by moving continuous medical care from the hospital to the home.

Back in the early the 1990's, practically all electronic cameras were based on so-called plumbicon recording tubes. These tubes were bulky and needed high voltages, as well as, magnetic focusing and deflection coils, making electronic cameras expensive and mainly reserved for the professional market. Within a decade that situation changed completely. With the introduction of silicon-based CCD (charge-coupled device) and CMOS (complementary metal-oxide-semiconductor) image sensors, the price of electronic cameras drastically went down, while at the same time quality increased with a dramatic reduction in size.

Significantly, this has consequences for medical ultra-sound imaging and therapy. Until now, most ultra-sound diagnostics were based on traditional piezo ceramic ultra-sound transducers. These are labour-intensive to fabricate and therefore expensive, limiting the use of ultra-sound diagnostic to professional users. Now, this situation is set to change dramatically during the next decade because exactly the same development in electronic cameras is at the moment taking place in medical ultra-sound diagnostics. After 60 years, during which it has proven its immense clinical value, ultra-sound is now ready to enter the consumer marketplace, thanks to projects such as ULIMPIA.

Open platform with continuous monitoring

ULIMPIA will combine state-of-the-art MEMS (micro-electro-mechanical systems) ultra-sound technology with innovations in conformably patches to create an open platform for diagnostic ultra-sound patches. These body patches will enable the continuous monitoring of bodily functions on the surface of the skin, but also deep inside the body. ULIMPIA will also demonstrate such applications as blood-pressure measurement; bladder monitoring; blood-vessel inspection of diabetes patients; early breast-cancer detection; needle guidance; and wound monitoring. The resulting platform will be accessible to multiple users, enabling them to concentrate on application development, rather than on the development of technological point-solutions.

A large European consortium consisting of 28 partners from seven countries will develop the necessary technological building blocks, which include: a programmable universal ultra-sound engine, conformable patch technologies and functional adhesive and bio-compatible materials.

The objectives of ULIMPIA are to:

- Enable ultra-sound diagnostics to become a consumer commodity;
- Create new markets, encompassing micro-fabrication, patch fabrication and applications;
- Fuel the market for large-area conformable assembly technologies;
- Help manage the cost of health care, by bringing point-of-care diagnosis to the patient.

Spreading the word

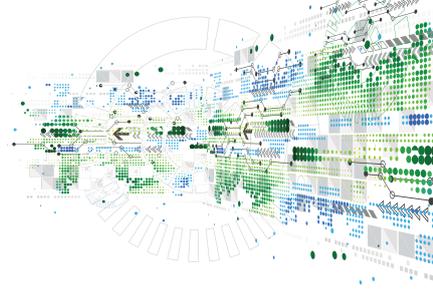
Dissemination of the project results to be delivered by the ULIMPIA consortium constitutes a key aspect of the project. Relevant activities are foreseen to ensure the visibility and public awareness of the project, and to support the adoption of its results in industry and its related research communities.

Dissemination activities will include:

- Workshops and demonstration events;
- Journal publications and conference contributions;
- A special session at the annual 'Be-Flexible' forum;
- Press releases;
- White papers and brochures;
- A web platform.

Medical, commercial and financial gains

The cost of health care in Europe amounted to \$383 billion in 2016, and it is expected to grow to \$425 billion in 2025. This expenditure is exacerbated by a rapidly ageing population. With ageing, the occurrence of many chronic diseases increases exponentially.



KEY APPLICATION AREAS

-  Health & Well-Being
-  Digital Industry
-  Digital Life

ESSENTIAL CAPABILITIES

-  Systems and Components Architecture, Design & Integration
-  Connectivity & Interoperability
-  Safety, Security & Reliability
-  Computing & Storage
-  ECS Process Technology, Equipment, Materials & Manufacturing

PARTNERS

IMEC VZW / MEPY BENELUX / PICOSUN OY / VTT Technical Research Centre of Finland Ltd / LINXENS France / Fraunhofer EMFT / GED Gesellschaft für Elektronik und Design mbH / Henkel AG & Co KGaA / Institutes of Textile and Fiber Research Denkendorf (DITF) / KARL OTTO BRAUN GmbH & Co. KG / NXP Semiconductors Germany GmbH / warmX GmbH / Delft University of Technology / Novioscan BV / Philips Electronics Nederland BV / TNO / Eurecat

COUNTRIES INVOLVED

-  Belgium
-  Finland
-  France
-  Germany
-  Netherlands
-  Spain

PROJECT LEADER

Ad de Beer
Philips Electronics Nederland BV
<http://ulimpia-project.eu/>

KEY PROJECT DATES

01 April 2018 to 31 March 2021

The ULIMPIA project will be vital in:

- Accelerating the current paradigm shift from large diagnostic equipment in hospitals to point-of-care diagnostics;
- Shifting continuous medical care from the hospital to the home environment, thus reducing the cost of health care and alleviating the socioeconomic burden;
- Enabling European players to capture substantial market share in consumer and clinical-grade, smart-body patches;
- Enhancing Europe's competitive advantage in the ultra-sound diagnostics and imaging;
- Consolidating Europe's leading position as a high-end semiconductor and MEMS supplier.

Diverse market opportunities

The global market for point-of-care diagnostics in 2015 was valued at nearly \$18 billion. This market is expected to grow from \$19.3 billion in 2016, to \$28.3 billion in 2021, at a compound annual growth rate (CAGR) of 8%. This growth, which is expected to continue for the coming years, is substantially fuelling the growth in the entire in-vitro diagnostics industry. In recent years, the market has witnessed an exponential increase in technological innovations in wearable electronics by the incorporation of sensors and wireless connectivity. This will play a crucial role in the growth of personalised diagnostics and monitoring markets.

The global market for wearable health-care devices is expected to reach a revenue level of \$18.9 billion in 2020, growing at a CAGR of about 30%. The consumer-health market, including wellness, fitness, and sport wearables, is expected to grow at a CAGR of 27.8% (2015-2020). And medical and clinical-grade wearables, the most promising product segment within health-care wearables, is expected to grow at a CAGR of 32.9% between 2015-2020.

Smart on-body conformable patches will be attractive candidates to boost the wearables health-care market. It is envisioned that they will record a mass-market proliferation in the near future due to the

growing interest from end-users, such as manufacturers of medical equipment and bandages, and pharmaceutical companies. The market size for "traditional, non-ultra-sound" smart patches has been estimated at over \$12 billion in 2015 with a CAGR of 11%.

It is relevant to also review the traditional ultra-sound imaging market. Europe accounted for the largest share of the global ultra-sound market in 2015, in which the second largest manufacturer of ultra-sound equipment globally had a market share of 20% and a turnover close to \$800m. Globally, the ultra-sound imaging segment is growing, and is expected to reach \$6.9 billion by 2020, at a CAGR of 5.5% from 2015.

Finally, the semiconductor market for health care in Europe is expected to reach \$3.4 billion in 2018 with a CAGR of 5.5%. This market consists of medical imaging (CAGR of 3.6%), clinical diagnostics and therapy (1.1%), and consumer medical electronics (8.7%). Importantly, the advent of consumer ultra-sound applications is expected to significantly grow this segment of the MEMS industry. MEMS processing and design knowledge is highly specialised and relatively scarce. Europe currently holds a leading position in the worldwide strongly growing €10 billion MEMS market, which has a CAGR of 13%⁹. The medical MEMS market will account for \$7.25 billion in 2019 with the highest CAGR of 23.9% in the global MEMS market (2012).

Continuity and growth ensured

At completion, the project consortium will ensure that the open platform is maintained and will continue to be available for validation and prototyping. This arrangement will be in place until the start of a venture that will own and exploit this platform. Here, project partners will have the opportunity to participate in the venture (owned by the participating partners) to exploit the pilot line. Initially, it will make use of the manufacturing facilities and pilot lines of project partners.

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ULIMPIA

ULIMPIA enables smart body-patches for ultra-sound monitoring at home

A project within the EUREKA PENTA programme

Paris, 23 October 2018 – ULIMPIA, a project within the EUREKA PENTA cluster managed by AENEAS Industry Association, is breaking new ground in health care by enabling ultra-sound monitoring at home through smart body patches.

The ULIMPIA technology goes beyond existing body patches that measure only parameters on the surface of the skin - temperature and humidity, for instance. ULIMPIA's new MEMS (Microelectromechanical systems) -based technology can look inside the body and continuously monitor and diagnose processes going on under the skin, or even deep within the body, such as blood pressure or bladder function. This will allow many more patients to stay at home instead of requiring hospital-based monitoring, while health services will benefit from reduced costs. In addition, the project's open platform approach will allow application developers to enter this entirely new consumer healthcare market by creating their own applications based on the ULIMPIA technology.

With an ageing population and rising rates of chronic diseases such as cardiac vascular diseases (CVD), obesity, diabetes and chronic obstructive pulmonary disease (COPD), Europe is facing significant increases in healthcare costs – from USD 383 billion in 2016 to an expected USD 425 billion in 2025¹. ULIMPIA aims to provide point-of-care diagnostic solutions that will both reduce the cost of continuous (remote) on-body diagnostics and empower patients to better manage their health at home. The patches will be wirelessly connected to a peripheral device such as a mobile phone, which analyses and displays the data to give real-time feedback to the user. Applications could include blood pressure measurement, bladder monitoring, blood vessel inspection of diabetes patients, early breast cancer detection, needle guidance and wound monitoring.

The ULIMPIA project represents a continuation and consolidation of Europe's strength in ultra-sound diagnostics. A large European consortium consisting of 17 partners in six countries will develop the necessary technological building blocks including: a programmable universal ultra-sound engine, conformable patch technologies (that adapt to the form of the human body) and functional adhesive and bio-compatible materials. By bringing ultra-sound to the consumer market, ULIMPIA is expected to drive high production volumes and fuel further innovation in MEMS ultra-sound technologies to support Europe's existing leading role in professional ultra-sound diagnostics.

¹ Vision 2025 – The future of healthcare, Frost &Sullivan, 2016



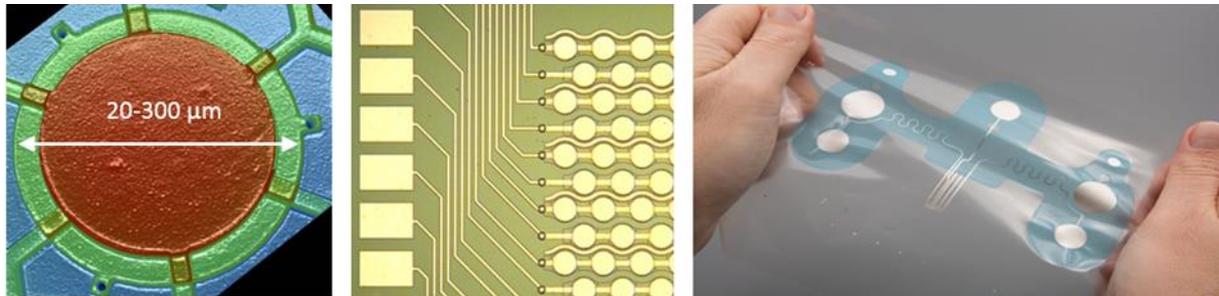


Figure. Left CMUT MEMS ultra-sound transducers are made using micro-fabrication. They can be fabricated on top of the ASICs that drive them (middle). Combined with innovations in conformable substrate technology they enable on-body personal ultra-sound diagnostics (photo: Philips, Holst).

About the PENTA programme (managed by the AENEAS Industrial Association)

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PENTA is managed by AENEAS, the European industry association

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About AENEAS: <https://aeneas-office.org>

About ULIMPIA



Ulimpia is a RD&I project consortium involving 17 partners in six countries. The project partners are: Philips Electronics Netherlands BV (Project leader), Philips Electronics Netherlands BV, TNO, Novioscan, TU Delft, IMEC, Mepy, Fraunhofer EMFT, Karl Otto Braun (KOB) GmbH, WarmX, Henkel, Institute for textile and fiber research denkendorf, Institute for textile and fiber research denkendorf, NXP Germany, GED Gesellschaft für Elektronik und Design GmbH, VTT, Picosun, Linxens, Eurecat. National funding support is provided by Finland, Germany, the Netherlands and Spain.

About ULIMPIA: <http://ulimpia-project.eu/>



VIDEO – INTERVIEW



ULIMPIA



► Interview Video: <https://youtu.be/6-oQ9Mfj4k8>

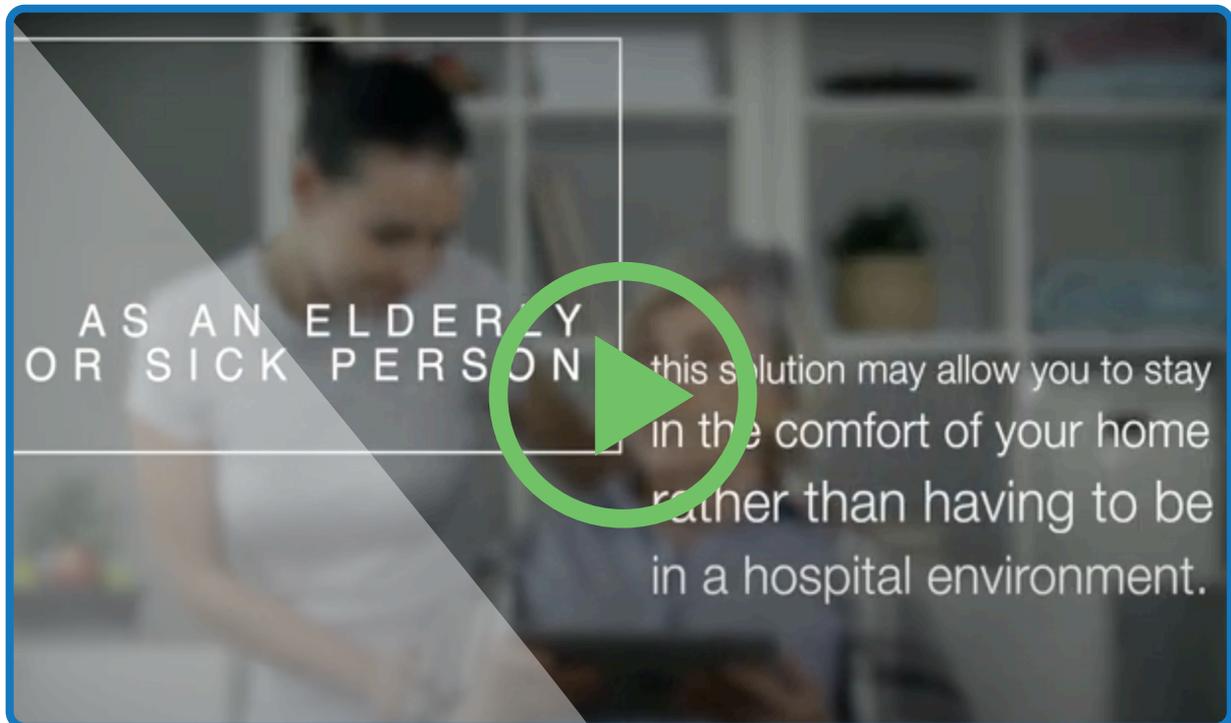




VIDEO – PROMOTION



ULIMPIA



▶ **Promotional Video:** <https://youtu.be/bO-CggEcpn8>



CAVIAR





PROJECT PROFILE

17003



Improved image capture technology will address key economic and societal demands and challenges

[CAVIAR: Cmos imAge sensor and VIdeo reseARCh]

The CAVIAR project brings together important players with proven track records to improve system-level image capture for medical diagnostics, sustainable agriculture, live television productions, and safety and security. It will also extend the functionality of professional CMOS image sensors for multiple applications.

We are facing several economic and societal challenges. Firstly, society is ageing, leading to an increase in chronic diseases requiring intensive healthcare, which drives the need for change to keep treatment affordable. Improved diagnostics reliability can shorten turn-around times. Then there is agriculture. To make the agro-food industry sustainable, new 'precision agriculture' solutions are needed to deal with, for example, early detection of possible food-related causes of ill-health in order to reduce the burden of such diseases on our healthcare services. Thirdly, consumers are looking for ways of improving their viewing pleasure through Ultra-High-Definition (UHD) TV and High-Dynamic-Range (HDR) pictures, forcing media content creators to move to UHD slow motion. The result is a continuing altering of the broadcasting landscape, in which camera operators will need better means to focus on UHDTV and ensure a healthy and comfortable working space. Finally, the digital-component industry is also coming under pressure to develop general-purpose image-sensors for use in industrial vision, but also in safety and security applications (where cameras trigger early-warnings) and in automotive for driver and passenger monitoring.

The common technology for addressing all these application demands is image capture. However, current image-capture and processing systems have to be improved beyond the state-of-the-art in spatial-, temporal-, and spectral resolutions that enable better diagnostics, and or perception. What's more, in the case of picture performance, not only better image sensors are needed; but also new hardware, image-processing capabilities and high-data-rate handling need to be developed. That's where the CAVIAR project can provide the necessary answers.

Developing image-capture technologies for key application domains

CAVIAR will develop various aspects of image capture technologies, such as optics, image capture, video processing and transmission, needed for these applications. These features will improve system-level image capture for medical diagnostics, sustainable agriculture, live television productions, and safety

and security, as well as, extend the functionality of professional CMOS image sensors for multiple applications.

In particular, key project goals, deliverables and activities are as follows:

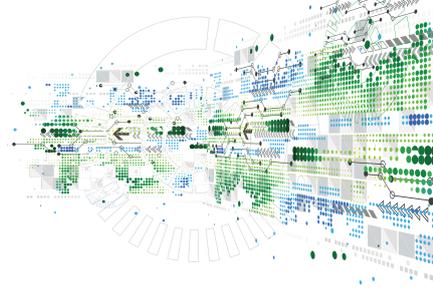
- Designing new image sensors and developing application demonstrators, including new hardware and firmware/software algorithms;
- Enhancing image performance by extending the light spectrum that can be captured, thus increasing pixel performance and enabling higher frame rates in UHDTV resolution;
- Developing image capture systems for digital pathology, Next-Generation Sequencing (NGS), operating room-assisted imaging and life-cell imaging to enable better diagnostics and shorter turn-around times in hospitals;
- Developing a multispectral camera for precision agriculture and food sorting, providing solutions for a sustainable agri-food industry and slow-motion image-capture for live television;
- Supporting content creators to transition from HDTV to UHDTV;
- Complying with the EMVA 1288, CoaXPress and SMPTE standards.

Additional benefits for Europe

Project research and results (mainly shared at conferences and trade shows) will close the knowledge gaps across the European value-chain for micro- and nanoelectronics-based components and systems, from technology providers to end-users. Importantly, project partners and their European business peers can use this market and application experience and expertise to define and specify next-generation CMOS image-sensor systems.

In addition, research conducted in CAVIAR will also reinforce and enhance existing strengths in Europe's micro- and nanoelectronics industries. To stay ahead of foreign competition in these markets, it is crucial to select and develop the right differentiating functionalities and





KEY APPLICATION AREAS

-  Health & Well-Being
-  Safety & Security
-  Digital Industry
-  Digital Life (Agriculture)

ESSENTIAL CAPABILITIES

-  Systems and Components
Architecture, Design & Integration
-  Connectivity & Interoperability
-  Safety, Security & Reliability
-  Computing & Storage
-  ECS Process Technology, Equipment,
Materials & Manufacturing

PARTNERS

Adimec Advanced Image Systems BV
AMS Sensors
CEA
EVS Broadcast Equipment Brussels
EVS Broadcast Equipment Liège
Grass Valley Nederland BV
Institut Langevin
MsEyeTech
TNO (Netherlands)
Université de Bourgogne

COUNTRIES INVOLVED

-  Belgium
-  France
-  Netherlands

PROJECT LEADER

Klaas Jan Damstra
Grass Valley Nederland BV
www.caviar-project.eu

KEY PROJECT DATES

01 March 2019 to 28 February 2022

to optimise technologies used in end-user applications. More to the point, sharing and deploying these requirements will help optimise performance and functionality in line with what is really needed in image-capture systems, instead of a more general optimisation for wider, but average use.

Bright market outlook

Main medical-market drivers in the coming years will be faster diagnosis for more patient-friendly treatment; higher diagnosis quality in having fewer false-positives and false-negatives; and a lower total cost of ownership for the overall diagnostics workflow and supply chain. In digital pathology, the number of oncology incidences is expected to grow, while the number of pathologists across countries declines. Surgery repeat-rate is 23% with an average cost of US\$13,500, resulting in an average savings of US\$3,000 per surgery, for an annual total of US\$325m. Tele-pathology consultation services will increase and regulatory approval of digital pathology products for primary diagnosis will be given. In NGS, the cost of human genome sequencing will come down, making personally targeted medicines and treatment feasible. The world-wide NGS market is expected to double in value during 2016–2021, to US\$6.5 billion.

For precision agriculture, the main market drivers in the coming years will be an increasing use of multispectral imaging system technology in research, and new emerging technologies to make smaller portable multispectral cameras with advanced imaging capabilities and an increase in accuracy and consistency in captured data. The multispectral imaging systems market is expected to grow worldwide, from US\$7.41 billion in 2016, to US\$12.71 billion by 2021 (with a CAGR of 11.4%).

Regarding broadcasting, consumption of live events is growing globally and will continue to increase, resulting in a continuous investment in cameras. Slow motion will continue to grow in popularity. Broadcasters will be using more slow-motion cameras in a wider range of applications/programmes. Equipment prices and operational costs will decrease, giving content creators a faster return on investment. In the coming years (according to research published by Frost & Sullivan, IABM and Devoncroft), content creators will continue to move towards higher-resolution formats for sports television and cinema, to create premium-quality content in a market with intense competition (with Japan being the first to roll out UHDTV in 4K and 8K for the Olympics in 2020).

Finally, investigating the digital-component market for image sensors in industry, market reports (by Yole Développement) expect machine vision and inspection image-sensor demand to grow with a CAGR of 13.5% to 4m units in 2021, resulting in an overall market size of approximately €300 million in 2021.

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CAVIAR

CAVIAR improves image sensing for healthcare, sustainable agriculture, industry and entertainment

A project within the EUREKA PENTA programme

Paris, 7 November 2019 -CAVIAR (Cmos imAge sensor and Video research), a project within the EUREKA PENTA Cluster and managed by industry association AENEAS, is developing new image capture technologies that will deliver benefits for healthcare, sustainable agriculture, digital industry and entertainment. By bringing together world-class engineering and research skills from across Europe, the CAVIAR project aims to enable higher imaging performance and new capabilities for these economically and socially important application domains. CAVIAR will develop image sensors and application demonstrators, including hardware and firmware / software algorithms, with the goal of improving system-level image capture and extending the functionality of professional CMOS image sensors for multiple applications.

Given the challenges of providing affordable and accessible healthcare as the world population ages and chronic diseases increase, healthcare is a key focus for the CAVIAR project. Improved imaging in diagnostics can improve reliability (fewer false negatives / positives) and support quicker, more effective and efficient patient-focused care. In particular, CAVIAR aims to deliver advances in image capture for digital pathology, Operation Room assisted imaging, cell imaging, ophthalmology and Next Generation Sequencing (NGS), which will be key for personalized medicine. Overall, the market opportunities in healthcare are enormous, with NGS alone expected to double from 2016 to 2021 to reach USD 6.5 billion a year.

CAVIAR's improved sensor technologies will also be applicable in multi-spectral imaging (i.e. capturing specific wavelengths of the electro-magnetic spectrum). Multi-spectral imaging is central to precision agriculture, which supports sustainable practices by providing farmers with detailed information about plants and conditions at a highly local scale. This can result in reduced inputs, better resource protection and increased traceability, and can help the expansion of organic agriculture which is highly recommended by the UN FAO (United Nations Food and Agriculture Organization).

In the fiercely competitive digital entertainment market, CAVIAR's innovations will support the move to higher-resolution formats for cinema and sports television. The project will develop image capture and replay for slow motion UHD (Ultra-High Definition) TV and optimizations from image capture to transmission. These will be particularly relevant as demand for live events continues to grow worldwide, and with Japan's roll-out of 4K and 8K UHD TV for the 2020 Olympic Games.





The CAVIAR project brings together 10 European organisations, including leading players in CMOS sensor manufacture and imaging applications, as well as world-class research institutions. This breadth of partners allows for a sharing of market, application and user expertise, and input into CMOS sensor design and manufacture for future systems. As a result, the project will be able to develop solutions across the entire value chain, covering requirements from technology providers to end-users and filling gaps in Europe's capabilities in these domains.

About the PENTA programme

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PENTA is operated by AENEAS.
More on PENTA: <http://www.penta-eureka.eu>
More on AENEAS: <https://aeneas-office.org>

About CAVIAR



CAVIAR is a RD&I project consortium involving 10 partners from 4 countries. The project partners are: Grass Valley Nederland BV (project leader), 3DHISTECH, Adimec Advanced Image Systems BV, AMS Sensors, EVS Broadcast Equipment (Brussels, Liège), CEA, Institut Langevin, MsEyeTech, TNO (Netherlands) and Université de Bourgogne

More on CAVIAR: <http://caviar-project.eu/>



VIDEO



CAVIAR



▶ Video: <https://youtu.be/0T5I4FEU7Bk>



CAVIAR

HiPer





PROJECT PROFILE

17006



Providing on-board computational and communication power and functionality for safe autonomous driving [HiPer]

The HiPer project will develop an automotive-grade HPVC computer system capable of handling level 5 autonomous driving and providing new electrical architectures which ensure sufficient compute power and the necessary communication interfaces. This will also mean fundamental changes to connectivity, computational power and safety in vehicle technologies.

Road travel and transportation are notoriously disadvantaged by the effects of traffic and congestion: not only the pressure and irritation caused to drivers and passengers, but also energy inefficiencies and, crucially, accidents and fatalities. Even though the newer generation of vehicles already support drivers with such niceties as route planning and guidance, assisted or automated parking and real-time traffic information, these functions and features do not go far enough: they cannot replace the human driver or provide highly flexible, efficient and safe travel; and neither do they really contain the volume of traffic. To address these issues and also create a new quality of driving comfort, autonomous driving (AD) could be the answer.

The Society of Automotive Engineers defines six levels of automation for autonomous cars, where each level has a specific set of requirements that a vehicle must meet before it can be considered to operate at that level. AD at level 5 requires truly high-performance vehicle computers (HPVC) to perform a multitude of complex functions, such as comprehensive vision processing, object recognition, intelligent traffic system and task dispatch between different electronic control units (ECUs) in the car. The HPVC system must be capable of safely handling all driving situations autonomously.

However, there are no automotive-grade HPVC modules and systems, and even though the first necessary components could become available shortly, they are not expected to be designed for the use in the harsh conditions of real vehicles. Furthermore, essential technological obstacles need to be overcome before solutions can qualify as 'regular' products at affordable prices. These are typical areas the HiPer project will focus on in its work to close these gaps.

Delivering automotive grade level-5 HPVC computer system

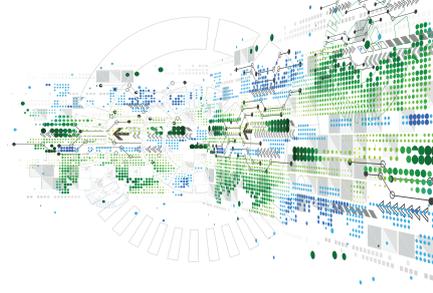
The main deliverable of HiPer will be an automotive-grade HPVC computer system capable of handling level 5 autonomous driving and providing new electrical architectures which ensure sufficient compute power and the necessary communication interfaces. This will

mean fundamental changes in vehicle technologies with respect to connectivity, computational power and safety. Importantly, the project consortium will also validate all of this by demonstrating the HPVC system in a passenger car by creating an HPVC demonstrator and an automotive-grade, in-car, high-speed network.

This calls for three tightly linked innovation paths and validation activities:

1. Computation path: will tackle the thermal challenges by new highly reliable automotive-grade cooling concepts based on advanced heat-path engineering with integrated spreader and heat-pipe technologies, as well as, novel 3D-printed micro channel and direct liquid cooling approaches. The work in this innovation path will require the introduction of new materials, and new heat transfer components and technologies in the vehicle;
2. Communication electrical connectivity path: will develop new HPVC interfaces that allow a data throughput of more than 10 Gbit/s as required on-board for all time-critical applications. New multi-channel, high-speed connectors and wiring harnesses solutions will become the future standard in autonomous cars. Furthermore, Ethernet chips, high-speed AD converters and a time-sensitive networking (TSN) protocol suite will be developed to increase the quality of service through, for example, high bandwidth, predictable low latency, and prioritisation of data streams;
3. System integration path: will improve HPVC thermo-mechanical reliability and functional safety in harsh automotive environments, achieving a lifetime of 50,000 hours in contrast to the current 8,800 hours. This will include: the development of an innovative mould underfill technology (equipment, process and simulation); the application of new accelerated testing and qualification methods; functional safety by prognostics and health management (PHM); new design for reliability (DFR) simulations; and reliability concepts developed in intense cooperation with the computational/thermal innovation path.





KEY APPLICATION AREAS

-  Transport & Smart Mobility
-  Safety & Security

ESSENTIAL CAPABILITIES

-  Systems and Components Architecture, Design & Integration
-  ECS Process Technology, Equipment, Materials & Manufacturing

PARTNERS

IMEC - Interuniversitair Micro-Electronica Centrum vzw
 Interflux Electronics nv
 Materialise
 AUDI AG
 CHEMNITZER WERKSTOFFMECHANIK
 Dynardo GmbH
 Fraunhofer Institute for Electronic Nano Systems
 GLÜCK Industrie-Elektronik GmbH
 NXP Semiconductors Germany GmbH
 Robert Bosch GmbH
 Technical University of Chemnitz
 Advanced Packaging Center BV
 Boschman Technologies BV
 Delft University of Technology
 Eindhoven University of Technology
 Fasttree3D
 NXP SEMICONDUCTORS NETHERLANDS BV

COUNTRIES INVOLVED

-  Belgium
-  Germany
-  Netherlands

PROJECT LEADER

Frank Pelz
 Robert Bosch GmbH

KEY PROJECT DATES

June 24, 2019 to June 23, 2022

In particular, the following key requirements will be addressed:

- Much higher computational power at the highest functional safety-level. Based on most modern technologies, powerful processors generate up to 300W;
- Comprehensive perception of the surrounding environment in real-time. This can only be achieved by deploying multiple video/radar/lidar/ultrasonic sensors in the car, which will generate much more data than in today's vehicles. Final data fusion will be done in centralised HPVC units. Therefore, the on-board communication network needs to ensure much higher data-rates and guarantee quality of service (QoS). New connectors, wiring harness solutions, as well as, communication chips and AD converters, are needed;
- On-board communication system and HPVC electronics need higher reliability and security/safety than currently available to protect human life in routine, and also difficult, traffic situations. This means that reliability and functional safety of AD electronic-systems must be increased substantially because the active human driver, who is constantly monitoring the driving behaviour of the car, will be replaced by a passive passenger, who leaves all control functions to the electronic system.

Societal, economic and environmental benefits

European society will massively benefit from AD technologies: reduced numbers of accidents and fatalities; better deployment of existing road infrastructure through harmonised and increased traffic flows; and a new quality in driving comfort and reduced fuel consumption and emissions. Europe will also benefit economically from the wealth generated by the continuing success of its automotive industry – in which it has a leading position and must be defended.

Engaging European industry

Fundamental changes have strong impact on the European automotive industry. European OEMs (or original equipment manufacturers, companies that produce parts and equipment that may be marketed by other manufacturers) need to be able to offer AD cars, so as not to lose their important market positions to America or Asia. Hence, European suppliers and OEMs need to firmly support and push towards new car IT architectures. Thanks to decades of experience and expertise in integrating electronic devices into vehicles, these newly centralised, standardised, safe secure HPVCs will be Europe-first creations.

According to MarketWatch's 2018 report, the global self-driving car market is expected to expand at a CAGR of 36.2%, leading to global revenue of US\$173.15 billion by 2023. By creating an HPVC demonstrator and an automotive-grade, in-car, high-speed network – the two key technologies required for AD cars – the HiPer project will enable European car manufacturers to offer new efficient mobility solutions, and enable the European automotive industry to stay at the leading edge of this worldwide market.



HiPer

HiPer creates High Performance Vehicle Computer and Communication System for Autonomous Driving

A project within the EUREKA PENTA programme

Paris, 31 October 2019 -HiPer, a project in the EUREKA PENTA Cluster and managed by industry association AENEAS, is building on Europe's leading position in automotive semiconductors (chips) to create electronics vital for the future of road travel. By creating an advanced High-Performance Vehicle Computer (HPVC) and Communication System, HiPer will fill a vital need for computer processors and electronic control units with the safety, performance, security and reliability necessary for real-world self-driving vehicles ('Autonomous Driving', also known as 'Level 5 automation').

The market for partially and fully autonomous vehicles is expected to rise from USD 42 billion in 2025 to nearly USD 77 billion in 2035¹, with the first virtually autonomous driving cars on sale by 2021. These vehicles will need to handle complex tasks such as vision processing, object recognition and interaction with intelligent traffic systems with complete reliability in real-time. However, electronic systems with the necessary processing power and speed of communication that can also withstand harsh vehicle conditions, such as heat and humidity, do not yet exist. HiPer intends to fill this gap through innovations in semiconductor design, manufacturing and packaging to create automotive grade solutions in three key areas: computation, communication and integration.

Among key innovations, HiPer will develop new cooling technologies for processors with a heat dissipation of 300 W and novel Automotive Ethernet technology to support high data rates, high data integrity and high-speed communication to systems outside the vehicle. The project will also work on new detectors and new chip packaging techniques to improve the thermo-mechanical reliability and functional safety of the HPVC in automotive environments, increasing operational lifetimes to 50,000 hours from today's 8,800 hours.

To achieve these goals, the HiPer consortium brings together industry, SME and research organisations from Belgium, Germany and the Netherlands, with expertise along the entire automotive value chain. Partners include Audi, a world leading premium car manufacturer; Robert Bosch GmbH, a leading global supplier of technology and services; and NXP, a leading manufacturer of high-performance IT platforms, vehicle electronics and communication solutions. The consortium aims to deliver market leading solutions for centralized, safe and secure HPVCs at affordable prices, based on architectures and concepts that can lead to new standards. These results will strengthen Europe's competitiveness and its ability to lead the world in the transition to electric vehicles and autonomous driving.

¹ www.bcg.com/de-de/industries/automotive/autonomous-vehicle-adoption-study.aspx





About the PENTA programme (managed by the AENEAS Industrial Association)

PENTA is a EUREKA cluster whose purpose is to catalyse research, development and innovation in areas of micro and nanoelectronics enabled systems and applications - where there is shared national and industrial interest. Based on the Electronic Components & Systems (ECS) Strategic Research Agenda (SRA) key areas and essential capabilities, PENTA programme contributes to the development of electronic solutions with the opportunity for rapid competitive exploitation and a strong impact on European societal challenges. The PENTA project team is supporting SMEs, large corporations, research organisations and universities by facilitating access to funding, fostering collaborative work and creating consortia.

PENTA is managed by AENEAS.
More on PENTA: <http://www.penta-eureka.eu>
More on AENEAS: <https://aeneas-office.org>

About HiPer

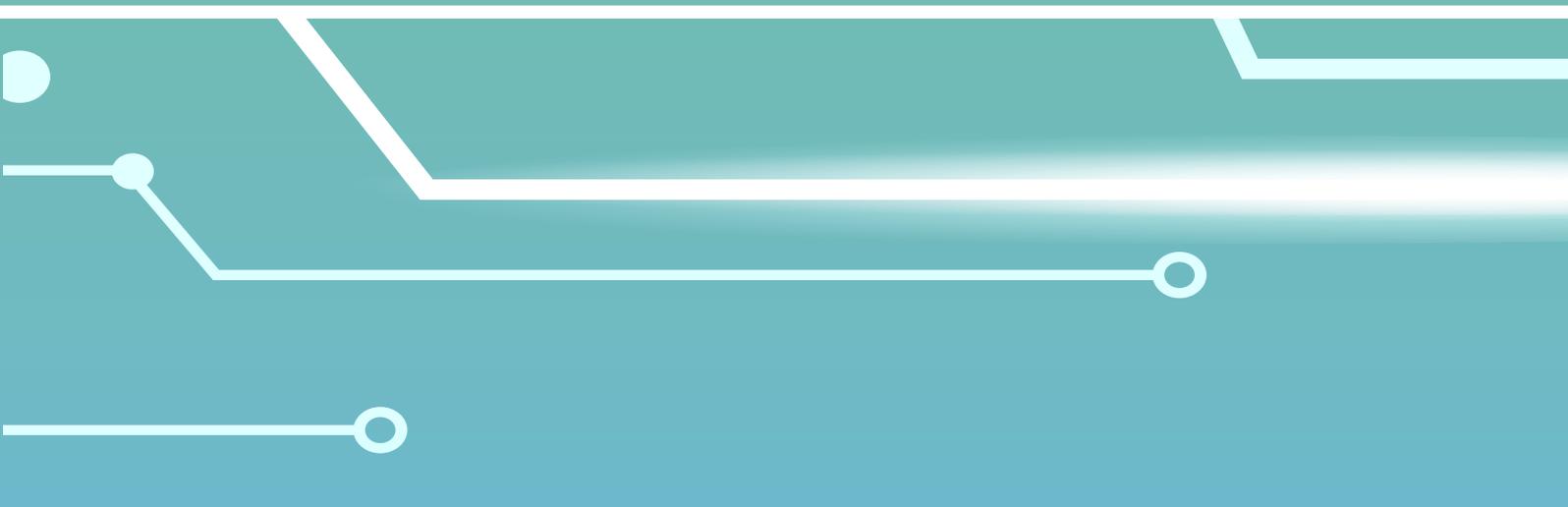


HiPer is a RD&I project consortium involving 17 partners from 3 countries. The project partners are: Robert Bosch GmbH (project leader), Advanced Packaging Center B.V., Audi AG, Boschman Technologies B.V., Technische Universität Chemnitz, Chemnitzer Werkstoffmechanik, Technische Universiteit Delft, Dynardo GmbH, Technische Universiteit Eindhoven, FastTree3D, Fraunhofer Institut für Elektronik und Nanosysteme, Glück Industrie-Elektronik GmbH, imec, Interflux Electronics, Materialise, NXP Semiconductors Netherlands B.V., NXP Semiconductors Germany GmbH.

National funding support is provided by Belgium, Germany and the Netherlands.



SunRISE





17004



AI and privacy-enhancing -technologies to enhance internet interoperability, resiliency and security for business and industry [SunRISE]

The SunRISE project will implement a comprehensive security solution, concentrating on aspects and issues critical to future systems related to the internet of things (IoT). Advanced digital technologies, such as artificial intelligence (AI), machine learning and privacy-enhancing technologies (PETs), together with security-data sharing, will be deployed to implement such system-security features as intrusion and anomaly-detection.

In recent years, the internet of things (IoT) revolution has been transforming our world, as we move towards one where everything is interconnected, everything is smart, and everything is – or should be – secure. Sensors, actuators, processors, networks and radios are crucial in building smart connected-devices enabling real-time sensing, contextual understanding, environment manipulation, and communication. Today, 2.9 billion people are online, 40% of the world's population. And by 2020 we expect about 50 billion devices to be connected.

While delivering clear benefits, these devices also increase the risk of data manipulation, data theft and cyberattacks. In 2015, European enterprises had at least a one-in-five chance of losing data through a targeted cyberattack. There is a severe risk that the European economy is falling behind in exploiting opportunities in emerging IoT markets. The lack of trust by businesses and consumers in smart connected-devices is a clear barrier to growth and jobs. At this point, it is no longer sufficient to provide ad hoc 'semiconductor' responses to these issues. Essentially, we need well-structured, interoperable and resilient secure solutions and systems.

AI and machine learning crucial to comprehensive IoT security

The SunRISE project will deal with one of the major challenges for the digital industry, namely IoT security. To obtain a comprehensive security solution, this project will address the following critical aspects in future IoT systems:

- Design of intrusion and anomaly-detection: by using machine learning (and the latest results) on IoT edge nodes;
- Sharing of security intelligence data (from IoT nodes to cloud back-ends): by creating a community with reference structures. Based on the larger dataset, machine learning can be accelerated and overall system security increased. This should result in security turning into a shared

responsibility, interest and effort, but also into improved efficiency, cost and resource usage;

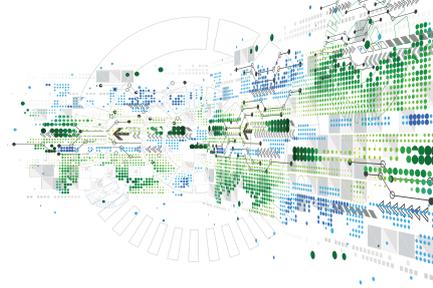
- Lack of trust by fearing the loss of confidential data: can be overcome by using privacy-enhancing technologies (PETs), like homomorphic encryption and secure multi-party computation (MPC);
- Efficient and cost-effective introduction of PET: by designing and manufacturing hardware which supports and accelerates AI specific to IoT end-nodes.

SunRISE activities will result in the following deliverables:

- A reference cloud-based platform for sharing security intelligence;
- Novel homomorphic encryption hardware accelerators and secure multi-party computation PET technologies;
- Efficient hardware for PET technologies and machine learning;
- A reference platform for secure IoT device identity and life-cycle management;
- Highly secure and cost-efficient root-of-trust hardware for IoT devices.

Crucially, this project will be guided by PENTA's three key objectives:

1. To reinforce existing strengths in Europe: SunRISE will use existing European expertise and experience in AI and machine learning to monitor the security of IoT devices and detect anomalies, thus preventing attacks or further shortcomings. The project will also develop tools capable of fixing detected errors and/or bringing the entire IoT system operation into a safe mode;
2. To close gaps across the European value-chain: To meet the high technological risk posed by this project's approach, SunRISE brings together experienced partners from three countries, all experts in their specific field.



KEY APPLICATION AREAS

-  Health & Well-Being
-  Digital Industry

ESSENTIAL CAPABILITIES

-  Connectivity & Interoperability
-  Safety, Security & Reliability
-  Computing & Storage

PARTNERS

Ancud IT Beratung GmbH
 AnyWi Technologies
 Cloud&Heat Technologies GmbH
 Delft University of Technology
 Eindhoven University of Technology
 ENGIE – Laborelec
 Fraunhofer IIS/EAS
 NXP Semiconductors Belgium NV
 NXP Semiconductors Germany GmbH
 Philips Electronics Nederland B.V
 Philips Medical Systems
 Sandgrain
 SIRRIS HET COLLECTIEF CENTRUM VAN DE
 TECHNOLOGISCHE INDUSTRIE
 Stichting IMEC Nederland
 Technical University of Munich
 Technolution BV
 University of Ulm

COUNTRIES INVOLVED

-  Belgium
-  Germany
-  Netherlands

PROJECT LEADER

Christopher Nigischer
 NXP Semiconductors GmbH

KEY PROJECT DATES

August 01, 2019 to July 31, 2022

The innovation strength for novel solutions will be enhanced by the cooperation between application owners (like smart grids, industry, eHealth) and leading-edge providers (of secure IC and sensors, security, AI/ machine learning);

3. To identify and develop new European market-leadership opportunities: SunRISE's use of disruptive security-oriented technologies (such as homomorphic encryption, lithography, AI and machine learning) in IoT-related domains (like intrusion-detection mechanisms) will improve European strengths. These technologies, together with the project's disruptive approach to business and markets, will also help the micro and nanoelectronics industry and associated sectors create and support future European champions.

The project will be executed by partners from the entire market value-chain. Significantly, they will offer a balanced effort between industry and academia, working towards a shared, integrated security-solution by contributing in such essential areas as security technology and related tools; secure IC and sensor component-building; and IoT systems.

Spreading the news

Effective dissemination, vital in ensuring results are well-tailored to various target-groups, will take place throughout the duration of the project. SunRISE will undertake a series of dissemination initiatives to ensure the sustainability of deployment actions. These will include organising special sessions at major European and international events to maximise the impact and reach the community at large. Project partners will publish in the most representative journals and participate in important conferences. And thanks to the interdisciplinary nature of the project, they will also ensure that they cross the different research domains and communities. In addition, white papers, workshops and presentations will be used to communicate results and findings – including those from participating PhD and Master's candidates – to other relevant industry, scientific and academic players and communities.

A thriving IoT

Gartner Inc. predicted in 2017 that 8.4 billion connected things will be in use worldwide in 2017 and this number will be increase to 20.4 billion by 2020. Based on this forecast, the total spending on endpoints and services could reach almost US\$2 trillion in 2017. Regionally, Greater China, North America and Western Europe are the main drivers of connected things and these three regions are predicted to represent 67% of the total IoT in 2017.

Global investments in IoT security was estimated at US\$703m for 2017 and is predicted to grow at a CAR (compound annual rate) of 44% to a US\$4.4 billion by 2023. These forecasts are based on IoT-security-relevant revenue of major technology companies across 12 industries and 21 technologies.

Importantly, McKinsey & Company reported in 2017 that IoT lacks well-established, overarching standards that describe how the different parts of the technology stack should interact. In other words, there is no standard approach for ensuring the security of critical IoT applications and large players and industry organisations all use their individual approaches. Some segments, such as industrial, still use a small set of proprietary, incompatible technology standards originating from major players. In other segments, such as automotive or smart buildings, standards for interoperable devices are very rudimentary, leading to high security risks and costs.

These are typical issues SunRISE is already anticipating. The best way of ensuring various international standards are implemented is through regular contacts with such regulatory, standards and certification organisations as ECSO, Eurosmart, AIOTI and ENISA.

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Penta (E! 9911), is EUREKA Cluster whose purpose is to catalyse research, development and innovation in areas of micro and nanoelectronics enabled systems and applications.





SunRISE

SunRISE project develops new approach to IoT security based on machine learning and trusted data sharing

A project within the EUREKA PENTA programme

Paris, 12 November 2019 - SunRISE, a project in the EUREKA PENTA Cluster and managed by industry association AENEAS, aims to transform Internet of Things (IoT) security through machine learning and data sharing. Existing IoT security is limited by proprietary solutions and standards, and an unwillingness of companies to share sensitive data related to security incidents. In contrast, SunRISE's platform approach is based on privacy enhancing technologies (PETs) that create trust in data sharing. As a result, vast amounts of data on security incidents will be available for machine learning, with the analysis feeding into a complete security chain. Innovative technologies and reference platforms will establish trusted identities and end-to-end security for IoT devices. They will securely manage devices over their entire lifetime, enable data sharing to detect anomalous behaviour and network intrusions, and recover devices to a secure state once a security issue has been detected.

The innovations delivered by SunRISE will have major importance as IoT systems are increasingly used in critical economic and social domains including Industry 4.0, automotive, energy and healthcare. By 2025, the annual economic impact of IoT is expected to be between USD 4 trillion and USD 11.0 trillion worldwide¹. However, this interconnectedness brings risks of data manipulation, data theft and cyberattack. For instance, in 2015, European enterprises had at least a 1 in 5 chance of losing data through a targeted cyberattack. Such attacks pose financial and reputational threats; they may endanger privacy and even human lives.

SunRISE is addressing fundamental technical challenges to tackle these security issues. Firstly, it will implement machine learning and security incident management on edge nodes (i.e. where IoT devices connect to the cloud, not in the cloud). This ensures that decisions on how to handle incidents can be made in real-time – essential for time critical applications such as autonomous driving. Secondly, it will develop PETs, particularly homomorphic encryption (a new technique that ensures no data needs to be shared in plain text), so companies feel confident to share security incident related data on a cloud-platform. This is a vital step in allowing the benefits of machine learning to be applied to evolving IoT security risks. Thirdly, SunRISE will develop new manufacturing technologies for low-cost, high-volume, secure ASICs (dedicated semiconductor chips) both for machine learning acceleration and for unique identification of individual devices.

¹ <https://www.mckinsey.com/industries/semiconductors/our-insights/whats-new-with-the-internet-of-things-of-May-2017>





The SunRISE consortium comprises 17 industry-leading partners including large enterprises, SMEs, and 6 academic and research institutions. It will also engage with standards bodies and application owners in fields such as smart grids, industry and eHealth, as well as with leading providers of secure ICs and sensors, security, and AI and machine learning technologies. The resulting technologies, guidelines and hardware for IoT security and privacy, will allow Europe to reinforce and expand its leading market position in cybersecurity solutions.

About the PENTA programme (managed by the AENEAS Industrial Association)

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PENTA is managed by AENEAS.

More on PENTA: <http://www.penta-eureka.eu>

More on AENEAS: <https://aeneas-office.org>

About SunRISE

SunRISE is a RD&I project consortium involving 17 partners from 3 countries. The project partners are: NXP Semiconductors Germany GmbH (project leader), Ancud IT Beratung GmbH, AnyWi Technologies, Cloud&Heat Technologies GmbH, Delft University of Technology, Eindhoven University of Technology, ENGIE – Laborelec, Fraunhofer IIS/EAS, Sandgrain, NXP Semiconductors Belgium NV, Philips Electronics Nederland B.V, Philips Medical Systems, SIRRIS HET COLLECTIEF CENTRUM VAN DE TECHNOLOGISCHE INDUSTRIE, Stichting IMEC Nederland, Technical University of Munich, Technolution BV and University of Ulm.

National funding support is provided by Belgium, Germany and The Netherlands.



XSR-FMC





17013



Developing a secure, reliable and ultra-low power flash-memory controller for key industrial users

[XSR-FMC]

The 'eXtra'-Low Power, Secure and Reliable Flash-Memory Controller (XSR-FMC) project will focus on developing secure memory storage with high reliability and ultra-low power consumption. These are key requirements of demanding automotive, Industrial Internet of Things (IIoT) and Industry 4.0 markets.

Electronic devices require an increasing amount of storage as distributed intelligence spreads. These storage devices control sensitive and vulnerable social investments and infrastructure, making security an increasing concern as these devices become exposed to failure and hacking. Unfortunately, emerging Industrial Internet of Things (IIoT), Industry 4.0 (part of the fourth industrial revolution which deploys digital technologies to produce higher-quality goods at reduced costs), automotive and many other sensitive applications and industries are using storage that has not been designed with proper security.

Aside from implementing security features as proposed by the European Union Agency for Cybersecurity (ENISA), it is also essential to provide the highest reliability to protect related investments, as well as, ultra-low power consumption to promote sustainability. Different aspects of computing demand different solutions pertaining to bandwidth and memory-system capacity, regardless of the type of computing, such as local, cloud or fog (extending cloud computing to the edge of a network).

NAND flash memory system requirements for automotive, IIoT and Industry 4.0 are positioned between the industrial market (high reliability) and the consumer market (low cost, high volume), with both markets offering attractive opportunities. Crucially, however, neither has the necessary eco-system for these new markets, an essential ingredient XSR-FMC intends to develop.

Eco-system to create the right flash-memory controller

The XSR-FMC project will address the shortcomings of current flash memory controllers for two key highly demanding markets: IIoT and Industry 4.0. In particular, its goal is to build an eco-system to create, for those markets, flash memory controllers that offer: ultra-low power consumption; high reliability; and certifiable security for generations of flash memory to come. This will mean putting in place a development platform to build an eco-system to develop any kind of flash-memory controller. Crucially, the project consortium

will deliver the necessary project expertise and experience.

As performance requirements increase, the high-speed, serial computer expansion bus standard called Peripheral Component Interconnect Express (PCIe) has constantly evolved and the PCIe gen4 standard is expected to strike the right balance between power and performance, alongside Non-volatile Memory Express (NVMe), a protocol designed to take full benefit of flash memories.

The technology used in flash-memory controllers are driven, on the one hand, by the evolutions of NAND flash technology and their new requirements of error-correction coding, interface and flash-management features; and on the other hand, by the type of demand for memory systems.

Key requirements of the target markets (as defined in this project) are summarised as follows:

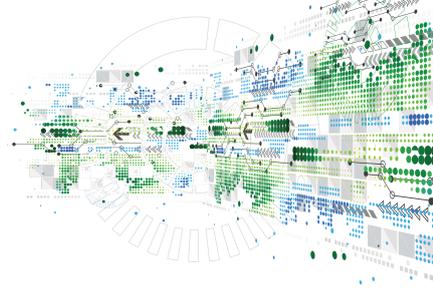
- High reliability across large ambient temperature range (most likely -40°C to +105°C);
- Extended lifetime;
- Resilience to sudden power failures;
- Ultra-low power;
- Fast interfaces;
- High security;
- Industrial/Automotive packaging grade;
- Diagnostic and support eco-system.

XSR-FMC will develop a demonstrator to ensure a rapid product ramp-up and time-to-market, and hence a better return on investment (ROI). The choice of interface will most likely be PCIe, but this can be revised, based on market changes. Notably, this interface will be flexible enough to adapt to, making only the host interface subject to change (although unlikely).

Added-value consortium

In order to offer a full NAND flash-memory system, the controller and memory must work symbiotically, which needs a very strong eco-system and relationship with flash suppliers. And the only way for Europe to





KEY APPLICATION AREAS

-  Computing and Storage
-  Security and Reliability
-  Digital Industry ECS Process
-  Transport and Smart Mobility
-  Equipment, Materials and Manufacturing Safety

ESSENTIAL CAPABILITIES

-  Systems and Components Architecture, Design & Integration
-  Connectivity & Interoperability
-  Safety, Security & Reliability
-  Computing & Storage
-  ECS Process Technology, Equipment, Materials & Manufacturing

PARTNERS

Extoll / Fraunhofer-Institut für Zuverlässigkeit und Mikrointegration (IZM) / GLOBALFOUNDRIES Dresden Module One LLC & Co. KG / HTWG (Hochschule Technik, Wirtschaft und Gestaltung, Konstanz) / Hyperstone GmbH / Racyics GmbH / SILICONGATE LDA / TIEMPO

COUNTRIES INVOLVED

-  France
-  Germany
-  Portugal

PROJECT LEADER

Damien Col
Hyperstone GmbH

KEY PROJECT DATES

15 November 2019 to 15 November 2022

successfully address those three markets is to join forces and foster partnerships. One way of achieving this is through a European project consortium comprising R&D-focused SMEs, research institutes and large manufacturing facilities, all capable of providing an ecosystem, a semiconductor product and platform, as well as, innovative, globally competitive intellectual property (IP) building-blocks. Importantly, several of these can be re-used and exploited independently in other future semiconductor designs, making them relevant to the ecosystem since they enable developments in semiconductor processes.

Furthermore, fostering cooperation between organisations that invest largely in R&D to develop state-of-the-art technology in their respective domains of expertise ensures the marketability of such a product. The consortium will also develop a reference design and packaging guidelines for a system-in-package (SiP) storage module, and deliver the necessary expertise to build a successful supply chain.

There are direct benefits for the entire consortium. XSR-FMC will provide project partners opportunities to address additional markets and applications outside their normal fields of operation. And relationships developed in this project could also trigger new opportunities.

What's in it for Europe?

With any flash-memory controller, there is a trade-off between cost, performance and reliability. Traditional Asia-based controller vendors tend to target consumer markets, and are therefore not interested in niche ones. However, opportunities arising from these key markets, together with their expected volumes, will encourage Asian and American suppliers to enter them. Europe can counter these moves with a good product and by partnering with experts.

Furthermore, providing such a technology platform will enable Europe to address different challenges within automotive, IIoT and Industry 4.0 with respect its storage requirements, and also strengthen Europe's leadership in highly demanding markets. The constant evolution of host and memory interfaces, and major flash-technology shifts, justify such a technology platform

and partner ecosystem. Crucially, critical security elements, building blocks and developments will all be done in Europe, strengthening the overall European security infrastructure, especially related to data storage.

What's more, added-value features of reliability, ultra-low power and security, both for the chip, but also the value chain, will more than make up for the price of the controller, which Europe cannot compete on.

Promising markets

Such trends as IIoT and Industry 4.0 will diversely re-shape social life and professional collaboration: from enabling services for the elderly, to maximising efficiency of industrial processes. Importantly, secure storage is part of all electronic systems involved.

And with cars and sensitive infrastructure-equipment or machines connected to the internet, security, especially for data storage, is of extreme importance. Many semiconductor sectors will also benefit from the increase in electronics in vehicles. All of this is reflected in market statistics. According to LP Information, automotive, IIoT and industrial markets had a CAGR of 10.2% from 2015 to 2020, and the trend is predicted to continue. According to HIS Markit, semiconductor revenue in automotive is forecast at over US\$ 40 billion by 2022. And Statista predicts global enterprise IIoT spending within automotive will be US\$ 303.3 billion in 2020. Finally, the automotive supply chain is also evolving and increasing in entropy. This creates new opportunities for semiconductor companies, which in turn will promote partnerships upstream.



XSR-FMC

Extra-Low Power, Secure and Reliable Flash-Memory Controller for Automotive, Industry 4.0 and Internet of Things

A project within the EUREKA PENTA program



Paris, 1 September 2020 - Within the European PENTA project, XSR-FMC, a new flash memory controller platform will be developed that will improve flash memory storage systems' security, safety and reliability. Furthermore, these controllers will significantly reduce energy consumption, contributing to greater sustainability.

Flash memory is part of everyday life. Widely used, it stores data in music players, memory sticks, and SSD in consumer applications. Currently, only flash controllers specifically developed for niche applications can offer the features targeted by the XSR-FMC project. However, with flash memories increasingly used in automotive electronics, digitally controlled machines in factories (Industry 4.0) and Industrial IoT, demand is growing for higher quality controllers in many applications and markets.¹



Photo by courtesy of Hyperstone

In many consumer devices, the 'controller' simply manages how data is stored and retrieved, with few capabilities to deal with errors or data protection. But in a car's electronic network or an industrial machine, failures could lead to breakdowns or even endanger human life. When devices are connected to the internet, unprotected storage systems are at risk of attacks – from intrusions over data privacy to disruption of vital functions such as a car's electronic controls.

The XSR-FMC consortium includes design and manufacturing specialists in flash controllers, semiconductor design and security to address these complex requirements. The initial design will offer high reliability for an extended temperature range, long life-time, ultra-low power consumption, certifiable security, error correction and robustness to sudden power failures.

This European collaboration will expand Europe's commercial position in technology required for new generation of flash memories and strengthen its capabilities in secure data infrastructure and storage.

¹ According to LP Information, automotive, IIoT and industrial markets had a CAGR of 10.2% from 2015 to 2020, and the trend is predicted to continue. According to HIS Markit, semiconductor revenue in automotive is forecast at over US\$ 40 billion by 2022. Statista predicts global enterprise IIoT spending within automotive will be US\$ 303.3 billion in 2020.





About the PENTA program

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PENTA is operated by AENEAS.

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About XSR-FMC

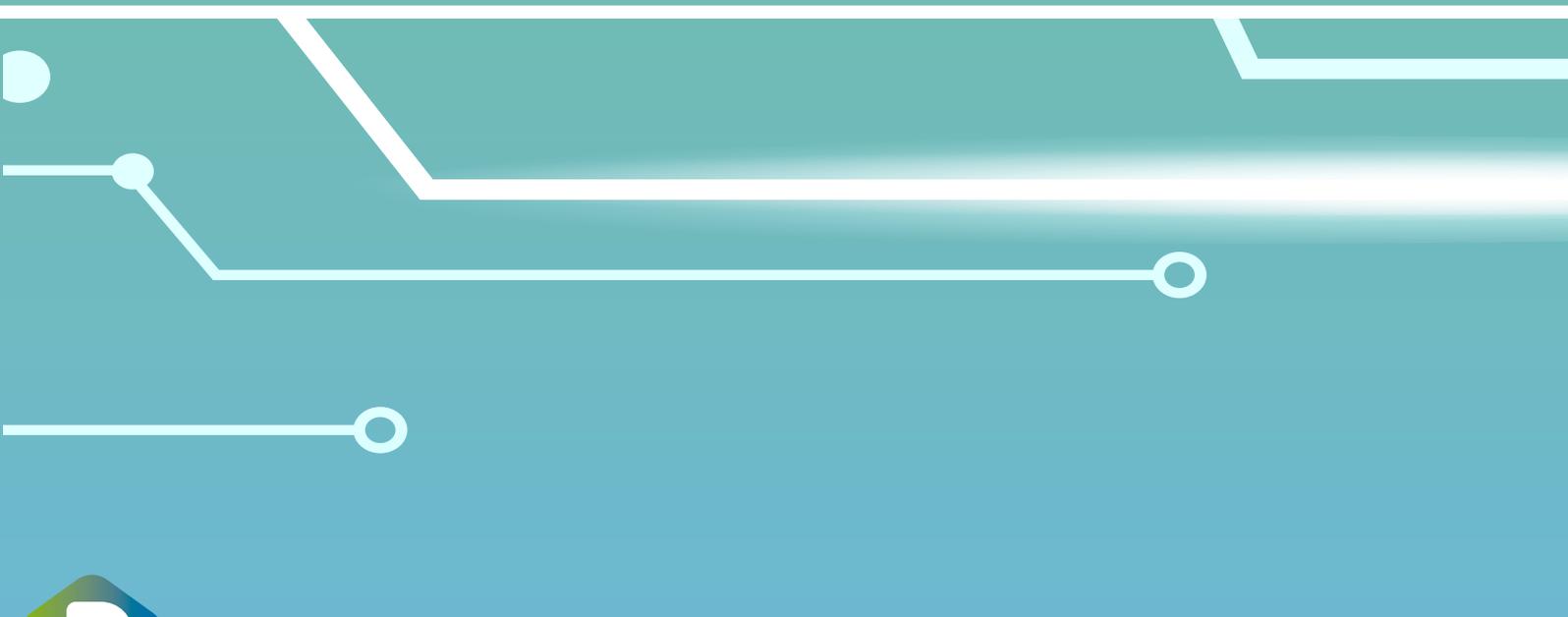
XSR-FMC is an RD&I project consortium involving 8 partners from 3 countries, France, Germany, and Portugal. The project partners are: Hyperstone (project coordinator), Extoll, Fraunhofer Institute for Reliability and Micro-integration (IZM), GLOBALFOUNDRIES Dresden Module One LLC & Co. KG, HTWG Konstanz - University of Applied Sciences, Racyics GmbH, SiliconGate LDA, and TIEMPO SAS.

More on XSR-FMC: <https://www.penta-eureka.eu/downloads/ProjectProfiles/penta-project-profile-xsr-fmc.pdf>





HEFPA





19011



Highly flexible and energy-efficient antennas can expand wireless comms market and attract smaller integrators and apps developers [HEFPA]

The 'Flexible Phase Array System for High Efficiency and Scalable Millimeter Wave Wireless Communications' (HEFPA) project is developing scalable unit array front-end components. These can be used as flexible building-blocks in implementing larger and more diverse antenna arrays in the upper bands of Frequency Range 2 (FR2), which includes frequency bands from 24.25 GHz to 52.6 GHz.

Thanks to the rapid growth in wireless-data traffic, millimetre wave (mmW) communications are set to become a major data conduit for fifth generation (5G) wireless communication systems. That said, mmW signals are highly susceptible to blocking and tend to have communication limitations owing to their poor signal attenuation compared to, say, microwave signals. This factor necessitates the usage of phased-array antenna systems to overcome signal-path loss.

Antenna configurations and array sizes (determined by the target applications) may vary from large arrays (such as 512 x 512 antenna elements) to small ones (such as 2 x 8 elements) that are more suited to mobile handsets and IoT (internet of things) devices. The phase relationship of the radio frequency (RF) signal between adjacent antenna elements enables steerable directivity of the radio signal, as compared to an omni or parabolic antenna (often used in fixed-link microwave and mm-W communications). In addition, electronic control of the signal phase and amplitude at each antenna in the array enables beam steering and network control of the signal power, along with the tracking of mobile-radio users.

These are some of the issues the HEFPA project is set to address and resolve.

Scalable and efficient building-block

The strategic objective of HEFPA is a highly flexible and energy-efficient RF front-end component that enables the creation of mmW transceiver systems. Under radio standards, such as 5G, mmW communications will rely on phased-array antennas that focus the RF signal in one or more directions in order to improve radio-link margin.

In particular, HEFPA will develop scalable unit-array front-end components intellectual property (IP) that can be used as a flexible building-block in the implementation of larger and more diverse antenna arrays. Embedded within each HEFPA module will

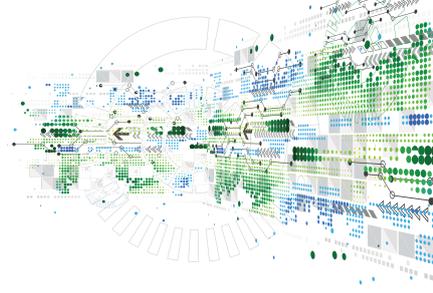
be highly efficient, mmW signal generation and conditioning power amplifiers, phase shifters, switching functions and low-noise amplifiers. In addition, new techniques to provide control, RF signal distribution, phase/time coherence and calibration among the unit elements, will be developed. These will ensure effective interaction between HEFPA components. Furthermore, the MIMO (multiple-input, multiple-output) order, link separation and the number of target users will be incorporated into a flexible scheme of analogue and digital communications between the respective HEFPA components.

Within a single HEFPA component, all the core RF functions for mmW (at 39GHz) radio signals are incorporated, including mmW signal-generation and conditioning, such as amplification, phase shifting and filtering, antenna elements and integrated circuit (IC) packaging. . More importantly, it can be placed into a cluster of other identical HEFPA components in order to create larger arrays. This modularity will enable mmW product-developers to quickly and flexibly build specific phased-array antenna configurations, as well as, hybrid combinations of phased arrays using MIMO technology by deploying a number of HEFPA modules.

The key innovations of HEFPA will be:

- A highly optimised and energy-efficient RF signal generation and amplification in a compact form factor. This will reduce energy consumption by 30% as compared to existing solutions in a multitude of radio links leveraging the mmW frequency bands;
- The implementation of a chip-on-board technology, which combines the technological advantages of conventional wafer-level-packaging approaches with the cost-efficiency and thermal-management capabilities of panel-level, printed-circuit-board fabrication (system-in-PCB);





KEY APPLICATION AREAS



Energy



Digital Industry

ESSENTIAL CAPABILITIES



Systems and Components:
Architecture, Design, and Automation



Connectivity and Interoperability



Process Technology, Equipment,
Materials and Manufacturing for
Electronic Components & Systems

PARTNERS

C-COM Satellite Systems Inc

Carleton University

Eindhoven University of Technology

NXP Semiconductors Netherlands BV

Semiconductor Ideas to the Market (ItoM) BV

Skyworks Solutions Canada Inc.

University of Waterloo

COUNTRIES INVOLVED



Canada



Netherlands

PROJECT LEADER

Estelle Holopherne & Dominique Defossez
NXP Semiconductors Netherlands BV

KEY PROJECT DATES

01 July 2020 to 30 June 2023

- System and digital integration of an arbitrary number of HEFPA components, working cooperatively to form the mmW beam(s).

There will be two main project deliverables:

- Pre-commercial prototypes of the HEFPA components, comprising all the integrated RF syntheses and front-end signal circuits, heat sinking-elements and integrated antennas;
- A system demonstration board with flexible MIMO order-forming and/or beam-forming capability, along with beam steering (+/- 45 degrees in azimuth and elevation). It will use project-developed hardware and software overlays, which enable HEFPA components to work collaboratively.

Notable project resources

The HEFPA project consortium will leverage its partners' strengths in use-case definition, IC design, packaging and system engineering in order to implement the core HEFPA building-block. Their expertise will also be used in deploying the antenna elements in various phased-array and hybrid-beam-forming configurations.

Technology drives business and markets

HEFPA will deliver a competitive advantage by combining several key component-innovations into a single RF front-end. Furthermore, this fully integrated assembly will also combine an innovative design with the best attributes of IC and low-loss packaging and thermal management to offer an additional advantage over other approaches.

Target markets will be very broad in the sense that any use-case, which is going to be reliant upon high-bandwidth and large data-throughput wireless communications, will benefit from being able to deploy HEFPA components in building phased arrays. Commercial impacts are primarily time-to-market, flexibility (including reuse of supporting infrastructure) and low energy consumption.

Significantly, the HEFPA IP and components will also reduce complexity in the formation and deployment of mmW radio-links, thereby expanding the market reach of data communications using this allocated band of RF spectrum. This will enable smaller system integrators and RF application developers to use HEFPA components to quickly build flexible phased-array antennas (with all the associated RF generation and signal-conditioning circuitry) using the upper band of FR2 frequency-bands (as allocated in each regional jurisdiction). New applications that will leverage high-bandwidth wireless communications will also be made possible through HEFPA components.

Finally, regarding future market numbers, we see that existing mmW base-station and point-to-point systems have unit deployments of, perhaps, several 100,000 systems per year. In contrast, consumer-grade cellular or WiFi systems have a market size of over one billion radio systems per year. It is anticipated that mmW-based radio handsets, for example, will be over 100m units per year by 2022. Even larger markets are anticipated for VR/AR (virtual reality/ augmented reality) systems, which leverage mmW radio systems for very-high-bandwidth data applications.

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Penta (E! 9911), is EUREKA Cluster whose purpose is to catalyse research, development and innovation in areas of micro and nanoelectronics enabled systems and applications.





HEFPA

HEFPA project to exploit full potential of 5G network with an energy efficient antenna solution

A project within the EUREKA PENTA program

Paris, 8 October 2020 - HEFPA (Highly Efficient and Flexible Phase Arrays), a project within the PENTA program, is developing IP and components that will reduce the complexity of building 'phased array antennas'. These are the electronic components required to receive and transmit radio waves in Satcom and 5G mmWave (millimeter Wave) mobile and infrastructure devices. In addition, the HEFPA components will boost energy efficiency, reducing consumption by 30% compared to existing solutions.

Think of downloading a full-length movie onto your phone in seconds or of a specialist surgeon using robotic arms to carry out a life-saving operation on a patient in another remote city by leveraging satellite communications. 5G (fifth generation) telecommunications and Satcom systems that will leverage the mmWave portion of the spectrum promises to turn such scenarios into reality. Industries and consumers will benefit from applications and services enabled by the Internet of Things (IoT), Artificial Intelligence (AI), Virtual and Augmented Reality (VR & AR) – from more energy-efficient manufacturing to personalized medicine, truly immersive entertainment, self-driving cars and more.

5G services currently being rolled out in Europe and elsewhere are based on updated 4G systems. In addition, a host of Low-Earth Orbit Satellite constellations are now in deployment that will leverage ubiquitous coverage between the north and south poles. However, the biggest gains will come from the introduction of new mmWave technologies, which use radio waves of much higher frequencies and shorter wavelengths. These technologies are the real key to improved network capacity, faster downloads (anywhere from 10 to 100 times) and reductions of up to 10-fold in 'latency' (i.e. the time to respond to an instruction or a command). Moreover, mmWave will leverage highly directional signal that can be steered to track moving objects with much reduced signal interference compared to sub-6 GHz frequency bands.

However, mmWave presents challenges. The RF signals experience higher path loss as they travel and are easily blocked by buildings, people and objects. New antenna technologies with 'beam forming' which focus signals in the direction of the intended user can overcome these limitations and deliver the full potential of 5G and Satcom applications. The HEFPA project aims to provide system integrators and product developers with a quick and flexible way to build such phased array antennas – with the further benefit of increased energy efficiency.





Bringing together an ecosystem of partners with experience in RF ICs (radio frequency chips), RF systems, chip packaging and PCBs (printed circuit boards), HEFPA will develop its modules for use in consumer user equipment. Current consumer grade mobile and WiFi markets account for over a billion radio systems a year, and mmW enablement in various RF communications subsystems is expected to reach 100 M units per year in 2022. An even larger market is anticipated for VR/AR systems that leverage mmW technology. Thus, HEFPA has major commercial potential, as well as playing its part in Europe's ambition to be a global leader in leveraging mmWaves as a strategic technology for the digital economy and society.

About the PENTA program

PENTA is a EUREKA cluster whose purpose is to catalyze research, development and innovation in areas of micro and nanoelectronics enabled systems and applications - where there is shared national and industrial interest. Based on the Electronic Components & Systems (ECS) Strategic Research Agenda (SRA) key areas and essential capabilities, PENTA program contributes to the development of electronic solutions with the opportunity for rapid competitive exploitation and a strong impact on European societal challenges. The PENTA project team is supporting SMEs, large corporations, research organizations and universities by facilitating access to funding, fostering collaborative work and creating consortia.

PENTA is operated by AENEAS.

More on PENTA: <http://www.penta-eureka.eu>

More on AENEAS: <https://aeneas-office.org>

About HEFPA

HEFPA is an RD&I project consortium involving 8 partners from 2 countries, Canada, and the Netherlands. The project partners are: NXP Semiconductors Netherlands BV (project coordinator), C-COM Satellite Systems Inc , Carleton University, Eindhoven University of Technology , Semiconductor Ideas to the Market (ItoM) BV, Skyworks Solutions Canada Inc., University of Waterloo.

More on HEFPA: <https://penta-eureka.eu/project-overview/penta-call-4/hefpa/>



GaNEXT





19009



Intelligent power module will increase efficiency, reliability and compactness of power systems [GaNext]

The Next Generation GaN Power Module project (GaNext) aims at removing the barriers to adopting Gallium Nitride (GaN) semiconductors and fully demonstrating the higher efficiency and compactness of GaN-based power systems. The main project deliverable will be an intelligent GaN power module where the gate drive, control and protection circuits are integrated or co-packaged with the power device.

Gallium Nitride (GaN) transistors are wide-bandgap compound semiconductor devices that enable compact power electronic systems with efficiencies and power densities that are impossible with today's silicon (Si) devices. This is due to the lower on-state resistance, shorter switching times and drastically reduced switching losses of GaN compared to today's silicon-based devices. These features enable much higher operation frequencies up to the MHz range. A higher frequency directly translates into smaller passive components, such as inductors and capacitors. And this leads to much smaller power electronic systems.

Furthermore, reductions in size and costs are achieved because the cooling system can be shrunk dramatically, due to the reduced losses and improved efficiency. Cooling solutions that today consist of a large heatsink and fans can be changed to a small heatsink with convective cooling only. This reduction in size and weight are particularly beneficial for many portable and mobile solutions, such as electric vehicles (EVs) or on-board chargers.

However, there is a downside to deploying GaN. Current state-of-the-art GaN devices have certain characteristics, such as the low gate-threshold voltage, as well as, electromagnetic interference (EMI) and oscillations caused by the fast switching that make them challenging to use. This is one of the main reasons these GaN devices do not have a larger market share yet, and the innovations from GaNext aim to solve these drawbacks.

Towards next-generation GaN power systems

The aim of GaNext is to remove the barriers to adoption for GaN, and to fully demonstrate the higher efficiency and compactness of GaN-based systems in a range of power systems. The heart of the project is the development of an intelligent

GaN power module where the drive, control and protection circuits are integrated or co-packaged with the power device.

The proposed integrated power module will fundamentally improve the key issues with today's GaN-based circuits. Firstly, end-users currently lose part of the advantages of GaN since it is required to slow down the switching speed to avoid high-frequency oscillations. However, these oscillations can be drastically reduced by integrating part of the passive components into the module and the reducing EMI at the origin.

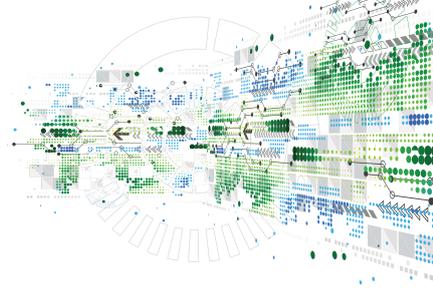
Secondly, the tailored design of the GaNext gate driver and the intimate integration in addition to the integration of auxiliary devices on the GaN integrated circuit (IC) will minimise any gate voltage distortions, which currently are a source of unreliable switching of the transistors. Furthermore, the full potential of GaN is unlocked by the added high-speed control IC with sophisticated safety features, in addition to an advanced heat-extraction technique.

Finally, integrating current and temperature sensors directly in the power module will significantly enlarge the safe operating area of the system. This multifaceted overall solution will position the GaNext module at the centre of next-generation GaN power systems.

All this will be achieved through the following:

- A GaN-on-Si power IC (650V) with integrated sensing and driving elements;
- Si and GaN low-voltage logic, control and level-shift silicon-on-insulator (SOI) gate drive circuitry;
- A dedicated package for the power module that will include the (GaN) power, control, and drive circuitry;





KEY APPLICATION AREAS

-  Energy
-  Transport and Smart Mobility
-  ECS Process Technology, Equipment, Materials & Manufacturing

ESSENTIAL CAPABILITIES

-  Systems and Components Architecture, Design & Integration
-  Connectivity & Interoperability
-  Safety, Security & Reliability
-  Computing & Storage
-  ECS Process Technology, Equipment, Materials & Manufacturing

PARTNERS

advlCo microelectronics GmbH
 Besi Netherlands B.V.
 Cambridge GaN Devices Ltd
 CSA Catapult
 Eindhoven University of Technology
 Fraunhofer IMS
 Infineon Technologies AG
 Lyra Electronics Ltd
 MACCON Elektroniksysteme GmbH
 Neways Technologies B.V.
 SUMIDA Components & Modules GmbH
 Signify B.V.
 TU Dortmund

COUNTRIES INVOLVED

-  Germany
-  Netherlands
-  United Kingdom

PROJECT LEADER

Cerdin Lee and Martin Arnold
 Cambridge GaN Devices Ltd

KEY PROJECT DATES

01 February 2020 to 31 December 2022

- Demonstrating competitive advantage of the power module in power systems, such as EV charger, lighting, motor drive and PV inverter applications; featuring optimised magnetic components.

Well-suited project consortium

The project consortium will cover the entire technology chain required for developing the intelligent GaN power module. A deep synergistic and interdisciplinary approach is indeed key to achieving the GaNext objectives, and the consortium has been carefully assembled to satisfy this need. Its experience and expertise cover a large part of the power electronics and power devices market value-chain: from semiconductor device design to sales of power conversion systems. Crucially, it includes such areas as: semiconductor chips and devices; semiconductor packaging and integration; magnetic components (such as inductors and transformers, key components for any power electronic system); and power electronic systems and products.

Green issues and other market drivers

The market for GaNext-related products can be divided into the following sub-segments:

- GaN power devices and GaN power modules;
- Gate driver and control-IC;
- Packaging;
- Magnetics;
- Power electronics (which is further divided into the specific market segments addressed in GaNext).

Now, every electronic or electrical device today contains at least one power electronic system. Crucially, GaN technology has the potential to improve the energy efficiency of the largest part of these systems. This

means that the GaNext project will help to reduce greenhouse gas emissions and energy consumption in Europe and beyond. Significantly, demonstrating this intelligent technology would be a breakthrough that will strongly support the clean-growth mission and electrification revolution that has started worldwide.

Environmental policy and regulations will further drive this market. Regulations set by Energy Star – an initiative of the U.S. Environmental Protection Agency and U.S. Department of Energy – that have also been adopted by the EU and Japan, are imposing higher energy efficiencies and therefore promoting GaN technology. Several governments have also announced ambitious targets for EV uptake in the next ten years, including the UK, Norway and Denmark. In addition, EV and the associated charging infrastructure are predicted to be strong drivers of GaN technology. Furthermore, the new JEDEC standard JC-70.1 on GaN devices will provide universal standards, another significant step forward in the adoption of GaN technologies.

This means that the overall power-electronics market this technology will address looks promising at over US\$200 billion. More specifically, the GaN power-devices market, which is growing at an impressive CAGR of 91%, is expected to reach US\$500m by 2022 with power supplies for EV and photovoltaic inverters sharing 60% of this market.

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GaNEXT

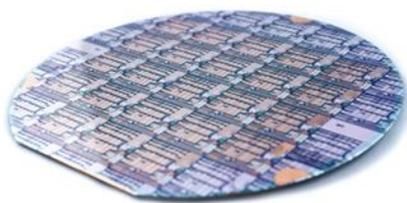
Intelligent GaN power modules to save energy and CO₂ in transport and industry

A project within the EUREKA PENTA programme

Paris, 17 July 2020 – A EUREKA PENTA project, GaNext, will have a major impact on global efforts to save energy and cut CO₂ emissions by creating highly efficient, compact and reliable GaN power modules for power systems. Today, every electronic or electrical device contains at least one power system – for instance, to convert mains AC electricity to DC current to drive a motor. From laptops to industrial machines, power systems are everywhere. The partners in GaNext aim to deliver a technology breakthrough by developing a next generation of intelligent ‘power modules’ (electronic components in power systems) based on a semiconductor called gallium nitride (GaN). These will significantly increase energy efficiency over existing modules most of which are based on silicon.

As a result, the GaNext project will strongly support worldwide moves towards energy efficiency and electrification. Suited to a wide range of applications, especially in transport and industry, the new modules will provide ways to meet stringent energy efficiency regulations. They will also be crucial for electric vehicles and charging infrastructures, which countries such as Norway and the UK are promoting through ambitious legislation.

GaN technology is not new, but GaNext is working to unlock its full potential by bringing together the expertise of companies, large and small, from across the entire power module technology chain.



Current GaN transistors can operate at much higher switching frequency with lower losses and lower on-resistance than state-of-the-art silicon devices. In other words, they can deliver higher performance with lower energy usage. But they cause interference with other components in the power system and can be unreliable. By eliminating these obstacles, GaNext will enable modules with increased energy efficiency that will be easy to build into power systems.

As electrification advances worldwide, demand for such solutions is high. The GaN power-devices market is growing at a CAGR of 91% and is expected to reach US\$ 500 million by 2022, with power supplies for electric vehicles and photovoltaic inverters sharing 60% of this market. Thus, the GaNext project will both make an important contribution to a low-carbon future and offer major commercial opportunities for European industry.



About the PENTA programme

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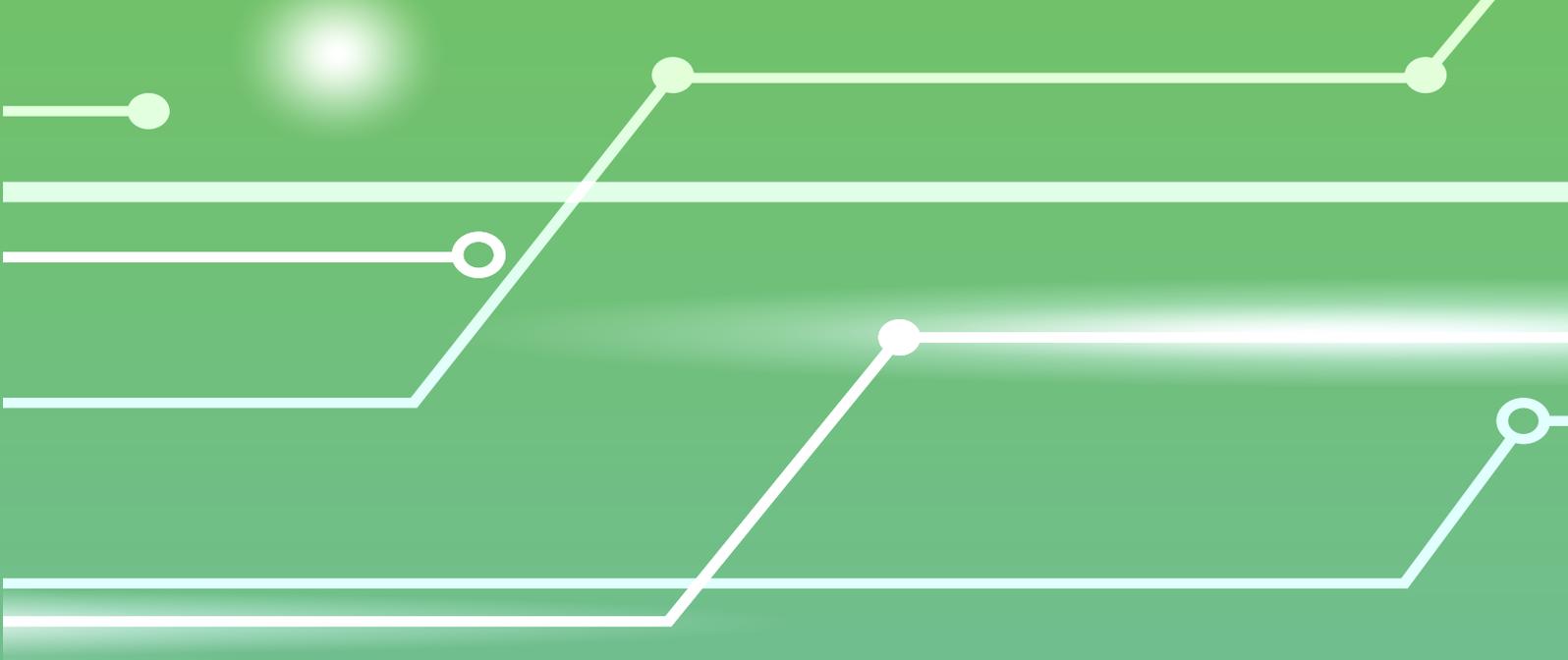
More on AENEAS: <https://aeneas-office.org>

About GaNext Project

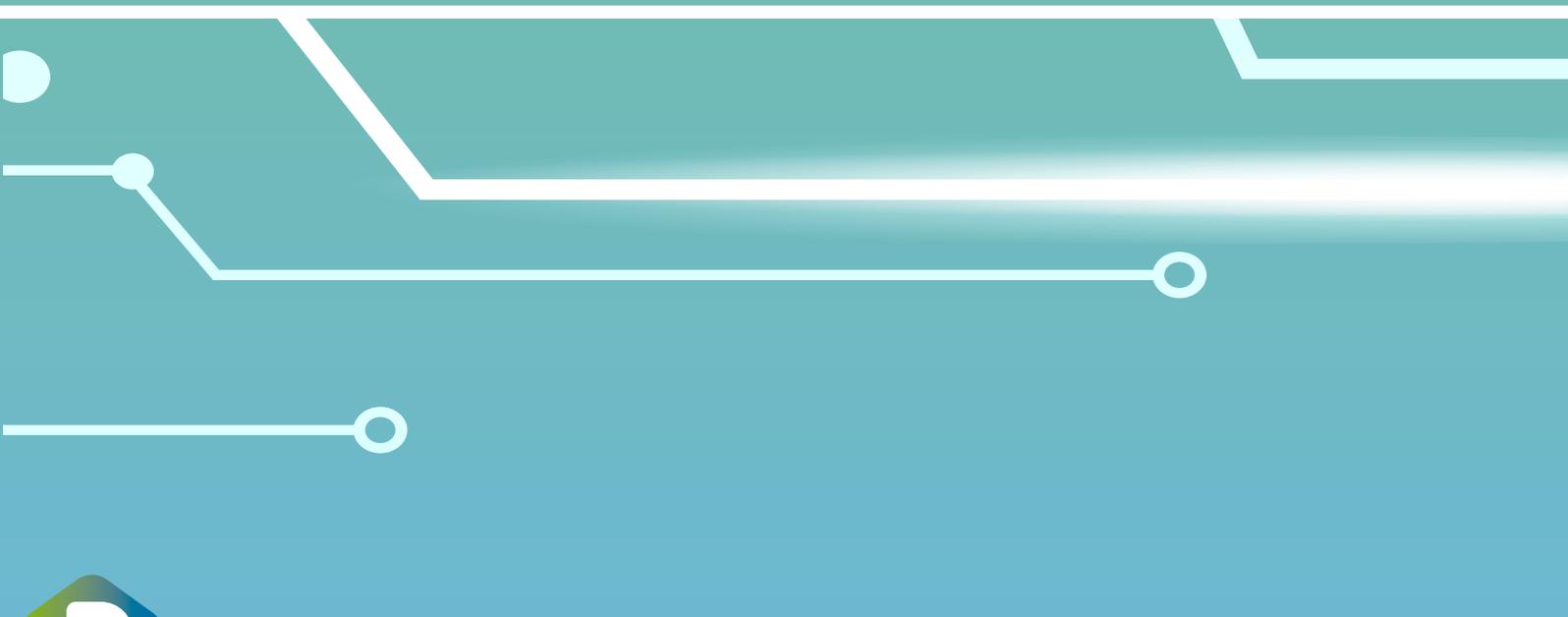
GaNext

GaNext is a RD&I project consortium involving 13 partners from 3 countries, Germany, Netherlands, and United Kingdom. The project partners are: Cambridge GaN Devices Ltd (project leader), advlCo microelectronics GmbH, BESI Netherlands B.V., CSA Catapult, Eindhoven University of Technology, Fraunhofer IMS, Infineon Technologies AG, Lyra Electronics Ltd, MACCON Elektroniksysteme GmbH, Neways Technologies B.V., SUMIDA Components & Modules GmbH, Signify B.V., TU Dortmund University.





Sentinel





19017



Frequent biomarker monitoring by an autonomous wearable patch as practical tool for clinicians and nurses to improve early warning. Reducing critical complications, improving patient care and quality of life [Sentinel]

Hospitals lack an essential facility to monitor – in a semi-continuous fashion – biomarkers, in combination with physiological and contextual ones, without causing a major disruption to a hospital's workflow. Responding to this problem, the Sentinel project will significantly improve the hospital's early warning system (EWS) targeting a reduction of serious complications and disabilities after their discharge.

According to the National Institute for Health and Care Excellence and the European Resuscitation Council (ERC) patients should be monitored to help identify those with a deteriorating clinical condition, or one at risk of deterioration. Regrettably, despite the deployment of early warning systems (EWSs), adverse events are currently estimated to affect a significant number of hospitalised patients, and to cause thousands of patient deaths every year – in the European Union (EU) alone.

Current EWSs are based on measuring physiological vital signs and consciousness levels. However, clinicians consider biomolecule markers to be valuable indicators of disorders. Efforts have been made to include these markers to improve EWSs, by either point-of-care (POC) testing or increased central lab testing. However, they have not been widely accepted, primarily because of poor integration into the workflow of the caregiver.

Therefore, to obtain a clinical-relevant scoring methodology with improved specificity to quantify the severity of these adverse effects, a technology should be available that:

- Simultaneously and in a timely manner measures relevant factors, hence in a semi-continuous way;
- Operates autonomously with minimum disruption to a nurse's workflow;
- Provides signal analysis and data analytics to discover clinically relevant relationships between the measured parameters and the above-mentioned health indicators.

Developing wearable device with hybrid marker sensing

The Sentinel project will address and resolve these issues by developing technologies which will result in a wearable solution – a hybrid patch – that integrates semi-continuous quantitative hybrid sensing of physiological, contextual and biomolecule markers, including affiliated algorithms, manufacturing technology and verified prototypes.

These technologies will be demonstrated in the area of patient monitoring by two clinical use cases: sepsis (including reduced peripheral perfusion) and delirium (including monitoring of stress). New developments in micro-nano technology will be needed, combined with microfluidics to interface with the person's bio-liquids and allow for (semi)continuous measurements for a week.

Sentinel will focus on seven areas:

1. Wearing formats:

- For many patients, an adhesive patch is acceptable, aided by the limited duration of use. For ones with frail skin, an attachment module will be developed that offers the wearer pressure relief.

2. Biomarker sample methods:

- Sweat is a non-invasive rich source of biomarkers. Since most patients do not undergo excessive physical strain, they have a low sweat rate of approximately 0.2 nL/min/gland. A complicating factor is that the concentration of so-called actively resorbed biomarkers not only depends on a disorder but also on the sweat rate per gland, not addressed by the state-of-the-art. Sentinel will develop high-end microfluidic designs for sampling sweat, capable of handling nanolitre volumes of bio-fluid.
- A small number of biomarkers may require sampling of interstitial fluid (ISF). If required, Sentinel will utilize miniature sensors for ISF sensing.

3. Sample methods for physiological and contextual markers:

- For sampling physiological and contextual markers, existing technology is used. This technology will be applied in synergistically manner for biomarker sample methods as well.

4. Sensor platform:

- Different use-cases will require the measurement of different markers in a semi-continuous manner, hence the need for semi-continuous and interchangeable sensors. Sweat and ISF sensor modules will be developed to accommodate various sensors without changing the architecture of the particular module.

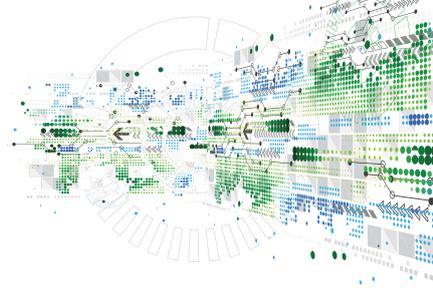
5. Microfluidic flow:

- A previously developed continuous-flow-operation principle, is the starting point for the development of a hybrid patch; capable of semi-continuous monitoring patients for at least four days.

6. Signal acquisition and Data Analytics:

- An algorithm will be developed to improve the signal-to-noise ratio of biomarker detection





KEY APPLICATION AREAS



Health & Well-Being

ESSENTIAL CAPABILITIES



Systems and Components
Architecture, Design & Integration

PARTNERS

AZ Turnhout

Catharina Ziekenhuis

Eindhoven University of Technology

Jobst Technologies GmbH

Micronit Microtechnologies BV

Philips Electronics Nederland BV

Sapienza University- Dept. Mech. Aerosp. Eng.

Tegema

Verhaert New Products & Services NV

COUNTRIES INVOLVED



Belgium



Germany



Italy



Netherlands

PROJECT LEADER

Eduard Pelssers

Philips Electronics Nederland BV

KEY PROJECT DATES

01 April 2020 to 31 March 2023

in sweat by considering physiological characteristics of sweat secretion in time and frequency;

- Data analytics algorithms will be developed to enhance the specificity and accuracy utilising the combination and synchronisation of physiological, contextual and biomarker signals; enabling studies to quantify the multifactorial phenomena;
- A data-quality Index toolbox will be built to produce a quality-scoring model for vital signs time series data through machine learning.

7. Manufacturing platform:

- Scalable and cost-effective foundry technologies will be applied for cost-effective manufacturing of the modules;
- Conflicting requirements, like cost price and use-case adaptability, will be addressed by standardising the module (miniaturised) dimensions, allowing various types of sensor modules to be integrated seamlessly on the so-called frames.

Advantageous position

Project partners are specialised in components (sensors and materials), integration (microfluidics and assembly), as well as, the signal chain (electronics, software, analytics, and clinical decision-support) of the Sentinel patch. This expertise combination puts them in an advantageous position to deal with user requirement provided by the clinical and medical industry, and to leverage existing state-of-the-art technologies around vital signs monitoring patches (energy, materials, and systems). Involvement of the end-user (clinical party) in the early phases of this project will improve the quality of the wearable patch requirements, as well as, provide relevant clinical results. These are essential and distinct advantages for market introduction and acceptance.

Impacting patients and the economy

Despite the use of EWS, adverse events are currently estimated to affect up to 12% of hospitalised patients and to cause up to 95,000 patient deaths per year in the European Union alone. In addition, infections associated with healthcare institutions affect an estimated 4.1 M patients. The United Kingdom National Audit Office estimates the cost of such conditions at £1 billion (US\$1.2 billion) per year. Infections that are detected late will lead to fast patient deterioration. Similar numbers are seen in the United States. In ensuring semi-continuous

monitoring in an autonomous and hybrid manner, Sentinel will decrease complications & mortality in hospitals and will reduce the number of permanent disabilities. This will not only improve the quality of life for patients after discharge, but will also reduce healthcare costs.

Promising market developments

Sentinel will target its products at these four market segments:

1. POC diagnostic market;
2. Healthcare wearable market;
3. Electrochemical-sensor technology market;
4. Main diagnostics market.

The global market for POC diagnostics in 2015 was valued at nearly US\$18 billion. This market is predicted to grow from US\$19.3 billion in 2016 to US\$28.3 billion in 2021, at a CAGR of 8%. This growth, which is expected to continue for the coming years, is substantially fuelling the growth in the entire in-vitro diagnostics industry.

The global market for wearable healthcare devices is anticipated to reach a revenue of US\$18.9 billion in 2020, growing at a CAGR of about 30%. The consumer health market, including wellness, fitness, and sport-wearable segment, is expected to grow at a CAGR of 27.8% (2015-2020). Medical and clinical-grade wearables, the most promising product segment within healthcare wearables, is expected to grow with a CAGR of 32.9% (2015-2020).

Electrochemical sensors show strong growth due to the unique properties of continuous sensing (low cost per measurement). Moreover, the concentration range fits in well with the markers Sentinel is planning to measure. The rising ageing population and the increasing incidence of chronic ailments will boost the demand for precise diagnosis, and drive investments and adoption of use in other application domains, for example such as safe driving in the automotive market and promoting healthy living. The global biochemical sensor market is forecasted to reach US\$58.48 billion by end-2025, a CAGR of 14.7% between 2016 and 2025.

Finally, main markets in clinical diagnostics (besides the already-mentioned POC one) are microbiology, molecular diagnostics, immunoassays, and flow cytometry, especially in preventing deterioration in the case of sepsis. This market is expected to grow at a CAGR of about 10% (2015-2022).

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Penta (E! 9911), is EUREKA Cluster whose purpose is to catalyse research, development and innovation in areas of micro and nanoelectronics enabled systems and applications.



Vivaldy





19021



Efficient re-verification and re-validation to enable rapid dissemination of innovations for AI-enhanced CPS in professional healthcare [Vivaldy]

The Vivaldy (Verification and Validation of Ai-enabLeD sYstems) project is developing efficient re-verification & re-validation strategies and effective regulatory approval guidelines for the incremental upgrade of class II¹, AI-enhanced CPSs in the professional healthcare domain. Based on a ‘DevOps’ approach, it will enable rapid incremental dissemination of innovations, increasing the frequency of major system upgrades from every three years to once a year, and module and/or AI upgrades from once a year to every six months. This will lead to better responses to fast-changing public health challenges, along with improved patient engagement and quality of care, while ensuring patient safety remains paramount.

Increasingly, products of all kinds – from consumer appliances to medical devices – are becoming intelligent, connected, and linked to the physical world. They incorporate Cyber Physical Systems (CPS) which interact directly both with embedded intelligence and with the real-world physical environment. Today, advanced CPS are characterized by frequent incremental upgrades (software, hardware and modules) after the initial product release, and by the addition of Artificial Intelligence (AI) to enhance their utility. This poses challenges in applications such as professional healthcare. With patient safety of paramount concern, class II medical devices must undergo certification to demonstrate that they comply with stringent safety requirements. However, there are currently no regulatory guidelines for incremental upgrades. This limits the ability of such devices to be upgraded rapidly to respond quickly to emerging public health challenges and to benefit from evolving advances in CPS and AI. Moreover, if upgrades are carried out, the evidential value of the initial verification and validation (V&V) required for certification is rapidly lost.

Enabling a DevOps approach to re-verification and re-validation

The Vivaldy project will address these issues by developing efficient, model-based (virtual) re-verification and re-validation techniques for rapidly evolving and AI-based CPSs. It will research practical guidelines, supporting tools and methodologies for the re-verification, re-validation and certification of three distinct kinds of incremental upgrades for healthcare class II CPSs in a ‘DevOps oriented’ total product lifecycle approach: (i) hardware upgrade, (ii) component upgrade and (iii) software/AI upgrade.

‘DevOps’ is set of practices that combines software development and IT operations in order to shorten

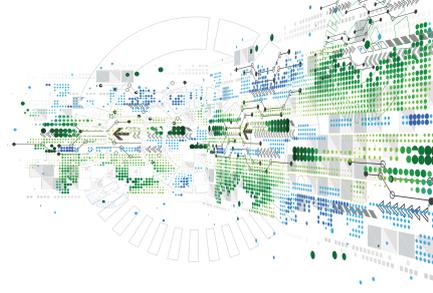
the systems development life cycle and provide for continuous delivery of high-quality software. Regulatory authorities such as the FDA (US), Notified Bodies (EU) and the CFDA (China) recognize the advantage of a DevOps release cycle for (AI-enhanced) healthcare to achieve the goals of faster public health responses and improved patient engagement and quality of care. The Vivaldy project will enable this paradigm shift by offering a total solution and guidelines for the transitioning from today’s product-oriented development cycles to a DevOps driven, upgrade-oriented development cycle for professional healthcare solutions.

Five key innovation areas will be addressed:

1. Analysis of field-obtained user/usage data for re-training and incremental upgrade of AI components for clinical decision support; and secondly, for selection of the most significant verification and validation (V&V) activities to safeguard patient safety;
2. Hardware upgrade strategy for efficient re-V&V while improving the effectiveness, reliability and safety of CPSs for clinicians and patients after the upgrade;
3. Change-based impact analysis combining patient risk-based analyses with analysis of potential impacts on functionality, reliability and patient’s or clinician’s safety of individual upgrades to minimize overall V&V effort for certification;
4. Integration and test framework combining virtual (simulation models / digital twins) and physical testing for V&V without compromising on product safety for patients and clinicians;
5. Guidelines for regulatory approval addressing the current lack of incremental upgrade guidelines in conjunction with a relevant user group.

¹ The FDA classifies medical devices based on (a) their intended use and (b) upon their potential harm to a patient. Clinical decision support systems (i.e. systems that provide recommendation to a healthcare professional on a health condition) are generally classified as class II medical devices and must comply with stringent patient-safety requirements.





KEY APPLICATION AREAS



Healthcare



Digital Industry

ESSENTIAL CAPABILITIES



Systems and Components
Architecture, Design & Integration



Safety, security and reliability

PARTNERS

Barco
icomatrix
Philips Medical Systems Nederland BV
TNO-ESI
TU Delft
Verum Software Tools BV
VITO NV
Unit040

COUNTRIES INVOLVED



Belgium



Netherlands

PROJECT LEADER

Mr. Dominique Segers
Barco, NV
www.vivaldy-penta.eu

KEY PROJECT DATES

01 February 2020 to 31 January 2023

The results will be proven on four industrial use cases each targeting a specific type of upgrade ranging from hardware and components to AI applications. In addition, the project consortium will involve regulatory authorities and partners active in other safety-critical industry domains in order to benefit from developments in various fields.

Shared vision

The partners in the Vivaldy consortium bring expertise from a wide range of relevant fields including medical devices, medical imaging analysis, visualization and simulations, software verification and impact analysis, and AI in medical applications. They will leverage this joint expertise to enable the necessary paradigm shift from today's development-centric engineering towards an approach that considers the development and operational phases of CPS in an integrated way.

Commercial opportunities and markets

The initial target for the Vivaldy project is the healthcare market which requires systems and solutions that must remain fit for purpose over a long lifecycle. In particular, the project will lead to exploitable results in minimally invasive diagnosis and treatment, AI-enhanced clinical decision support systems and visualization solutions. Its outcomes will support rapid, cost-efficient re-verification, re-validation, and certification of incremental CPS upgrades that will allow the industry to respond more quickly and efficiently to the needs of its customers. In many cases, this will provide a competitive edge for medical device makers in the huge global healthcare market.

Worldwide, healthcare expenditure is currently estimated at USD7.6 trillion and its growth will continue to be greater than that of GDP, reaching double the rate in some countries². Within the EU, healthcare including health & wellness represents up to 25% of the economy. In the areas of diagnostic imaging and interventional radiology, where Vivaldy's results have major potential, markets are growing significantly. The worldwide diagnostic imaging market is expected to reach USD36.4 billion by 2021, at a CAGR of 6.6% from 2016 to 2021³; while the global interventional radiology market, covering the complete spectrum of medical imaging systems, is anticipated to reach USD22.9 billion by 2024, registering a CAGR of 5.8% over the period between 2016 and 2024⁴. Much of this growth derives from ageing populations, and the rise of chronic diseases, often resulting from lifestyle changes. In addition, AI is expected to bring important productivity gains in healthcare and AI applications could potentially create growth in the AI health market that could reach USD 6.6 billion by 2021 – a CAGR of 40%⁵.

At the end of the project, the Vivaldy partners anticipate that its resulting innovations will be introduced step by step into product development processes. Consequently, AI-enhanced CPS medical devices that can be incrementally upgraded could be introduced on the market within three to four years. In the long term, through its interaction with the scientific community, industry, end-users, policymakers, regulatory and standardization bodies in various market segments, Vivaldy will help enable regulatory approval of AI-enhanced and incrementally upgradeable products in other safety-critical areas such as the automotive industry.

² World Economic Forum, Value in Healthcare, Insight Report April 2017

³ Markets and markets – Diagnostic Imaging Market, February 2017

⁴ <http://www.transparencymarketresearch.com/interventional-radiology-market.html>

⁵ Frost and Sullivan, Cognitive Computing and Artificial Intelligence Systems in Healthcare, Dec 2015.

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Vivaldy

Bringing benefits to patients and public health through efficient and effective safety-certified upgrades for AI-enabled medical devices

Paris, 27 January 2021- The PENTA project, Vivaldy (Verification and Validation of Ai-enabLeD sYstems) aims to allow medical devices such as those used in the analysis of medical images and in minimally invasive surgery to be upgraded more easily and frequently, but with full safety certification. This will bring improved quality of care, help patients better engage with their care, and allow healthcare systems to adapt quicker to fast-changing public health challenges. In technical terms, its goal is to develop efficient re-verification and re-validation and effective regulatory approval guidelines for the incremental upgrade of class II¹, AI-enhanced Cyber Physical Systems (CPSs) in the professional healthcare domain.

Many of today's medical devices incorporate CPS – systems that interact both with computing capabilities built into the product and directly with the physical world (e.g. a monitoring system that reacts to sensors on the body). Often, these devices also include Artificial Intelligence (AI) which enhances their utility. For instance, AI helps doctors spot critical diagnostic information in scans, while CPS and AI in X-ray systems guide doctors during extremely precise minimally invasive procedures.

Given that patient safety is always paramount, these devices require lengthy certification by relevant authorities. However, CPS and AI are rapidly evolving fields and there are currently no guidelines to allow for frequent incremental upgrades so such medical devices can keep pace with the latest advances. The Vivaldy project seeks to solve this issue by developing techniques that enable upgrades to be implemented and re-certified more efficiently. Major system upgrades could happen once a year instead of every three years, and module and/or AI upgrades every six months instead of once a year.

To achieve these ambitions, the project partners bring expertise in medical devices, medical imaging analysis, visualization and simulations, software verification and impact analysis, and AI in medical applications. They aim to create a 'DevOps²' approach to verification and validation which involves integrating product development and the ability to deliver frequent upgrades into a single engineering approach.

Besides patient and healthcare provider benefits, the project will increase the competitiveness of European players in huge and growing global healthcare markets. The worldwide diagnostic imaging market is expected to

¹ The FDA classifies medical devices based on (a) their intended use and (b) upon their potential harm to a patient. Clinical decision support systems (i.e. systems that provide recommendation to a healthcare professional on a health condition) are generally classified as class II medical devices and must comply with stringent patient-safety requirements.

² DevOps integrates the two worlds of development and operations, using automated development, deployment, and infrastructure monitoring. It's an organizational shift in which, instead of distributed siloed groups performing functions separately, cross-functional teams work on continuous operational feature deliveries. This approach helps de-liver value faster and continuously, reducing problems due to miscommunication between team members and accelerating problem resolution





reach USD 36.4 billion by 2021, at a CAGR of 6.6% from 2016 to 2021³; while the global interventional radiology market, covering the complete spectrum of medical imaging systems, is anticipated to reach USD 22.9 billion by 2024, registering a CAGR of 5.8% over the period between 2016 and 2024⁴. In addition, the Vivaldy project will establish user groups with industry, regulators, researchers, and end-users to bring its results not only to healthcare but also to other safety-critical areas such as the automotive industry.



Virtual Test Platform- Copyright: Philips

About the PENTA programme

PENTA is a EUREKA cluster whose purpose is to catalyse research, development and innovation in areas of micro and nanoelectronics enabled systems and applications. Guided by the Electronic Components & Systems (ECS) Strategic Research and Innovation Agenda (SRIA) four technology layers, four cross-sectional technologies and six ECS key application areas, the PENTA programme enables the development of electronic solutions to help drive the digital economy through the formation of collaborative ecosystems along the ECS value chain. This creates the opportunity for rapid competitive exploitation and a strong impact on European societal challenges. PENTA supports SMEs, large corporations, research organisations and universities to work together in project consortia by facilitating access to funding, fostering collaborative work and creating consortia in areas of mutual industrial and National interest.

PENTA is managed by the Industry Association AENEAS

More on PENTA: <http://www.penta-eureka.eu>

More on AENEAS: <https://aeneas-office.org>

About the Vivaldy project:

Vivaldy is a RD&I project consortium involving 8 partners from 2 countries. The project partners are: Barco (Project leader), icometrix, Philips Medical Systems Nederland BV, TNO-ESI, TU Delft, Verum Software Tools BV, VITO NV, and Unit040. National funding support is provided by Belgium and the Netherlands.

About Vivaldy: <https://www.vivaldy-penta.eu/>

³ Markets and markets – Diagnostic Imaging Market, February 2017

⁴ <http://www.transparencymarketresearch.com/interventional-radiology-market.html>

FA4.0





19007



Smart AI-based tools for ensuring reliable electronic devices for smart mobility and industrial production [Failure Analysis 4.0]

The Failure Analysis (FA) 4.0 project will address a fundamental challenge for the digital world: how to ensure that increasingly complex electronic systems operate with complete reliability and safety in daily use. This is essential in safety-critical applications such as autonomous vehicles and in digitalized industrial production (Industry 4.0). FA 4.0 will provide innovative AI-based tools and methods to analyse and avoid defects and failures during the development and manufacture of electronic components and systems. With its holistic approach spanning chip production, assembly & packaging, to board and system level, the project's outcomes will be crucial for the competitiveness of European electronic devices, especially in the demanding automotive and industrial sectors.

From self-driving cars to medical devices and smart homes, rapidly evolving digitalization and automation are transforming everyday life. Industrial production itself is becoming 'smarter' and ever-more automated. These trends offer enormous market potential for high-tech products based on increasingly complex electronic systems. However, these electronic components and systems (ECS) must combine advanced functionality with the ability to function faultlessly whenever required. Average usage of many electronic devices may rise from a few hours a day currently to over 20 hours a day. For instance, even when not on the road, the electronics in an electric vehicle will be active during the charging cycle. Thus, the electronics must not only reach rigorous automotive safety and quality standards, but also have a long lifetime.

At the same time, innovation in applications such as automotive electronics is very rapid and electronic systems are growing in complexity on many levels – in functional density, reduced footprint size, new materials and compositions, and the introduction of novel technologies including 3D integrated devices, hetero-integrated system in package, and high-density interconnects for printed circuit boards, to name a few. These developments are leading to extreme challenges for reliability, quality and manufacturing yield.

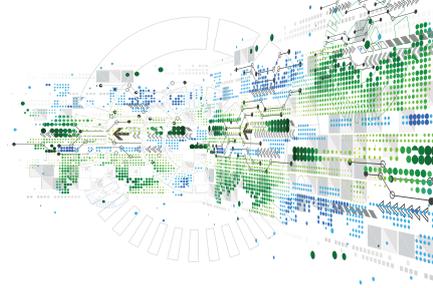
In applications where ECS are a key enabling technology, mastering the related reliability risks requires more effective process-related defect characterisation and failure analysis than currently exists. It also calls for holistic control of all the uncertainties along the process chain of component design, manufacture and quality management.

Today, however, failure analysis is carried out manually, driven by single tasks coming from production, reliability testing and field returns. This is time-consuming and does not allow for analysis of combined electrical and material testing and metrology data from along the manufacturing process flow. It is also susceptible to human error, and diagnostic tools are not linked to each other or a central database to provide information for the next steps in a failure analysis workflow.

Applying AI for smart failure analysis

To address these challenges, FA 4.0 will create cutting edge tools and methods for analysing, understanding and avoiding defect mechanisms and failure risks during development and manufacturing. It will develop a comprehensive, central recording analysis of metrology parameters and process-related inhomogeneities, tracked along the production process in correlation with existing failure catalogues. Newly discovered failure mechanisms identified in final components will be explored as part of a novel holistic approach for quality assurance and process improvement. This holistic analysis approach will be enabled by advanced FA tools with integrated smart preparation and signal analysis capabilities.

Above all, the project aims to apply breakthroughs in the field of AI research and data correlation to provide largely automated diagnostic tools combined in efficient failure analysis workflows. It will focus on two primary innovation areas 1) a next generation of efficient diagnostic tools and workflows, and 2) smart algorithms for failure identification and cataloguing.



KEY APPLICATION AREAS



Transport and Smart Mobility



Digital Industry

ESSENTIAL CAPABILITIES



ECS Process Technology, Equipment, Materials & Manufacturing

PARTNERS

cyberTECHNOLOGIES GmbH
 Direct conversion AB
 Ecole des Mines de Saint Etienne
 Ericsson AB
 Excillum AB
 Fraunhofer Institute for Microstructure of Material and Systems IMWS
 Gimic
 Infineon Technologies AG
 Jean Monnet University (Saint-Etienne) in Lyon University
 Kern Microtechnik GmbH
 Materix AB
 Matworks GmbH
 Orsay Physics
 PVA TePla Analytical Systems GmbH
 RISE IVF AB
 Robert Bosch GmbH
 STMicroelectronics Grenoble 2 SAS
 STMicroelectronics (Tour) SAS
 STMicroelectronics (Rousset) SAS
 TESCAN ORSAY HOLDING
 University of Stuttgart

COUNTRIES INVOLVED



Czech Republic



Germany



France



Sweden

PROJECT LEADER

Dr. Klaus Pressel
 Infineon Technologies AG

KEY PROJECT DATES

01 April 2020 - 31 March 2023

Using AI-based algorithms, targeted working hypotheses can be derived more quickly and confirmed with only a few analysis steps. New approaches in the fields of automated and self-learning image processing, measurement systems and failure analysis methods could also be utilized for defect control. Linking smart and more automated failure diagnostic tools along the process chain (in line with concepts derived from Industry 4.0) and correlating these with degradation mechanisms and failure catalogs offers great potential for improving the efficiency and quality of production and reducing manufacturing costs.

Furthermore, these fast and powerful tools for failure recognition and interpretation, as well as for correlation to available metrology and electrical testing data along the manufacturing process chain, will be key for further technological developments.

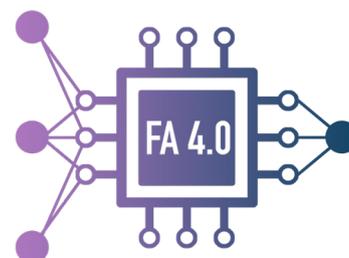
Expertise across the entire value chain

FA 4.0 is able to take its holistic approach by bringing together research institutes and companies from across the entire value chain, including leading semiconductor and electronic system suppliers and medium and small businesses (SMEs). The project will strengthen the strategic alliance of European semiconductor manufacturers, FA tool providers and research institutes, and leverage their combined expertise in failure analysis, methodologies and tool supply to develop these new solutions for smart failure analysis.

Strategic market access and new opportunities

The market importance of FA 4.0 is huge. As demand for high-tech products for applications like autonomous driving, electric vehicles, smart industry, energy efficiency, 5G telecommunications and Internet of Things (IoT), and medical applications grows, reliability and quality are no longer an 'add-on' to technological innovation but an essential requirement for market access. Experts in the field have stated that "Reliability is emerging as the top priority across the hottest growth markets for semiconductors, including automotive, industrial and cloud-based computing...". Moreover, AI is seen as having a key role in enabling this reliability. Thus, the outcomes of FA 4.0 will be of crucial importance to ensuring the European electronics industry has access to the strategic markets of the future. In addition, the project will open up opportunities for European failure analysis equipment manufacturers.

In effect, the collaboration in FA 4.0 between semiconductor and system suppliers, diagnostic tool manufacturers and leading research institutes will strengthen the European ECS industry's global competitiveness to design and manufacture reliable, high quality and cost-effective products. The close cooperation between the partners in the consortium will allow European companies to deliver both innovative electronic products and the required failure analysis tools that increase reliability and quality and shorten product development cycle times.





Failure Analysis 4.0

Smart AI-based tools for ensuring reliable electronic devices for smart mobility and industrial production

A project within the EUREKA EURIPIDES² & PENTA programmes



Paris, 9 March 2021 - The Failure Analysis (FA) 4.0, a co-labelled EURIPIDES² and PENTA project, is addressing a fundamental challenge for the digital world: how to ensure increasingly complex electronic systems operate with complete reliability and safety in daily use.

As digitalisation and automation rapidly advance, complex electronic systems and components will play an ever-bigger role in everyday life, enabling innovations from self-driving vehicles to smart homes. Even industrial production itself is becoming 'smarter' and more automated. These advances will help to improve the quality of life in our homes and cities; as well as making industry more efficient. However, to do this, the electronics at the heart of each product must operate safely and reliably at all times, especially in safety-critical applications such as automotive. In developing a smart approach to further improve failure analysis methods, tools and workflows by introducing Artificial Intelligence (AI) and sharing data throughout the design and manufacturing process, FA 4.0 will provide to tackle these crucial challenges.

Failure analysis is a process that allows the designers and manufacturers of semiconductor chips, printed circuit boards and other electronic components and systems to analyse, understand and avoid defects and failure risks during development and manufacture. However, failure analysis is currently a manual, time-consuming process, and test data is not shared between different design and manufacturing steps.

By applying breakthroughs in the field of AI research and data correlation, FA 4.0 intends to develop a holistic approach, that combines largely automated diagnostic tools in an efficient FA workflow process. The project will draw on the combined expertise of leading European electronics companies, SMEs and research institutes, to deliver key innovations in next generation diagnostic methods, tools and workflows as well as smart algorithms for identification and cataloguing of failures.

The challenge is both fundamental and highly demanding as the technologies used to create high performance electronic devices, components and systems (ECS) are constantly evolving. Devices are becoming ever smaller, with more densely packed functionality on each tiny device; plus, new materials, new types of assembly and packaging, and new ways of connecting devices into circuits are rapidly emerging.

At the same time, as demand for applications such as autonomous driving, smart industry, energy efficiency and medical applications grows, reliability and quality are becoming an essential requirement for high-tech products to enter the market. Thus, the outcomes of the FA 4.0 project will

be highly important to deliver the benefits of digitalisation for society and their resulting economic impact. They will allow European companies to create innovative electronic products and the failure analysis tools necessary to increase reliability and quality while reducing product development time and costs. The European electronics industry will be ensured to access the strategic future markets, particularly in safety critical applications. European failure analysis equipment manufacturers will have new opportunities in their global market segment of diagnostic tools as well.

About EURIPIDES

[EURIPIDES²](#) is a [EUREKA](#) Cluster promoting the generation of innovative, industry-driven, pre-competitive R&D projects in the area of Smart Electronic Systems. Guided by the [Electronic Components & Systems \(ECS\) Strategic Research and Innovation Agenda \(SRIA\)](#), EURIPIDES² is the innovation hub for smart sensors, smart power modules, electronic hardware platforms and more generally electronic product integration and embedded systems for automotive, aeronautics and space, security, medical electronics, smart everywhere (cities, home, wearable) and industrial electronics. EURIPIDES² facilitates access to national funding in Europe and beyond. As a EUREKA Cluster, the network is open to participants worldwide.

More on EURIPIDES²: <https://www.euripides-eureka.eu>

About PENTA

[PENTA](#) is a [EUREKA](#) cluster whose purpose is to catalyse research, development and innovation in areas of micro and nanoelectronics enabled systems and applications. Guided by the [Electronic Components & Systems \(ECS\) Strategic Research and Innovation Agenda \(SRIA\)](#) key application areas, foundational technology layers and cross-sectional technologies, the PENTA programme enables the development of electronic solutions to help drive the digital economy through the formation of collaborative ecosystems along the ECS value chain. This creates the opportunity for rapid competitive exploitation and a strong impact on European societal challenges. PENTA supports SMEs, large corporations, research organisations and universities to work together in project consortia by facilitating access to funding, fostering collaborative work and creating consortia in areas of mutual industrial and National interest.

More on PENTA: <http://www.penta-eureka.eu>

About FA4.0

FA4.0 is an RD&I project consortium involving 21 partners from 4 countries, Germany, France, Czech Republic and Sweden. The project partners are: Infineon Technologies AG (project coordinator), Direct conversion AB, Ecole des Mines de Saint Etienne, Ericsson AB, Excillum AB, Fraunhofer IMWS, Gimic, Jean Monnet University (Saint-Etienne), Kern Microtechnik GmbH, Materix AB, Matworks GmbH, Orsay Physics, PVA TePla Analytical Systems GmbH, RISE IVF AB, Robert Bosch GmbH, STMicroelectronics (Rousset) SAS, STMicroelectronics (Tours) SAS, STMicroelectronics (Grenoble2) SAS, TESCAN ORSAY HOLDING and University of Stuttgart.

More on FA4.0: <https://penta-eureka.eu/project-overview/penta-call-4/fa4-0/>

WMC





19022



Europe's open, multi-application platform for wafer production with onsite configurability [WMC]

The Wafer Metrology Center (WMC) project will develop an open, modular metrology and inspection tool for wafer handling in a wide range of semiconductor applications, and which can be retooled onsite to deal with rapidly-changing requirements. Importantly, this platform will also establish a European foothold in a key marketplace.

Current semiconductor metrology and inspection tools are often too monolithic and cannot be reconfigured to many different and fast-changing requirements of emerging products. Even a minor retooling change in the field is, in most cases, not possible. Equally important, this lucrative market is currently dominated by five large companies, none of which are European.

What is needed is a European platform that not only offers flexibility in functionality and application, but also provides a 'framework' which is innovative and open in its approach to business, operational process and technology.

Building an open, flexible, multi-application wafer-handling platform

The goal of the WMC project is to develop an open, modular metrology and inspection platform for wafers in a wide range of semiconductor applications – especially for, but not limited to, wafer-level packaging. WMC will be innovative on three fronts: business, process and technology.

The WMC business model will attract innovative technology companies and research and development (R&D) institutions in the field of optical-sensor techniques, as well as, semiconductor customers. Manufacturing resellers (OEMs) will benefit from a technology, sales and distribution platform, while customers and users from a flexible, scalable, multi-application and cost-effective tool.

Operational processes, open and modular in concept, will deploy multiple sensors in a wide range of applications, which can be combined and retooled onsite – a unique capability in the semiconductor market. Even though there are systems currently available with multiple sensors, these platforms are mostly neither open nor reconfigurable.

Technology innovation will cover five areas of R&D:

1. Metrology and automation platform:
Retooling of sensors requires a lot of engineering work, especially in the software architecture where sensor and automation components must be configurable; metrology recipes combined

and linked together; and standardised Interfaces designed specifically for optoelectronics, mechatronics and software. Furthermore, data transfer, graphics programming and many other techniques will need to be considered. The same modularity provided for sensor technologies is also required for wafer handling to make this 'generic' platform deployable in a broad range of applications along the semiconductor value-chain.

2. Digital holography microscopy:

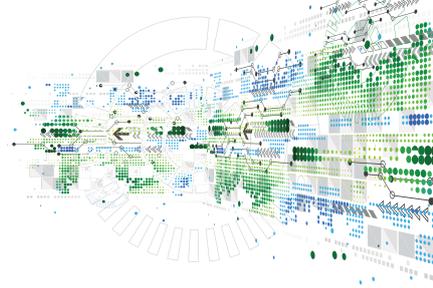
The advantage of a digital holography microscope is that holograms may be captured with the frequency of a CMOS camera. Since there are no moving parts inside (for example gratings) like in phase-shift interferometers, measurement-taking is very fast. The challenge in semiconductor front-end applications is the transparent insulating layer, which usually causes false topography. The approach in this case is to measure the thin layer using the physics of reflectometry without any additional measuring.

3. Mid-IR reflectometry:

This new sensor will be primarily dedicated to measuring the EPI (epitaxial) thickness of silicon (Si), silicon germanium (SiGe), silicon carbide (SiC) or gallium nitride (GaN) layers on wafers. The reflectometry sensor requires a spectrometer to measure the spectra. The main goal is to boost its throughput to a production-level standard. Both, Fourier transform infrared spectrometer and wavelength-swept quantum cascade laser will be evaluated to ensure this improvement. Notably, the laser approach will be emphasised to boost speed, but also accuracy and reliability.

4. Multi-wavelength interferometer (MWI):

For 3D packaging inspection with structures in the micron range, the above-mentioned holography sensor does not work since its dynamic range is less than a couple of microns. The project will evaluate a new approach based on multi-wavelength interferometry (MWI), using a fast line-scan camera to speed up bump-profiling and improve its reliability, especially



KEY APPLICATION AREAS



Semiconductor Fabrication

ESSENTIAL CAPABILITIES



ECS Process Technology, Equipment, Materials & Manufacturing

PARTNERS

CSEM

Lyncée Tec SA

Fraunhofer-Gesellschaft – the Instituts for reliability and microintegration (IZM), for production technology and automation (IPA) & for applied solid state physics (IAF)

Nedinsco B.V

Sentronics Metrology GmbH

COUNTRIES INVOLVED



Germany



Netherlands



Switzerland

PROJECT LEADER

Bernd Srocka
Sentronics Metrology GmbH

KEY PROJECT DATES

01 March 2020 to 28 February 2023

for the smaller μ -bumps. With this approach, the throughput can be increased significantly, and wafer-scanning to within one minute is made possible. Recently announced multi-line cameras should make this throughput-target possible.

5. Extended depth of focus (DOF) camera:

Aspect ratios, especially in the advanced-packaging market, are growing constantly. At the same time, resolution requirements have reached levels around single microns, causing a principle issue with state-of-the-art camera techniques, limited in DOF by physics principles. Today, no system available can provide extended DOF while maintaining resolution. The project will extend the DOF of a camera-based imaging product by a factor of about 10, compared to currently available cameras. This will be achieved without any moving mechanics or liquids. The project aims to improve inspection performance, and especially 2-dimensional metrology for high aspect-ratio structures. A proof of concept has already been developed for this innovative optical system. It comprises a lens column, a mounted camera, and includes proprietary image-processing algorithms.

Critical success factors

In a nutshell, the project aims to deliver Europe's first open platform for metrology and inspection in the semiconductor industry that, at its launch, will already address nine different optical sensor technologies. It will deploy four new sensor technologies in combination with five existing ones, and aims to be open to further additions in the future. The platform will cover an extensive variety of wafer-manufacturing applications, including front-end, back-end, and packaging metrology and inspection ones.

WMC will also be unique since current metrology tools do not have the flexibility to be retooled in case of changing

requirements. What is more, WMC will allow European companies to compete in this important marketplace. Another key spin-off is the globalisation of intellectual property of scientists and engineers participating in semiconductor fabrication. This project will also create a symbiosis-like ecosystem of technology exchange, from which every project partner will benefit.

Standardisation is also key to this project, considering a critical project objective is to position the WMC platform as an open, highly standardised and flexible platform to a growing community of European (metrology) sensor-providers.

Crucially, building a product which faces competition dominating the current semiconductor metrology and Inspection market, also calls for a project consortium with the right experience, expertise and building blocks to collectively meet the technological and business challenges the WMC project faces.

State of the market

Five companies dominate the current US\$ 6 billion semiconductor metrology and Inspection market, with a combined share of 87% in 2017, up from 75.3% in 2002, as the market consolidated from 37 companies to 20.

WMC's potential market can be divided into five main application groups: 1) layer metrology; 2) 3D surface metrology; 3) wafer geometry; 4) 2D Inspection; and 5) high-throughput 3D packaging inspection. The WMC project is expected to generate new opportunities for applications in various other fields also requiring the highly configurable, cost-effective WMC platform. Potential growth for project partners in a new market segment is US\$ 600m, based on current conditions, growing with a 10% CAGR to US\$ 880m in 2022.

Importantly, the WMC project's legacy will include an ecosystem of European high-tech companies and research centres that will continue to collaborate beyond the completion of this project.



WMC

Wafer Metrology Centre (WMC) – an upgradeable solution for the challenging task of minute measurement in chip manufacturing

A project within the EUREKA EURIPIDES² & PENTA programmes

Paris, 13 October 2020 - The co-labeled EURIPIDES² and PENTA Wafer Metrology Centre (WMC) project led by an SME, aims to provide manufacturers with new and more flexible tools to check the miniscule features on electronic chips during the production process. Designed for measurements during quality control, the integrated WMC hardware and software platform will be easily able to evolve as new applications, designs and demands on performance continue to grow.

Silicon chips are everywhere in our digital world: in computers, phones, cars, medical devices, industrial machines, LED lights – the list is vast. And each of these tiny chips (or ‘integrated circuits’ (ICs)) contains hundreds of millions, or even billions, of electronic transistors, measuring just billionths of a meter (nanometers) in size.

Consequently, chip manufacturing is highly intricate, requiring extreme precision to ensure chips operate correctly and reliably. Yet there is constant pressure to deliver higher performance at lower cost, to produce ever-more complex chips based on new designs and materials, and to reduce production faults to just a few parts in million.

Wafer metrology plays a key role in achieving these goals. It is the technology used to measure the components and wires on chips as they are ‘printed’ or ‘etched’ onto pieces (wafers) of silicon or other materials. But current wafer metrology tools often lack the flexibility to evolve to meet changing requirements and new applications, which is where the WMC comes in.

The partners in the WMC consortium are developing a modular metrology and inspection tool platform for a wide range of semiconductor applications. They will also create new optical sensors which, combined with existing sensors, will allow the platform to cover a full range of production steps. These include wafer manufacturing processes, front-end, back-end and packaging metrology and inspection. In addition, the platform will provide a software editor to create customized filters, and a scalable interface which links to an advanced data-mining solution that turns raw data into meaningful input for decision-making.

Among key applications areas will be Si (silicon), SiC (silicon carbide) and GaN (gallium nitride) based ICs for power devices, LEDs and MEMS (micro electro-mechanical systems). Most importantly, a high degree of standardization in the platform will enable it to be quick and easy reconfigured even in the

field to meet changing requirements and applications. This is a unique advantage compared to existing metrology solutions and will allow the European project partners to compete effectively with incumbent global players in this important market.

About EURIPIDES

EURIPIDES² is a EUREKA Cluster promoting the generation of innovative, industry-driven, pre-competitive R&D projects in the area of Smart Electronic Systems. EURIPIDES² is the innovation hub for smart sensors, smart power modules, electronic hardware platforms and more generally electronic product integration and embedded systems for automotive, aeronautics and space, security, medical electronics, smart everywhere (cities, home, wearable) and industrial electronics. EURIPIDES² facilitates access to national funding in Europe and beyond. As a EUREKA Cluster, the network is open to participants worldwide.

More on EURIPIDES²: <https://www.euripides-eureka.eu>

About PENTA

[PENTA](#) is a [EUREKA](#) cluster whose purpose is to catalyse research, development and innovation in areas of micro and nanoelectronics enabled systems and applications. Guided by the [Electronic Components & Systems \(ECS\) Strategic Research Agenda \(SRA\)](#) key application areas and essential capabilities, the PENTA programme enables the development of electronic solutions to help drive the digital economy through the formation of collaborative ecosystems along the ECS value chain. This creates the opportunity for rapid competitive exploitation and a strong impact on European societal challenges. PENTA supports SMEs, large corporations, research organisations and universities to work together in project consortia by facilitating access to funding, fostering collaborative work and creating consortia in areas of mutual industrial and National interest.

PENTA is operated by AENEAS.

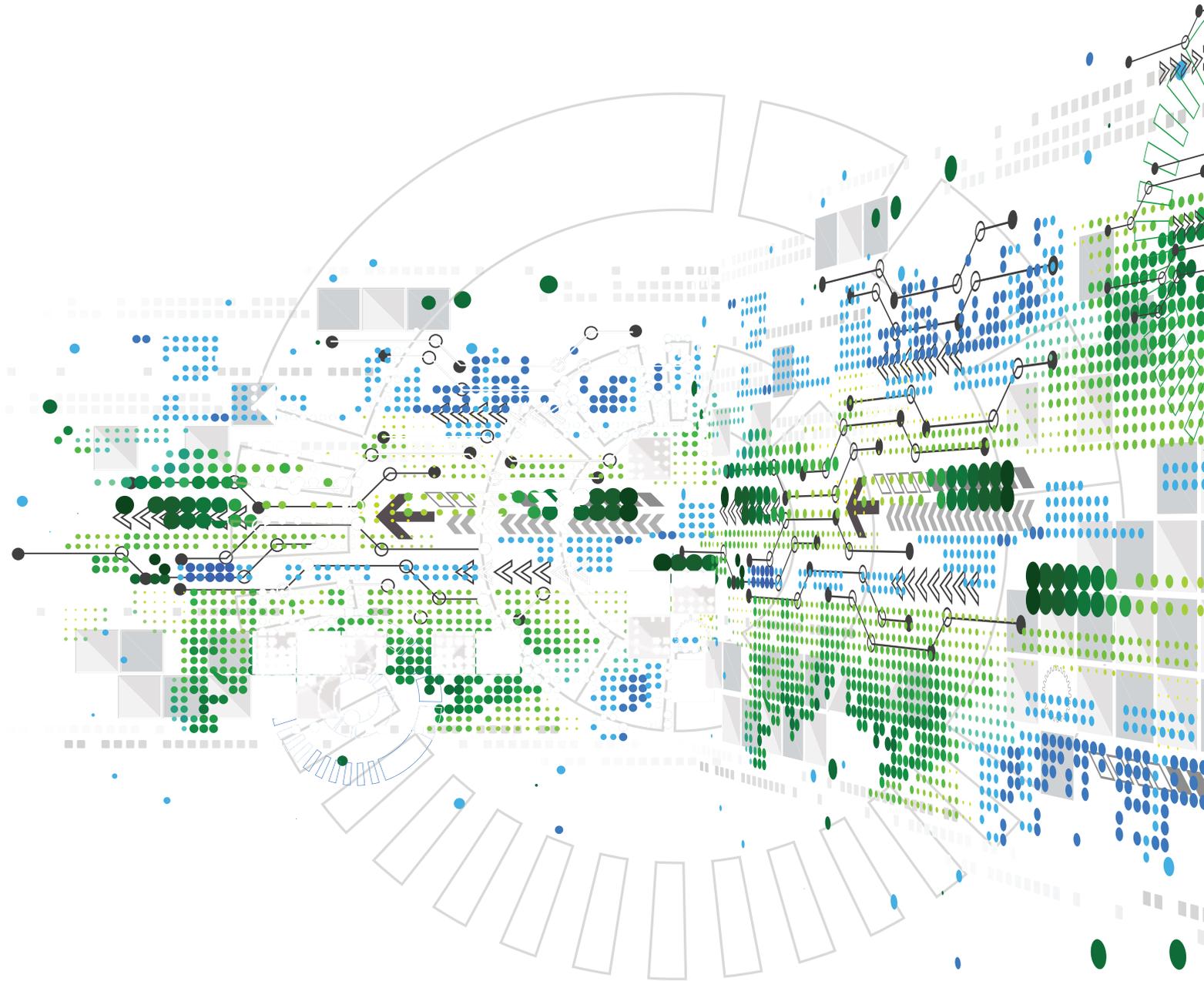
More on PENTA: <http://www.penta-eureka.eu>

More on AENEAS: <https://aeneas-office.org>

About WMC

WMC is an RD&I project consortium involving 5 partners from 3 countries, Germany, Switzerland, and the Netherlands. The project partners are: sentronics metrology GmbH (project coordinator), CSEM, Fraunhofer-Gesellschaft – institutes IZM ASSID, IAF and IPA, Lyncée Tec SA and Nedinsco B.V .

More on WMC: <https://penta-eureka.eu/project-overview/penta-call-4/wafer-metrology-center/>



Penta (E! 9911), is EUREKA Cluster whose purpose is to catalyse research, development and innovation in areas of micro and nanoelectronics enabled systems and applications.



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